

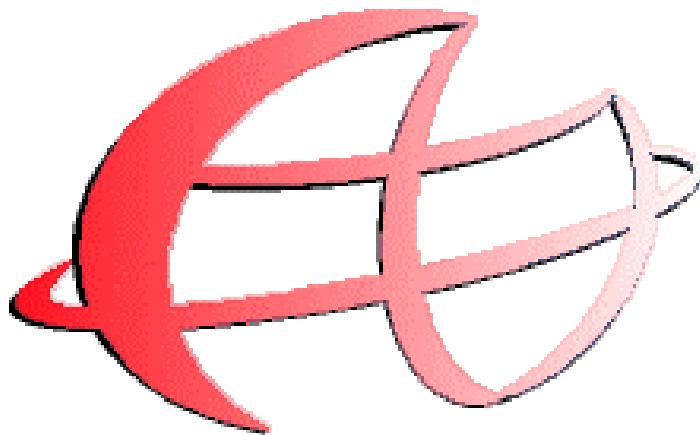


MOTOROLA

Personal Communications Sector

 **GSM**
Service Support
Level 3 Authorized

V2288



GSM Service Support

Training - Documentation - Engineering



**Level 3
Circuit Description
17 / 02 / 99
V1.0**

V2288 Level 3 Product Guide

RF: Receive

- 1) The RF Signal from the base station is received through the Antenna **A100** and is fed to **J300**, which is a purely mechanical switch which is operated when an cable is plugged into the Aux RF socket of the phone. This connects RF to the Aux RF port or the antenna.
- 2) The RX signal is then fed directly into **U100** RF Switch, the switch acts as an isolation between TX and RX, this is controlled via the signals **VA** and **VB** which are previously created by **TX_EN** and **RX_EN** respectively through **Q110**.
- 3) Provided **VB** is high, then the received signal will be passed to the band pass filter **FL470**, where the selected frequency band (GSM 1800 or GSM900) will be filtered through, *Note. The front-end filter has a bandwidth that is capable of working with the American GSM standard 1900Mhz. This gives the option of creating a PCS unit without the need to change many components.
- 4) The appropriate signal is then fed onto **FL472** (For GSM 1800) or **FL480** (For 900) where any existing harmonics or other unwanted frequencies are removed.
- 5) Our received RF frequency is now fed into the **Front End IC (U432)**. This IC is new to the T2288 and has several main purposes; reduce discreet part count and therefore cost as it replaces the mixer stage and also the two other front end filters from previous products and also the main RX VCO buffer. (Refer to Front End IC Document for internal block diagram interpretation). The IC's power is maintained by **RF_V2** (MAGIC), and is controlled with the aid of **RVCO_250** (created by **SF_OUT** (MAGIC) and **GPO4** (MAGIC) through **Q172**), **RX_EN** (Whitecap) and **DCS_SEL** (MAGIC). The GSM 900 signal is fed in through **Pin 13**, back out through **Pin 12** to matching circuitry, then returns to the IC on **Pin 9**, where the signal is internally mixed with the RX VCO signal to produce a balanced + and – 400 MHz IF Signal. The main reason for using the balanced IF output is to provide cancelling of the 3rd harmonic. This is then fed out on **Pins 3 and 4**. The GSM 1800 route is of the same description but uses the **Pins 18-20-23-3 and 4**.
- 6) The **RX VCO U253** is now an integrated circuit and is controlled firstly from the Whitecap using the **MQ SPI** bus to program the MAGIC and then MAGIC drives the RX VCO IC using the **CP_RX** signal **Pin B1**. The power is supplied by **RVCO_250 (SF_OUT + GPO4** through **Q172**).
- 7) The + and – IF, is now fed to the **SAW FL490** filter (Surface Acoustic Wave), this filter is the same as was used in previous 400MHz products, and is balanced to accept the new + and – IF.
- 8) The signal is then passed to the **MAGIC IC U200 PRE IN Pin A7**
- 9) The signal is then demodulated internally using an external Varactor diode RX Local Oscillator set up **CR249**, which is driven by **PLL CP Pin A9** of **MAGIC U200**.
- 10) Where in earlier products, we used to have **RX I** and **RXQ**, these signals are now only used in digital form within the MAGIC and cannot be measured. The demodulated signal is now converted internally to digital form to be passed along an RX SPI bus to the Whitecap.

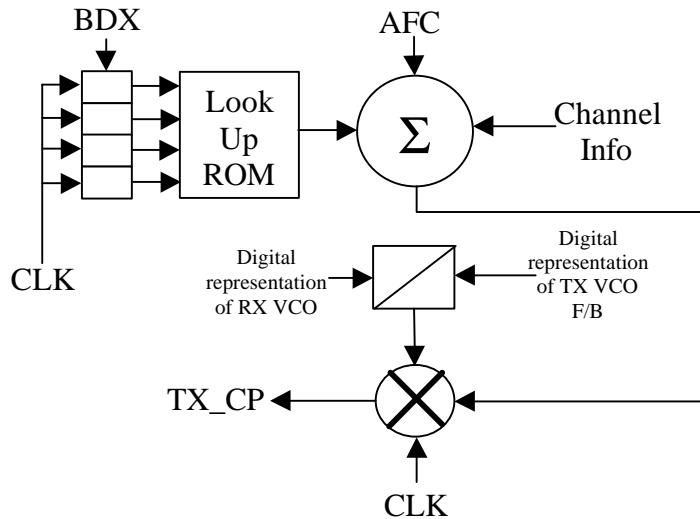
- 11) The **RX SPI** signal is made up of **BDR** (Base band Data Receive), **BFSR** (Base band Frame Synch Receive) and **BCLKR** (Base band Clock Receive, fed from MAGIC Pins **G8, G9 and F7** respectively.
- 12) The **Whitecap U800** receives these signals on **Pins A3, D4 and B4**, within the Whitecap the signal is digitally processed. Baud rate reduced, Error correction bits removed, etc...
- 13) The digital signal is now being fed down the **DL_AUD_SPI** bus to the **GCAP II U900**, internally, the digital signal is converted to analogue and distributed to the correct outputs
- 14) For Earpiece, from GCAP II **Pins H6 and H7** to speaker pads **J502** and **J503**
- 15) The Alert is generated within the Whitecap, given the appropriate data from the incoming signal, SMS, call etc... and is fed to the alert pads **J510** and **J511**. This signal is supported by the signal **ALRT_VCC**, which is generated from B+ through **Q903**.
- 16) For the headset only the **SPKR-** signal is used and feeds the **Stereo Audio IC U1500**, **Pin 12**, and is fed out on **Pin 1**, the exact operation of which can be found in the Level 3 Block diagram IC description. The output is then fed out on **HEADSET_L** to the **Headset Jack socket J504**. *NB There is no stereo headset operation for voice calls.

RF: Transmit

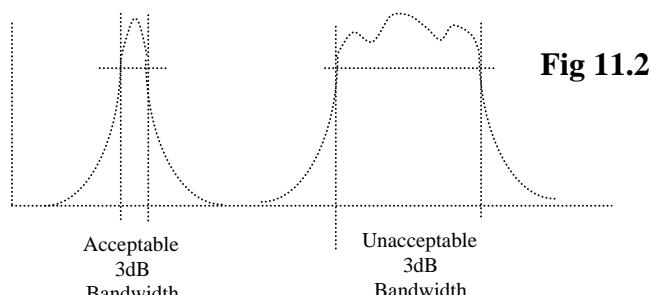
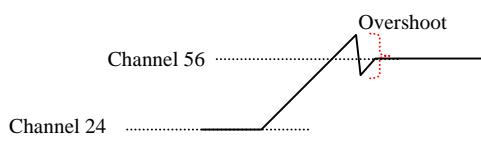
- 1) There are 2 Mic inputs, firstly from the **Xcvr mic J900**, where the analogue input is fed to the **GCAP II U900 Pin J2**
- 2) Secondly the analogue voice can be fed from the Aux Mic attached to the headset and will be routed from **connection 1** of the **headset jack J504**, through to GCAP II, **Pin H3**.
- 3) Within the GCAP II the analogue audio will be converted to digital and clocked out onto the **DI_AUD** SPI bus to the **Whitecap U800**.
- 4) It is within the Whitecap that all information about the transmission burst is formulated i.e. The timing of the burst / The channel to transmit on / The error correction protocol / In which frame the information will be carried to the base station, etc, etc...
- 5) All this information is then added to the digitised audio and is transferred to the **MAGIC U200** along a TX SPI bus. The bus is made up of **BCLKX** (Base band Clock Transmit) **Pin B2** and **BDX** (Base band Data Transmit) **Pin B6**. The timing for this data is already decided for the transmission burst, and therefore a frame synch is not required.
- 6) The SPI comes into the MAGIC at **Pin G7 (BCLKX)** and **Pin J2 (BDX)**
- 7) The operation of the MAGIC is very complex and with respect to the transmit path, intergrates the functions of the Modem and its function of GMSK (Gaussian Minimum Shift Keying) and also the functions of the TIC (Translational Integrated Circuit).

- 8) A very basic block view of how the transmit path works within the MAGIC is demonstrated in: Fig 8.1

Internal MAGIC Operation Fig 8.1



- 9) The data is transmitted from Whitecap to MAGIC on TX SPI bus **BDX**, within the MAGIC each bit of data is clocked into a register. The clocked bit and the 3 preceding bits on the register are then clocked into the look up ROM, which looks at the digital word and from that information downloads the appropriate GSMK digital representation. Channel information and AFC information from MAGIC SPI is then added to this new digital word, this word is then representative of the TX IF frequency of GIFSYN products. As in the case of the TIC, the TX frequency feedback and the RX VCO frequency are mixed to give a difference signal, this is digitally phase compared with the ‘modulation’ from the look up ROM. The difference creates a DC error voltage **TX_CP** that forms part of the TX Phase locked loop.
- 10) The error correction voltage **TX_CP** is then fed from **Pin B1** of MAGIC to **Pin 6** of the **TX VCO IC U301**, adjoining this line is the loop filter (See Loop Filter document).
- 11) The Loop filter comprises mainly of **U310 / Q310 / Q311** and it’s main function is to ‘smooth’ out any overshoots when the channel is changed, see Fig 11.1. If this overshoot were fed to the TX VCO the resulting burst would not meet the world standards for GSM with respect to bandwidth, see Fig 11.2.

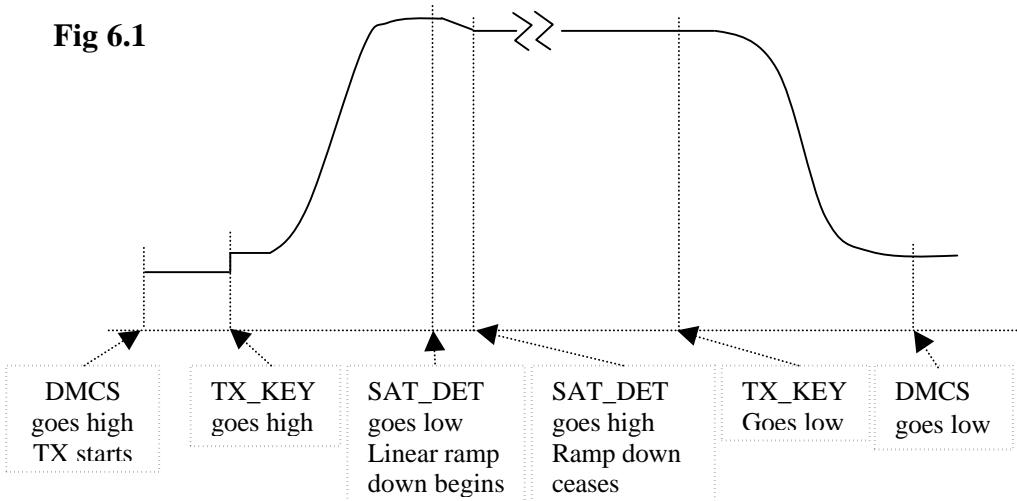


- 12)** The Loop filter basically acts then as a huge capacitor and resistor to give a long CR time for smoothing. It uses a small capacitor and the very high input impedance buffer Op-Amp. During the **TX_EN** (Whitecap) period when the transmitter is preparing to operate the capacitor charges, then on receipt of **DM_CS** (Whitecap) when the Transmitter actually fires; the capacitor discharges through the Op-Amp giving a smooth tuning voltage, carrying modulation to the TX VCO. The support voltage for the Loop filter is **V1_SW** (**V1** from GCAP II through Q913).
- 13)** The TX VCO IC now creates our required output frequency with the support signals **DCS_TX_VCO** (**DCS_SEL** (U110) + **TX VCO_EN** (Q140) through Q130) and **GSM_TX_VCO** (**GSM_SEL** (U110) + **TX VCO_EN** (Q140) through Q130), to enable either GSM or DCS frequency production and the IC Power is supported by **SF_OUT** (MAGIC).
- 14)** The signal is then fed out through a buffer amplifier **Q320**, which is switched on and off via **DM_CS** and supported by **RF_V2** (MAGIC)
- 15)** To prevent the output frequency from the TX VCO before stabilisation has occurred, being amplified and transmitted, there is an **Isolation Diode CR320** placed. This is biased ‘on’ by the exciter voltage from the **PAC IC U350** (Power Amplifier Control IC); this allows the TX output frequency through to the **Exciter Amplifier Q330** and at same time gives more or less drive to the exciter stage.
- 16)** The signal is then fed to a two stage, wide bandwidth **PA** made up from **Q331** and **Q370**, these are driven by the exciter voltage from the PAC IC, and supported by **B+** and **REG_B+** (Q332 / Q333 **B+** regulated by **TX_EN**).
- 17)** PA matching is provided using the signal **TX_GSM_*DCS** (**TXVCO_EN** + **DCS_SEL** through Q160) to switch on or off the diodes **CR380 / 370 / 390 / 350** and **340** to match the PA between GSM and DCS using the inductive strips on the PCB.
- 18)** The amplified signal is then fed back to the **RF switch U100**, as discussed in **Receive**, then passed to the **Ant / Aux Switch J300** and transmitted through either the **antenna A100** or the Aux testing port.

RF: Power Control Operation

- 1)** The **PAC IC U350** (Power Amplifier Control Integrated Circuit) controls the power control of the transmitter. Below is a list of the main signals associated with the PAC IC and their purposes.
- 2)** The RF detector (**RF_IN Pin 2**) provides a DC level proportional to the peak RF voltage out of the power amplifier, this is taken via an inductive strip from the output of the PA **Q370**.
- 3)** **DET_SW Pin 11.** This pin controls the variable gain stage connected between the RF detector and the integrator. The gain of the variable stage will be unity when **DET_SW** is low and will be 3 when **DET_SW** is high (floating).
- 4)** **TX_KEY Pin 10.** This signal is used to ‘pre-charge’ the Exciter and P.A. and occurs 20μS before the start of the transmit pulse.
- 5)** **EXC Pin 7.** This output drives the power control port of the exciter. An increase of this voltage will cause the exciter to increase its output power.

- 6) **SAT_DET Pin 12.** If the feedback signal from the RF detector lags too far behind the AOC signal then this output will go low, indicating that the loop is at or near saturation. This signals the DSP to reduce the **AOC_DRIVE** signal until **SAT_DET** rises. See **Fig 6.1**
- 7) **AOC_DRIVE Pin 8.** The voltage on this pin will determine the output power of the transmitter. Under normal conditions the control loop will adjust the voltage on EXC so that the power level presented to the RF detector results in equality of the voltage present at INT and AOC. The input level will be between 0 and 2.5V.
- 8) **ACT Pin 9.** This pin will hold a high voltage when no RF is present. Once the RF level increases enough to cause the detector to rise a few millivolts then this output will go low. In the GSM radio a resistor is routed between this point and the AOC input to cause the radio to ramp up the power until the detector goes active.



Logic: Power Up sequence

- 1) Three power sources available, battery, External Power via Charger (**Battery must be present to power up**) a power source via the test adapter, to allow power to be applied to the unit whilst there is no battery present.
- 2) T2288 charger will only work with NiCd and NiMH, Lithium Ion and Alkaline batteries are not supported.
- 3) Battery Power Source: The unit will contain 3 X 1.2V Nickel Metal Hydride (NiMH) cells each 700mAH, type AAAL (theses are different to AAA regular batteries) part number SNN5518A. They are connected to the unit by **battery contacts J605** and produce **B+** through **Q691**
- 4) Charger Power Source: When the charger is connected (**IRQ4** goes low), **V2** (GCAP) will provide a supply onto the sense resistor within the charger, the resultant voltage drop over the resistor is sensed by the signal **MAN_TEST_AD** (approximately 2.4V), **CHGR_SW** must be high. This is sent to the GCAP II **Pin A1**, this decides the charging current that the charger is capable of delivering. The GCAP II then checks the MOBPORTB line (**PWR_ON** from **COVIC U960**). If the batteries are present and in usable range, **PWR_ON** is pulled to 6.7V and the unit will power on. The

presence detection of the batteries is decided within the COVIC by comparing the actual battery voltage with the **B+** created by the charger (**Q960**→**CR960**→**Q691**). If **B+** is higher than the normal operating voltage of the batteries, **PWR_ON** will go low, powering the phone off. Battery voltage is sensed by **B+ Pin E10** GCAP II when battery not present, or **BATTERY Pin F7** GCAP II when batteries are present this is then output to Whitecap as **BATT_SENSE**.

- 5) Test Adapter Source: **B+** is sent directly from the external power source i.e. replaces the battery power source entirely and therefore the unit has no requirement for the batteries to be present.
- 6) The GCAP II is programmed to Boost mode (5.6V) by **PGB0 Pin G7** and **PGM1 Pin G8** both being tied to Ground. Once **B+** is applied to GCAP II **Pin K5**, all the appropriate voltages to supply the circuit are provided. These are:
 - **V1** – Programmed to 5.0V. **V1** is at 2.775V at immediate power on, but is ‘boosted’ to 5.0V through the switch mode power supply **L901 / C901 / CR902** and **C913**. See Fig 6.1 for basic operation. **V1** supplies the DSC bus drivers, negative voltage regulators and MAGIC. **V1** is created from GCAP II **Pin A6** and can be measured on **C906**.

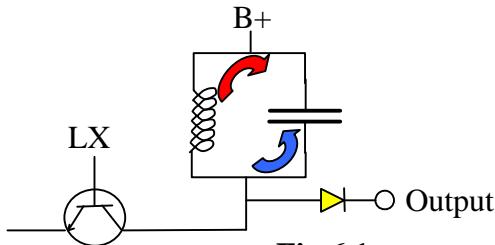
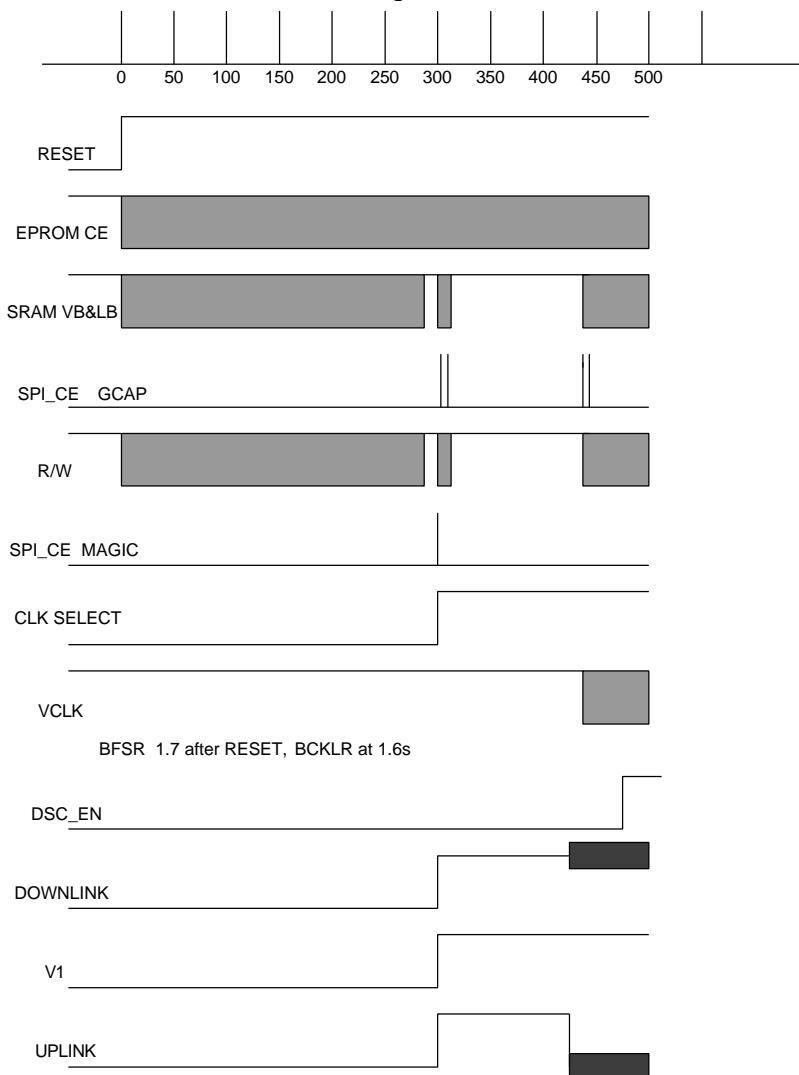


Fig 6.1

The basic circuit operation for the Boost circuit is as follows the **LX** signal (GCAP II **Pin B10**) allows a path for **B+** to charge the capacitor, when the switch is on, the capacitor then discharges through the inductor (switch off), setting up an electric field. The field then collapses setting up a back EMF to charge the capacitor, and so on and so on. The back EMF created by the inductor is greater than **B+** with the +ve half of the cycle passing through the diode to charge a capacitor from where the **V_BOOST** voltage is taken. The frequency of the switching signal **LX** decides the duty cycle of the output wave and therefore the resultant voltage. **V_BOOST** is fed back into the GCAP.

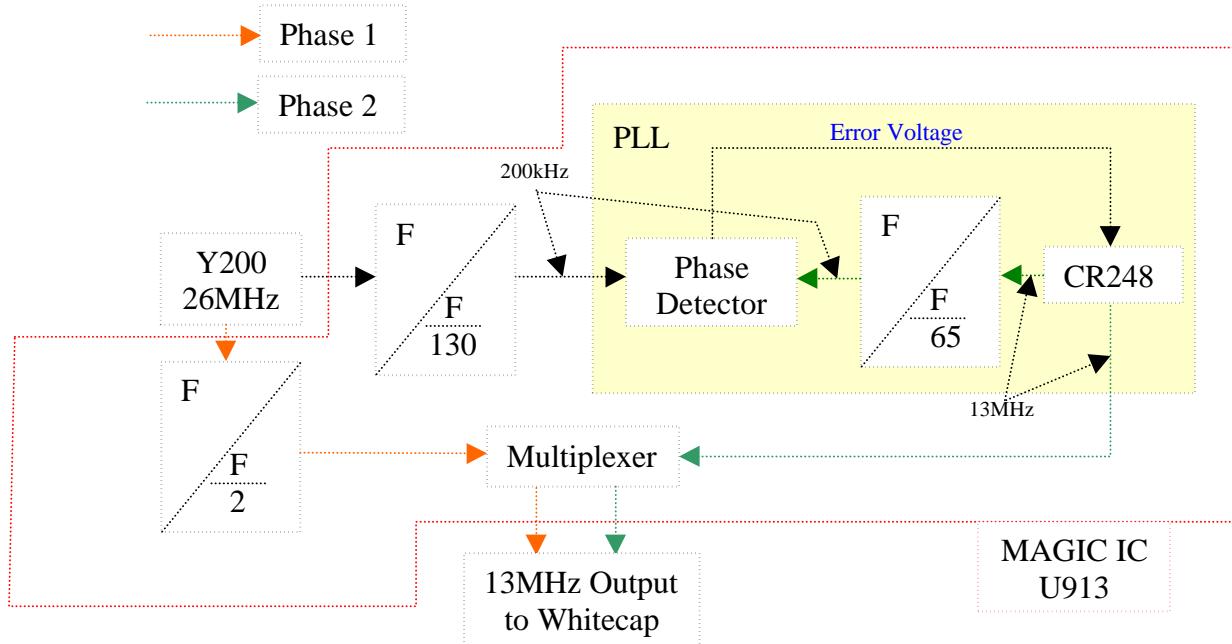
- **V2** – Programmed to 2.775V, available whenever the radio is on and supplies most of the logic side of the board. **V2** is supplied out of GCAP II **Pin J2** and can be measured on either **C939** or **C941**.
- **V3** – Programmed to 2.003V to support the Whitecap, but does support the normal 2.75V logic output from the Whitecap, it originates from GCAP II **Pin B5** and can be measured on **C909** or **C910**.
- **VSIM1** – Used to support either 3V or 5V SIM cards. Will dynamically be set to 3V upon power up, but if the card cannot be read then the SIM card is powered down and an attempt to read the card at 5V is tried. VSIM1 can be measured on **C905** and is distributed from GCAP II **Pin C6** (For further information, see SIM Card Operation).

- **VREF** – Programmed as **V2** i.e. 2.775 and provides a reference voltage for the MAGIC IC, distributed from GCAP II Pin **G9** and can be measured on **C919**.
 - **-5V** – Used to drive display and **-10V** – Used for RF GSM / DCS selection signals through **Q160**. Both voltages produced by **V1** through **U903** and **U904**.
 - **SR_VCC** – **Power Cut Circuit** - Used to buffer the **SRAM U702** voltage with a built in soft reset within the unit's software. The reason for this is to protect the user from any accidental loss of power up to 0.5 seconds i.e. If the unit is knocked, causing a slight battery contact bounce, the **SR_VCC** will, to the user, keep the unit running normally, whilst internally the unit resets itself. During this loss of power the unit takes it's power from a 10mF capacitor **C960** (This is a replacement for the RTC battery and is charged by **V2** and outputs to GCAP II Pin **D6**)
 - **V1_SW** – See **Deep Sleep Mode**
- 7) Once the power source has been selected to power the phone on the **PWR_SW** must be toggled low. This can be done by pressing the **Power Key S500** to create **PWR_SW**, which is supported by **ON_2** (GCAP II Pin **G5**).
- 8) The unit will then follow on as in the sequence below:



On initial power up, all the backlights (DS500 – DSDS11) will be on they are supported from the signal **ALRT_VCC** (B+ through **Q903**) and switched by **BKLT_EN** (Whitecap Pin **K3**) through **Q907**.

- 9) **13 MHz clock.** On Power Up there are 2 different reference clocks produced. Initially, as soon as power is applied to the MAGIC IC the **crystal**, **Y200**, supported by the **CRYSTAL_BASE** (MAGIC Pin **E1**) will emit a 26MHz signal to the MAGIC IC, which will internally be divided by 2 to give our external 13MHz clock. This is then fed out of the MAGIC on **Pin J6** (**CLK_OUT**) and distributed to Whitecap **Pin H10** (**CLKIN**), then from Whitecap to GCAP II **Pin F5** as **GCAP_CLK**. At the same time the 13MHz **Varactor Diode CR248** is producing an output. This output is controlled in the following way: The 26MHz from **Y200** is divided down to 200 kHz and fed to a phase comparator within the MAGIC. The 13MHz from **CR248** is also divided down and fed in to the phase comparator, the difference in phase produces an error voltage that is fed onto the cathode of the **Varactor CR248**. Which regulates the output to a stable 13MHz clock. Once the software is running and the logic side of the board has successfully powered up, the **CLK_SELECT** signal from Whitecap **Pin 1** is fed to MAGIC **Pin G6**. This in turn then switches the Multiplexer from the output of **Y200** to the **CR248** output.



Logic: SIM Card Interface

- 1) Once powered up, the SIM card is interrogated. The SIM interface is part of the **Whitecap U800** and it supports both ‘synchronous’ (Prepay card) and asynchronous, serial data transmission. Although the T2288 is programmed only for asynchronous. **VSIM1 (SIM_VCC)** is originally programmed to 3V but if the card is 5V then the SIM card will be powered down and **VSIM1** will be reprogrammed to 5V. The signal levels for in and out of the SIM are now required to be level shifted within **GCAP II U900** to 3V. these signals are:

- **Reset** (Whitecap Pin E9 – **RST0**) in to GCAP II **Pin K7 – LS1_IN_TG1A**. This signal is then level shifted to the required voltage and fed out to **SIM Contacts J803 Pin 4** from **Pin J7 - LS1_OUT_TG1A**.
- Clock: This is a 3.25MHz signal from Whitecap **Pin E9 – CLK0 Pin E7** to GCAP II **Pin G6 – LS2_IN**. This signal is then level shifted to the required voltage and fed out to **SIM Contacts J803 Pin 6** from **Pin F6 – LS2_OUT**.
- **SIM I/O** – Data transmission to and from SIM card; for TX, from SIM card contact **SIM I/O Pin 5** through to GCAP II **Pin J8 SIM I/O**. Through level shifter to desired voltage and out through **Pin K10 (LS3_TX_PA_B+)** to Whitecap **Pin F3 DAT0_RX**. For RX data from Whitecap **Pin B5 DATA0_RX** to GCAP II, **Pin H8 – LS3_RX** where the signal is level shifted to desired voltage and outputted on Pin J8 **SIM I/O** to SIM contacts **Pin 5 SIM I/O**.
- **SIM_PD** – This signal is provided by the signal **BATT_SENSE**, activated by GCAP II, **BATTERY Pin F7**. If there are no batteries present then the unit will not power up. If batteries are present but the SIM card is either not inserted or faulty ‘CHECK CARD’ will be displayed. The reason behind this is to prevent the extra cost of a mechanical SIM presence detect switch and to prevent the SIM card being removed whilst connected to Aux Power.

Logic: Charger Circuit

- 1) The charging circuit contains the new **COVIC U960** (Charging and Over Voltage Integrated Circuit). See COVIC Block Diagram. There are 2 charge modes either full rate charge or Trickle current charge.
 - 2) Trickle Rate is used to safely charge a dead battery up to its usable range or to top up a charged battery.
 - 3) Full Rate is used to charge a battery within its usable range.
 - 4) For the circuit operation, as mentioned before the unit must first establish what type of charger is connected. The charger plug is inserted into the **Charger Jack J904**. This then results in **IRQ4 (EXT B+_DET)** being pulled low through **Q961** (supported by **V2**). This interrupt is sent to Whitecap **Pin M3**.
 - 5) Once **IRQ4** is received GCAP II **Pin A1** then checks the **MAN_TEST_AD** DC voltage level from Charger Jack **Pin 4**. The type of accessory connected will give a different voltage level, dependant on the value of the MANTEST resistor within. Some typical value are:
 - Illegal Charger - **MANTEST_AD** > 2.4V (unit does not beep, charge or enable backlights)
 - CLA - **MANTEST_AD** < 2.4V but > 1.7V (Unit beeps, enables backlights and starts to charge)
 - Easy Install Handsfree Car Kit - **MANTEST_AD** < 1.7V but > 0.8V (Unit beeps, enables backlights and starts to charge)
 - AC Charger - **MANTEST_AD** < 0.8V (Unit beeps, enables backlights and starts to charge)
- NB* CHGR_SW MUST BE HIGH FOR MANTEST_AD TO BE READ.**

- 6) When high **CHGR_SW** will limit the CLA or EIHF current output to 400mA, when low **MANTEST_AD** the current output is limited to 900mA. The AC charger output a current of approximately 350mA.
- 7) When the batteries are discharged and we turn the phone on, for the first second, full rate charge is delivered, (this is due to the LX signal for **V_BOOST** being unstable and therefore creating a power surge). This enables the phone to consume most of the current from the charger but at the same time trickle charge the batteries up to their usable voltage level. This is achieved by setting **ENABLE** 'high': from Whitecap Pin L7 to COVIC Pin 5 and **TRLK_SET** 'low' (Whitecap Pin K4 to COVIC Pin 2). The result of this is that the signal **DRV**, COVIC Pin 1 opens or closes the 'gate' of **Q960** (very similar to the **CHARGC** function of other GCAP II products). The charge is then fed through **CR960** and out to **dual-FET Q691** to charge the battery.
- 8) The circuit function describing when the batteries are in the usable range and normal full rate charging is enabled is as above, however the extra current now charges the batteries and the support voltage for the phone is taken directly from the batteries.
- 9) For High Rate trickle charging, again the operation is as above but **TRLK_SET** is set 'high' and **ENABLE** set 'low'.
- 10) For Low rate Trickle charging **TRLK_SET** is set 'low' and **ENABLE** is set 'low'
- 11) I Sense COVIC Pin 7 is used as a control for the charging DRV signal
- 12) The Over Voltage protection part of the circuit works in the following way:
- 13) The normal operating range of the batteries is between 3V through to 4.5V and an over voltage condition would be classed at >5.1V. If a transient above this occurred then this would be sensed by the current Sense resistor R960, and fed back into the COVIC on Pin 7. This would drive **ENABLE** 'low', enabling Trickle charge mode and reducing the current to the batteries to approximately 40mA.
- 14) If the transient is >6.1V then all charging stops. The over voltage comparator within the COVIC has hysteresis built in and the capacitors will begin to discharge until the voltage level is <5.1V at this point **I_SENSE** is reviewed again if still > 5.1V the unit begins to trickle charge.
- 15) Instrumental in both these operations being carried out successfully is a $10\mu F$ capacitor C970 (Situated near **V_BOOST** circuitry). As the transient occurs this capacitor charges up, and reduces the voltage rise to the COVIC circuit, therefore giving the COVIC more time to operate.

Logic: Deep Sleep Mode

- 1) Deep sleep mode is there to provide a facility to save battery life by intermittently shutting off part of the PCB. This is achieved in the following way. The signal **STBY_DL** is generated from Whitecap Pin **F1**, through a standby delay circuit **CR912** and **U906** and onto **Q834** and **Q912**. This has the effect respectively of:
- 2) Grounding **VREF** which makes MAGIC inoperable
- 3) Grounding **V2** This switches off MAGIC, Front END IC and inhibits the Transmit path through **RF_V2**
- 4) The shutdown is only for a fraction of a second and during that time the GCAP Clock supports the logic side of the unit. The GCAP clock is generated by **Y900**, which

generates a 32.768MHz clock. This clock is output from Whitecap **Pin C7** and fed directly to Whitecap **Pin P4**. The clock is always monitored by Whitecap and should it fail, the unit will no longer go into deep sleep mode.

Logic: Keypad Operation

- 1) The keypad works as a matrix supported V2. The signals inform the Whitecap upon a key press by dropping the signal ‘low’. Below is the Key Matrix.

	KBR0	KBR1	KBR2	KBR3	KBR4	KBC0	KBC1	KBC2	KBC3	KBC4	GND
KBR0	X	8	7	X	X	#	0	6	5	X	X
KBR1	8	X	1	X	X	9	SCROLL UP	3	2	X	X
KBR2	7	1	X	X	X	*	4	MAIL BOX	CLEAR	X	X
KBR3	X	X	X	X	X	X	X	X	X	X	VOL DOWN
KBR4	X	X	X	X	X	X	X	X	X	X	FM RADIO
KBC0	#	9	*	X	X	X	X	SHIFT	SCROLL DOWN	X	X
KBC1	0	SCROLL UP	4	X	X	X	X	X	MENU	X	X
KBC2	6	3	MAIL BOX	X	X	SHIFT	X	X	OK	X	X
KBC3	5	2	CLEAR	X	X	SCROLL DOWN	MENU	OK	X	X	X
KBC4	X	X	X	X	X	X	X	X	X	X	VOL UP
GND	X	X	X	VOL DOWN	FM RADIO	X	X	X	VOL UP		X

FM Radio: FM IC

- 1) The FM IC is new to any Motorola product and is incorporated into the V2288 Modulus II (R). It is controlled by the FM data bus, consisting of:

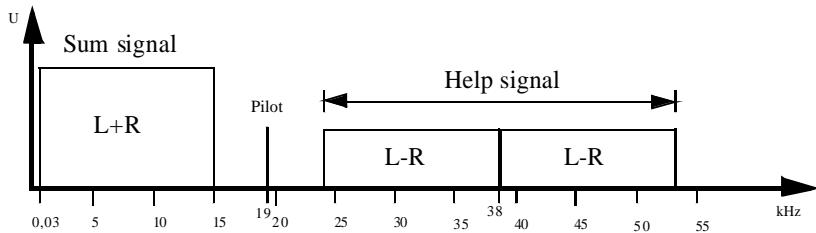
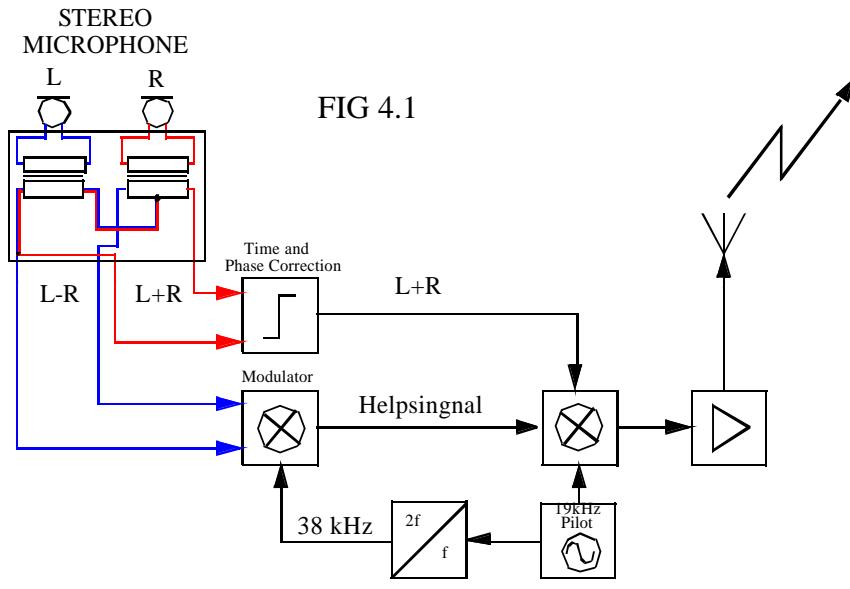
- **RW_AM_FM**: WhiteCap output **Pin M2**. When low, WhiteCap signal **DATA_AM_FM** (Whitecap **Pin N1**) is configured as an input to read data from the FM IC. When high, **DATA_AM_FM** is configured as an output. The Whitecap shall then send appropriate data to the FM IC.
- **CLK_AM_FM**: Whitecap output, **Pin D2**. This has two functions. 1st: To clock the SPI bus data (100KHz). 2nd: Tells the **MO_ST** output of the **FM IC U1001 Pin 26** to indicate the mono/stereo or the tuned / un-tuned status.
- **DATA_AM_FM**: WhiteCap data in/output.

Refer to FM IC Block Diagram

Basic FM IC Operation:
Receiver function

- 1) The antenna signal **FMin** is routed from the headset ground line through the antenna matching circuit into the tuned front end on **Pin 47** of the **U1001**. The front end and the FM Oscillator are tuned by the **TUNE** signal from the internal PLL circuit of the IC.
- 2) The output signal from the tuned front-end and the FM Oscillator are routed into the mixer stage. The output of the mixer is a 10.7 MHz IF signal; this is due to the FM Oscillator running 10.7 MHz above the antenna signal.
- 3) The 10.7 MHz IF signal passes the first IF filter and the first amplifier stage. Behind the amplifier the signal path is split in two-signal path.
 - The first supports the AM FM Indicator Stage that converts the IF signal to an analogue voltage. This voltage is routed to **Pin 22** of the **U1001** as **FM_RSSI**. The **FM_RSSI** level is corresponding to the receiver field strength.
 - The second passes the signal to the 2nd IF filter and IF amplifier to feed into the Demodulator stage.
- 4) The FM demodulator stage is using the **10.7 MHz crystal Y1003** to demodulate the IF signal. The output supports three different parallel filter stages.
 - The 1st is filtering the frequency-band from 0 to 15kHz that contains the **L+R** information.
 - The 2nd is filtering the frequency-band from 23 to 53kHz that contains the **HELP Signal**.
 - The 3rd is filtering the **19KHz** pilot tone and is working to detect the pilot to support the 38 kHz PLL/VCO stage.

See **Fig 4.1** for a block diagram of the transmitter stage to see how the 3 different bands are created.



- 5) The 38KHz PLL/VCO Stage needs to be phased because the amplified output is used to demodulate the **HELP SIGNAL** into the original **L-R** signal. The 2nd output of the amplifier is multiplied by 4 to get a 152KHz signal on **Pin 26** of the **U1001**.
 - This **152 kHz /MO_ST** signal output is used, while phasing, as a control signal for the test set. The tolerance should be +/- 2KHz.
 - The **MO_ST** part of the signal works in conjunction with the **CLK_AM_FM** signal to indicate the mono/stereo or tuned/not tuned status to the WhiteCap IC. (See table below)

CLK_AM_FM	MO_ST	Result to WhiteCap PA5
LOW	LOW	stereo
LOW	HIGH	mono
HIGH	LOW	tuned
HIGH	HIGH	not tuned

- 6) The **L-R** signal out of the mixer and the **L+R** signal from the 0-15KHz filter stage are feeding into the Decoder Matrix. Result of sum and difference are the left **FM_L** and

right **FM_R** audio signal at **Pins 15 and 16** respectively from the **U1001**. These are then fed to the **Stereo Audio IC U1500**.

FM Radio: Stereo Audio IC U1500

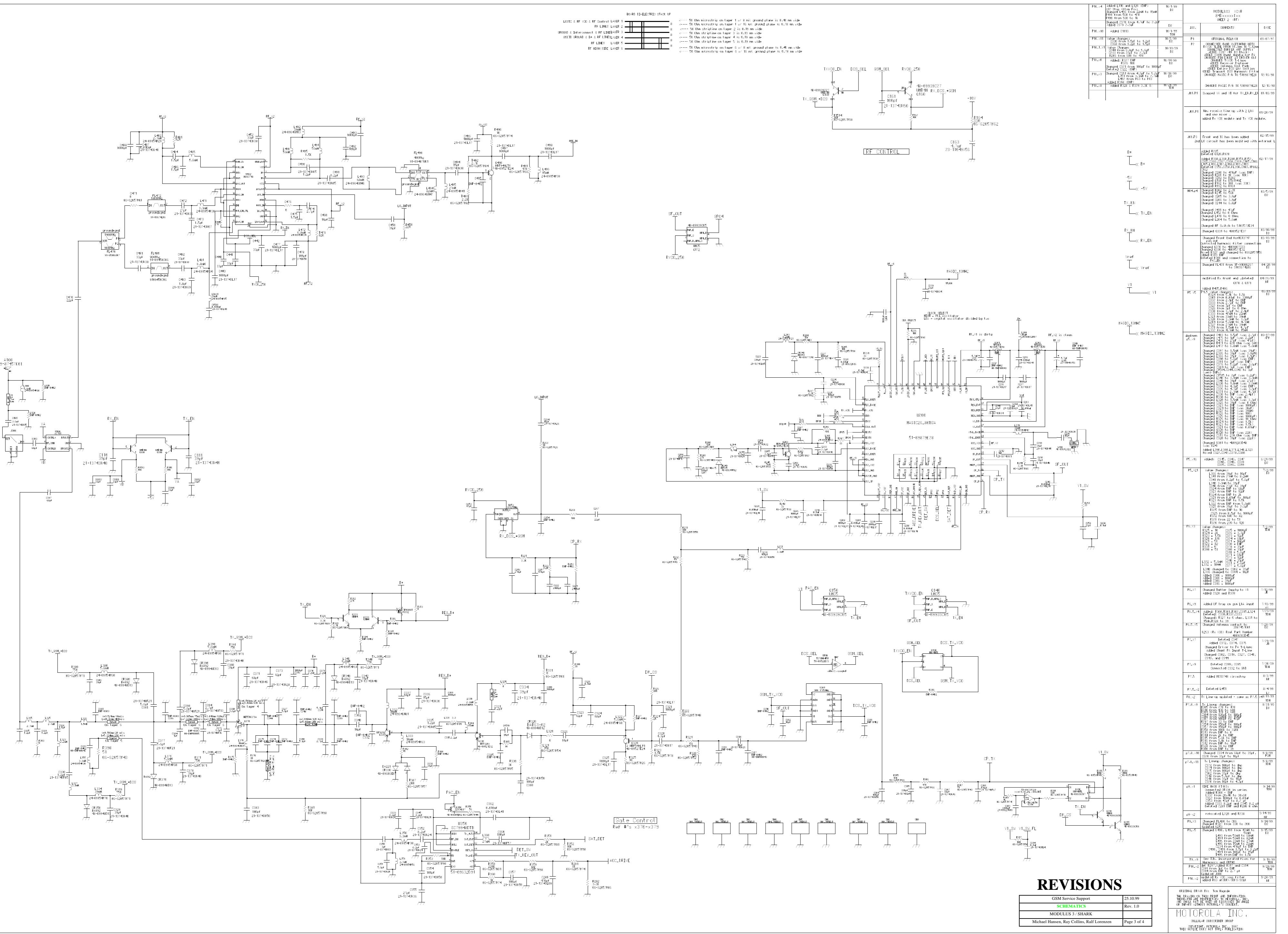
The Stereo Audio IC (sometimes referred to as JAMS IC) is basically a path selector for audio and has 6 different modes of operation. For further information refer to the Stereo Audio IC document.

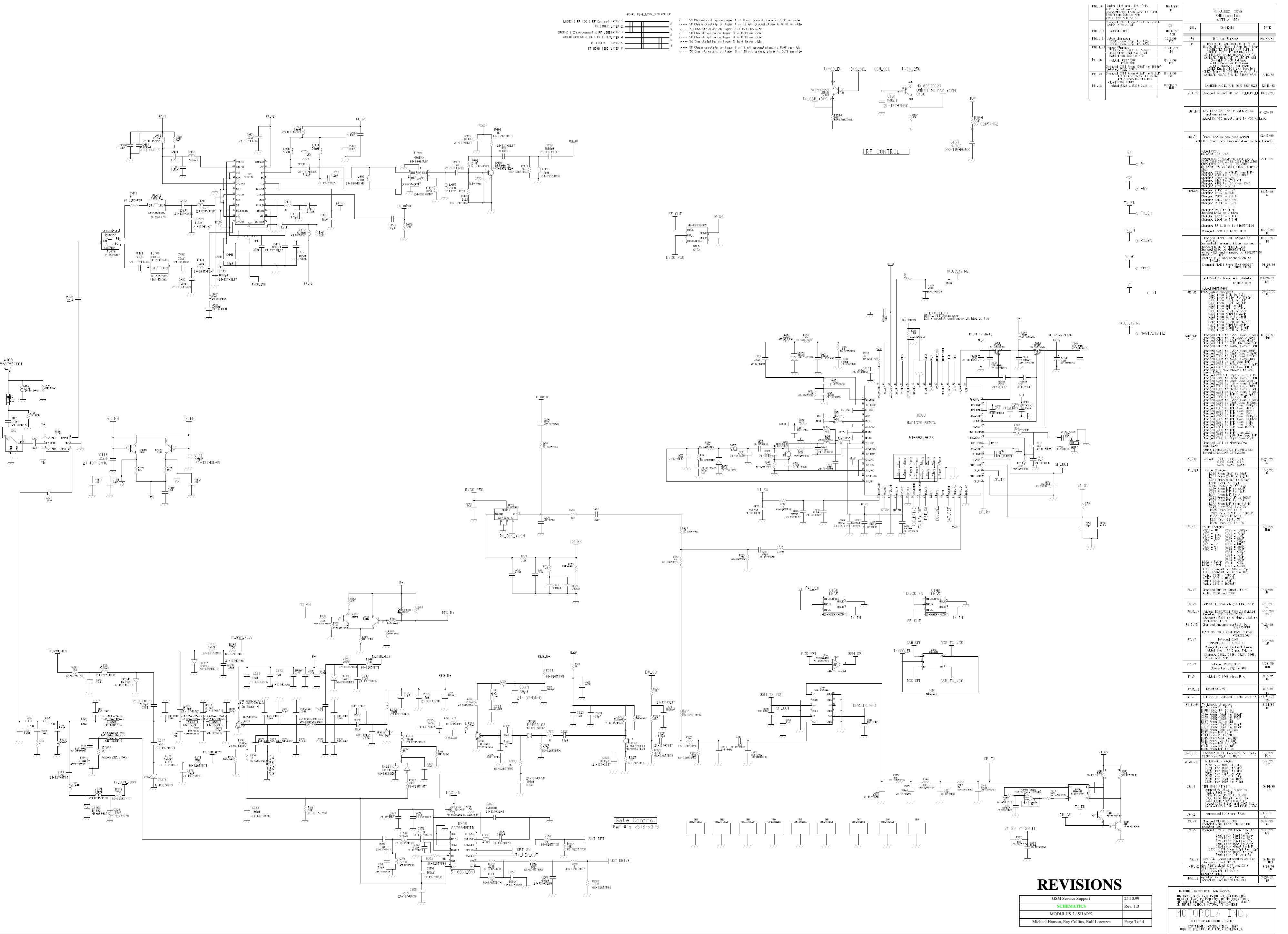
The 6 modes of operation are:

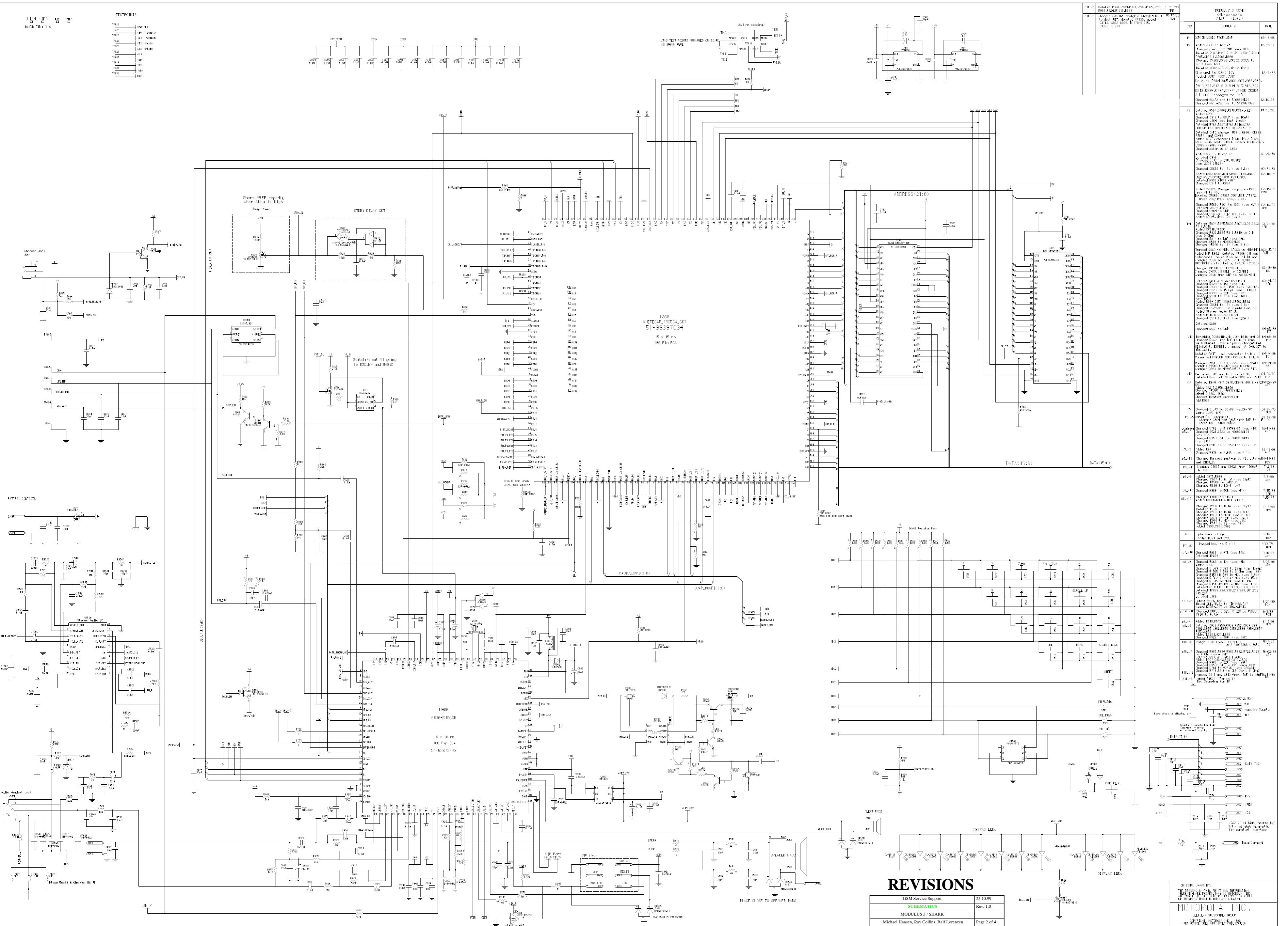
- 1) Voice to Earpiece Speaker – As with other GCAP II products Speech audio will be routed through the GCAP to **SPKR + and –**
- 2) Voice to Mono Headset – GCAP II **SPKR+** will be disabled and the speech will be routed from **SPKR –** to **VC_R_IN2** to drive **SPKR_R_OUT**. Left Channel will be muted.
- 3) Voice to Stereo headset – As above
- 4) FM Radio to Earpiece Speaker – Signal routed from FM IC to JAMS, from **VC_LOUT1** of JAMS the signal will be sent to the Aux Mic I/P of the GCAP II, within the GCAP the Codec is bypassed and both **SPKR + and –** are enabled. – **NOT USED**
- 5) FM Radio to Mono headset – R Channel of FM IC will be routed to **VC_R_IN1**, which will drive **SPKR_R_OUT**; the left channel of JAMS will be muted.
- 6) FM Radio to Stereo Headset – As above but in this circumstance the left channel of the FM IC and the JAMS will be enabled driving both **SPKR_R_OUT** and **SPKR_L_OUT** respectively.
- 7) **IRQ2** is used as a master-detect (Active Low) **JAMS DIV_REF** buffer and Comparator enabled.
- 8) **IRQ3** determines headset type i.e. Stereo or Mono

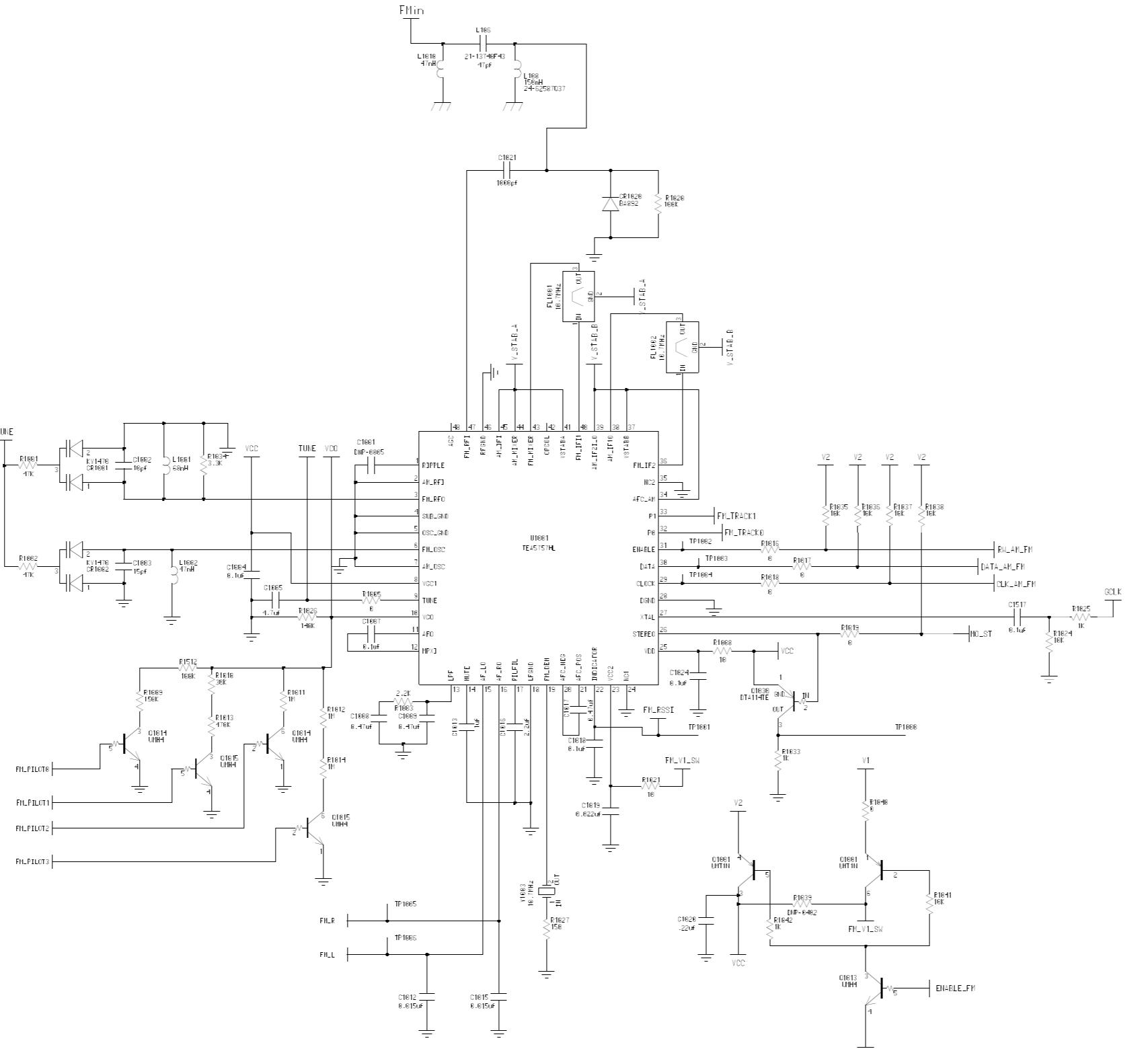
Logic: Display

- 1) The display is a 96 X 64 pixel graphics display and is connected to the PCB via a 16 Pin ZIF connector **J902**. The LCD is controlled by:
 - **CS1** Chip Select which originates from **DP_EN_L**, Whitecap **Pin A11** to **J902 Pin 1**.
 - **RES** which originates from **RESET**, Whitecap **Pin P2** to **J902 Pin 2**.
 - **R/W** which originates from **R_W**, Whitecap **Pin P2** to **J902 Pin 2**.
 - 7 Data Lines from Whitecap **DO – D7**
 - The display is supported by **-5V** originating from **U903** and can be measured on **C963** and **V2**
 - Also the data / command signal **AO** from Whitecap **Pin B12**.



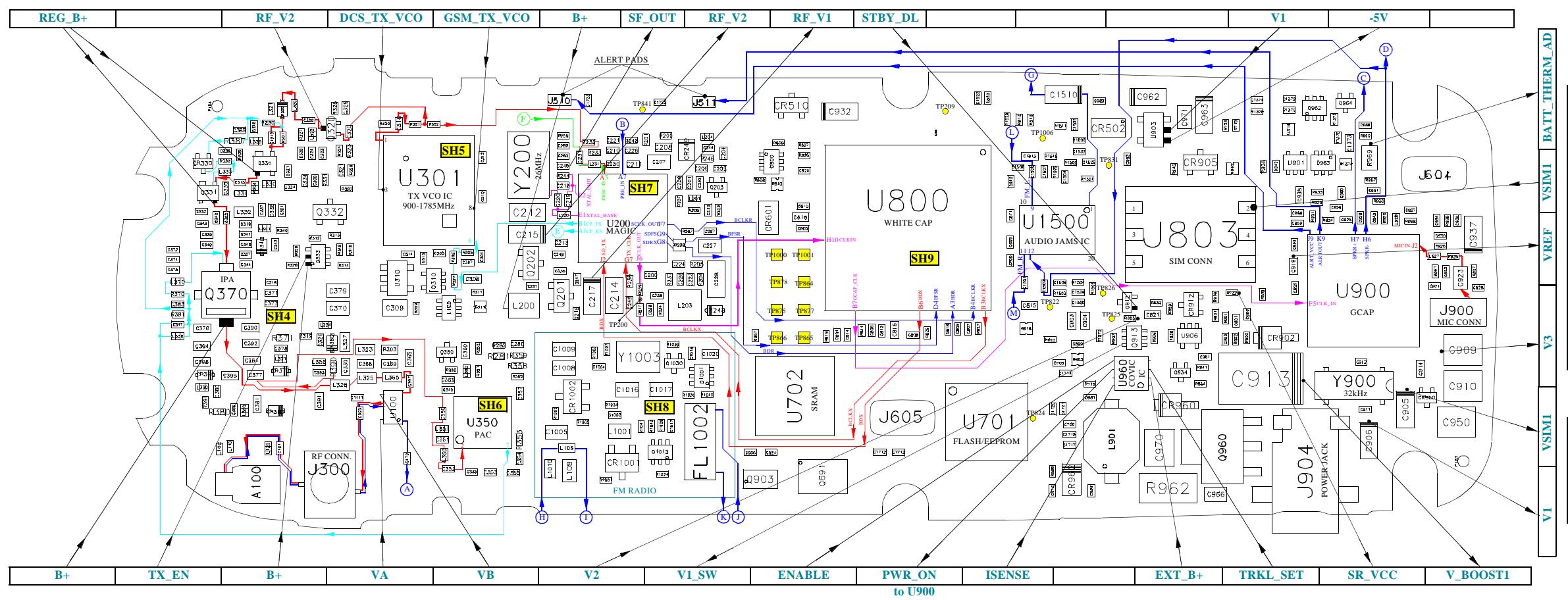






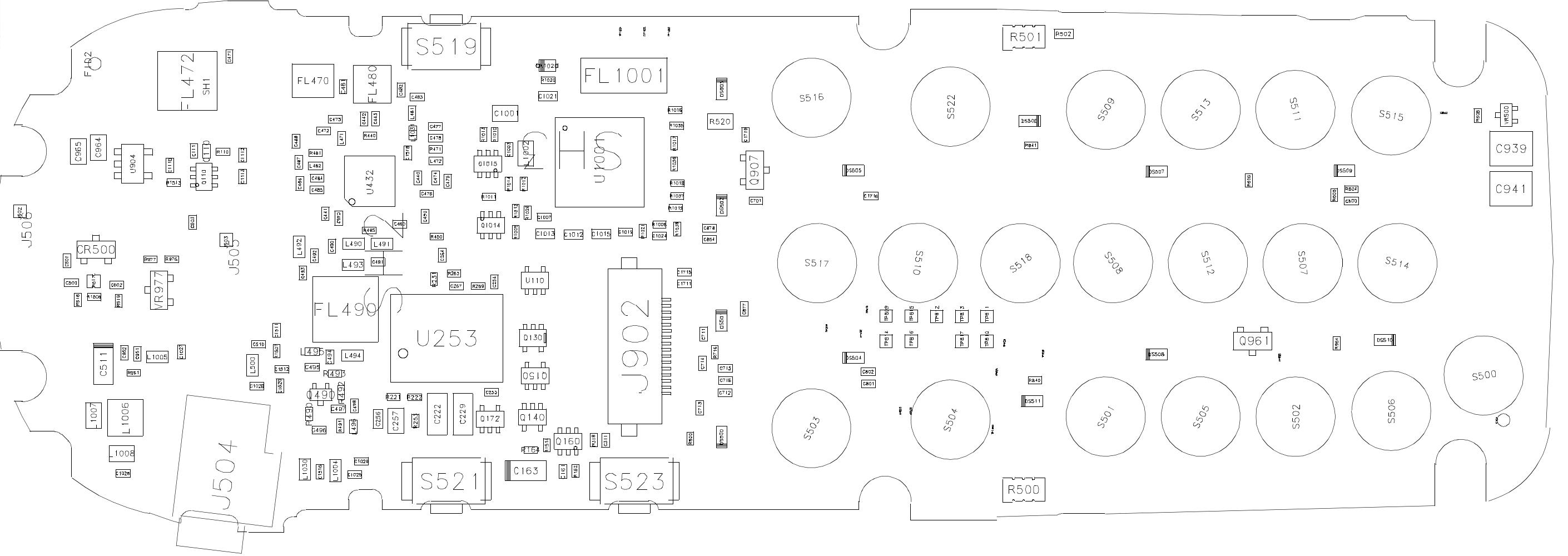
Dualband Modulus III (Shark) 8485933H04_P13

 GSM Service Support
Level 3 Authorized



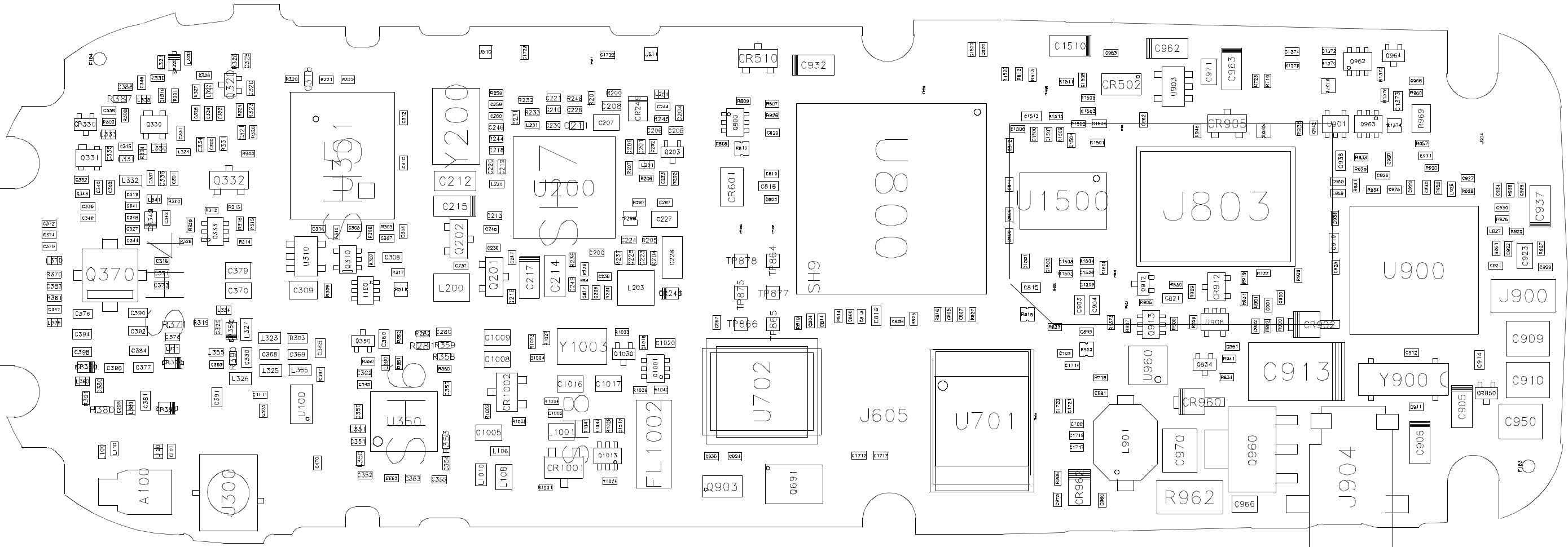
Dualband Modulus III (Shark) 8485933H04_P13

 GSM Service Support
Level 3 Authorized



REVISIONS

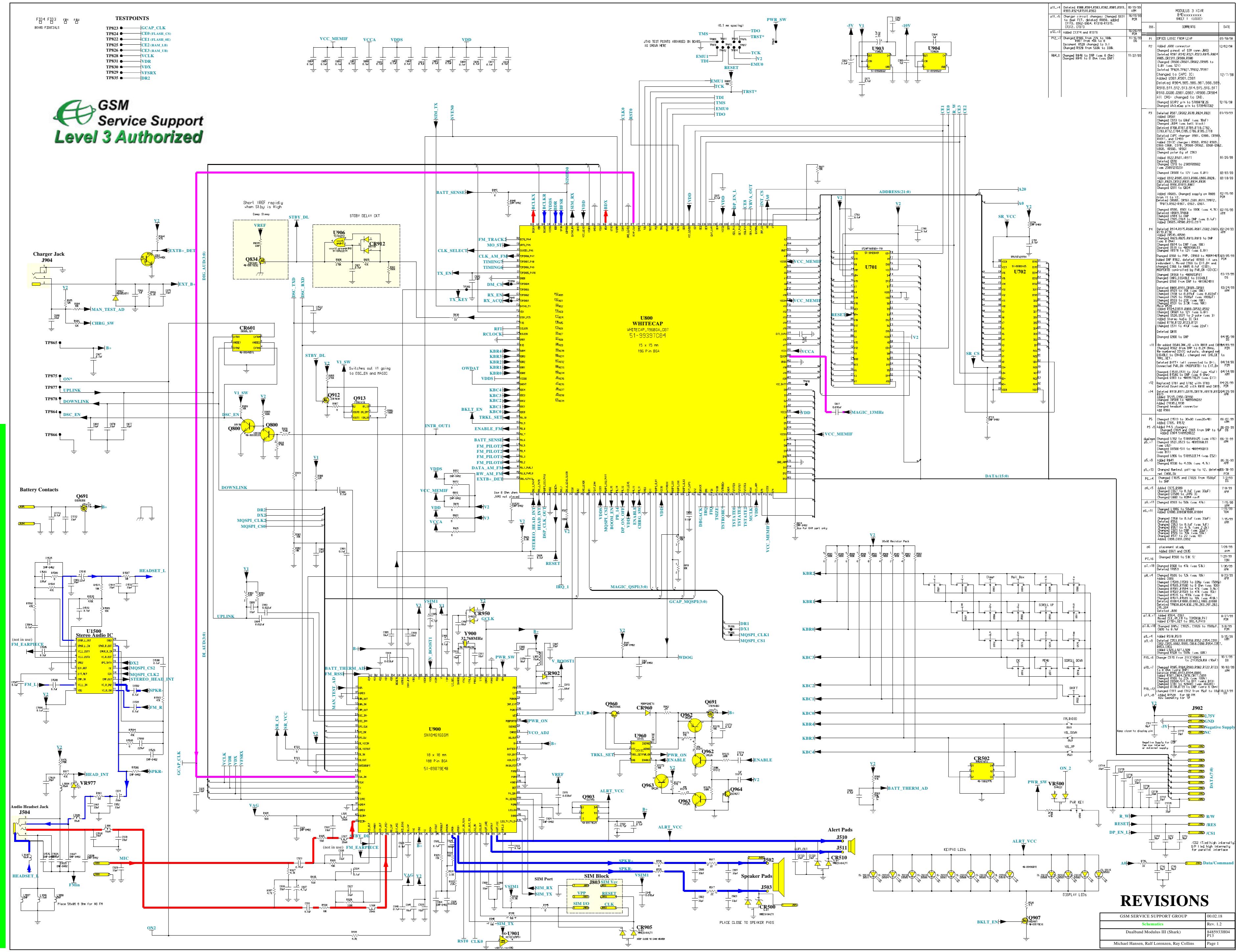
GSM SERVICE SUPPORT GROUP	12.04.00
LEVEL 3 LAYOUT	Rev. 1.1
Modulus III (Shark)	
Michael Hansen, Ralf Lorenzen, Ray Collins	Page 2 of 2



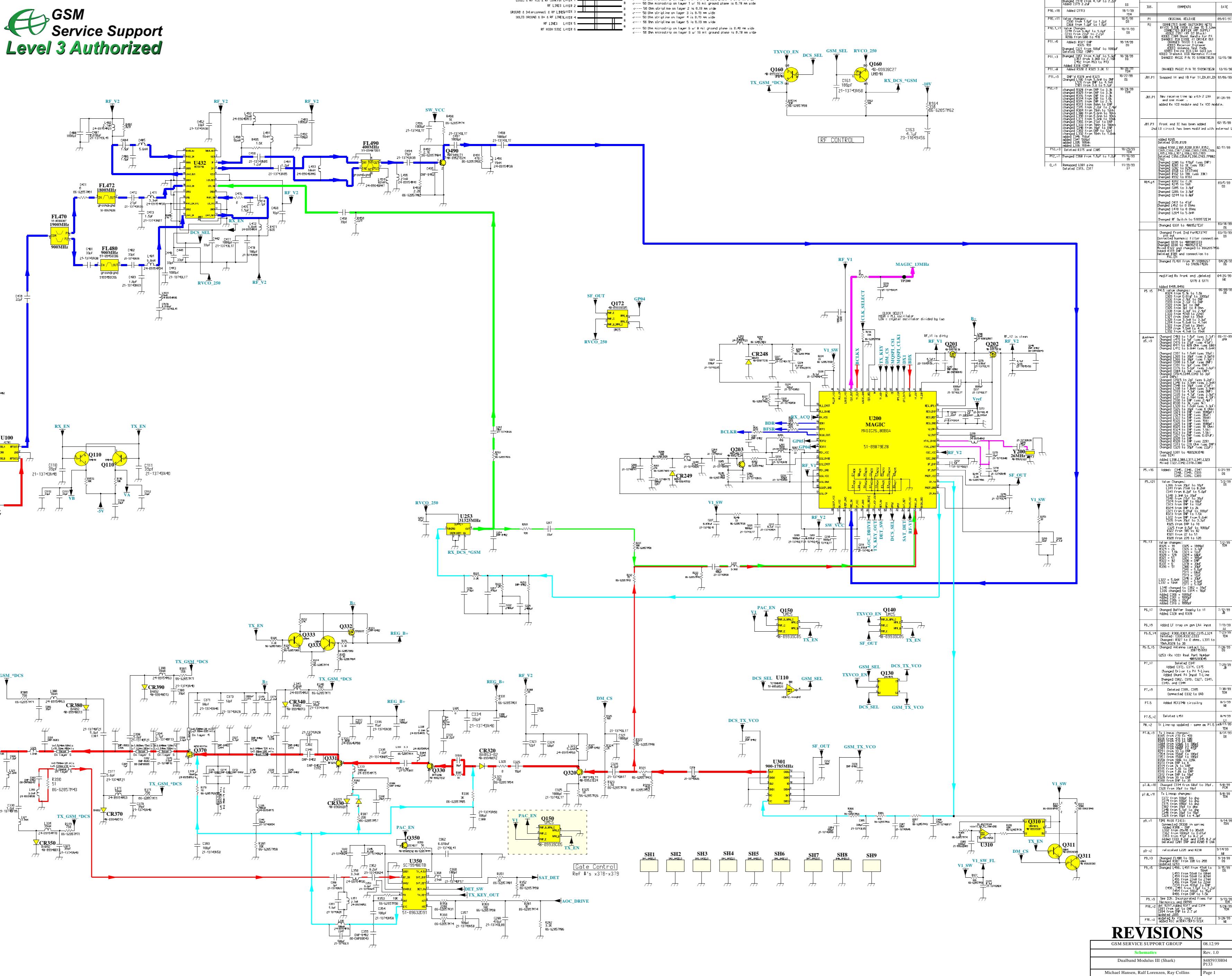
REVISIONS

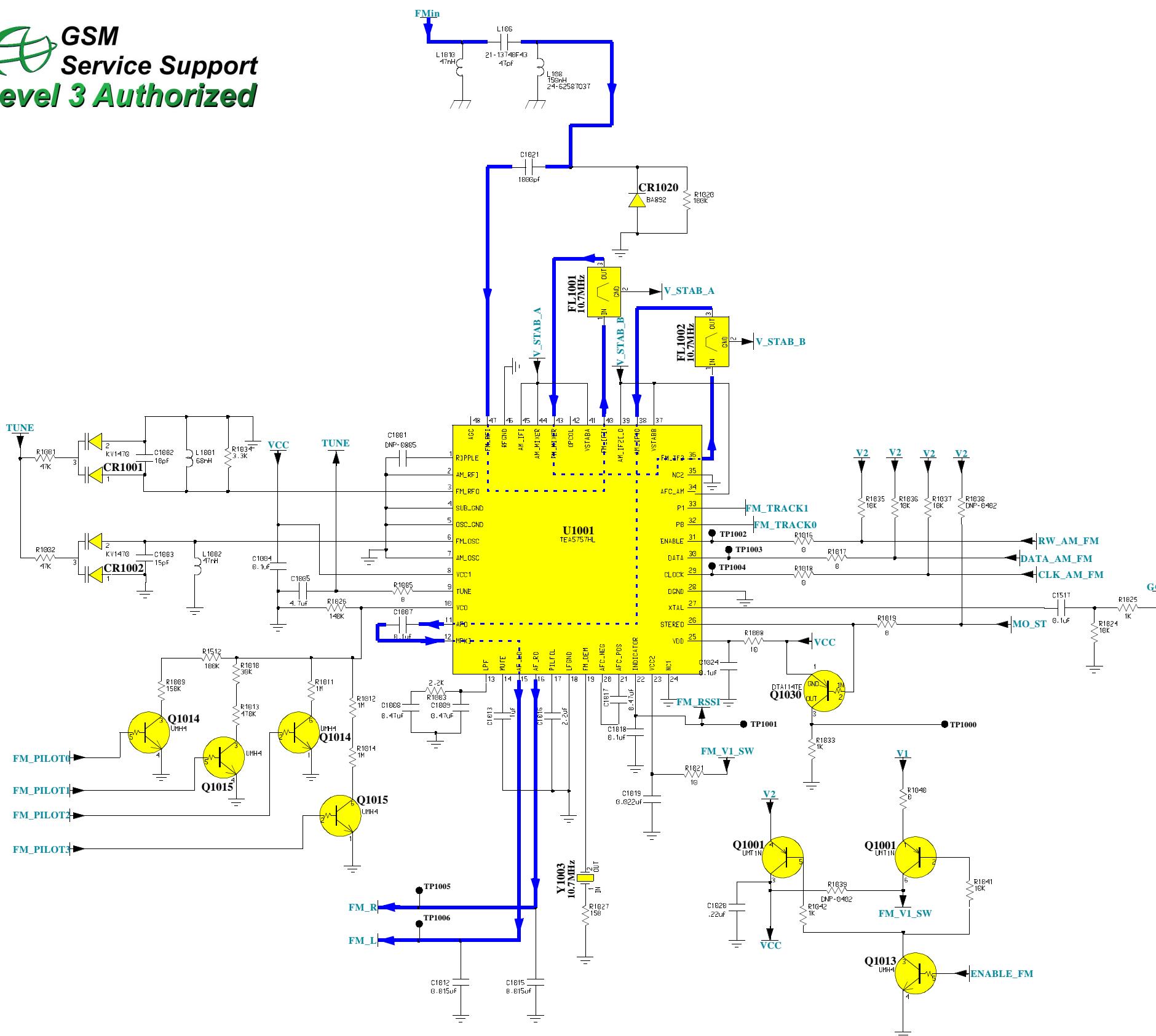
GSM SERVICE SUPPORT GROUP	12.04.00
LEVEL 3 LAYOUT	Rev. 1.1
Moddulus III (Shark)	
Michael Hansen, Ralf Lorenzen, Ray Collins	Page 1 of 2

Dualband Modulus III (Shark) 8485933H04_P13



Dualband Modulus III (Shark) 8485933H04 P13



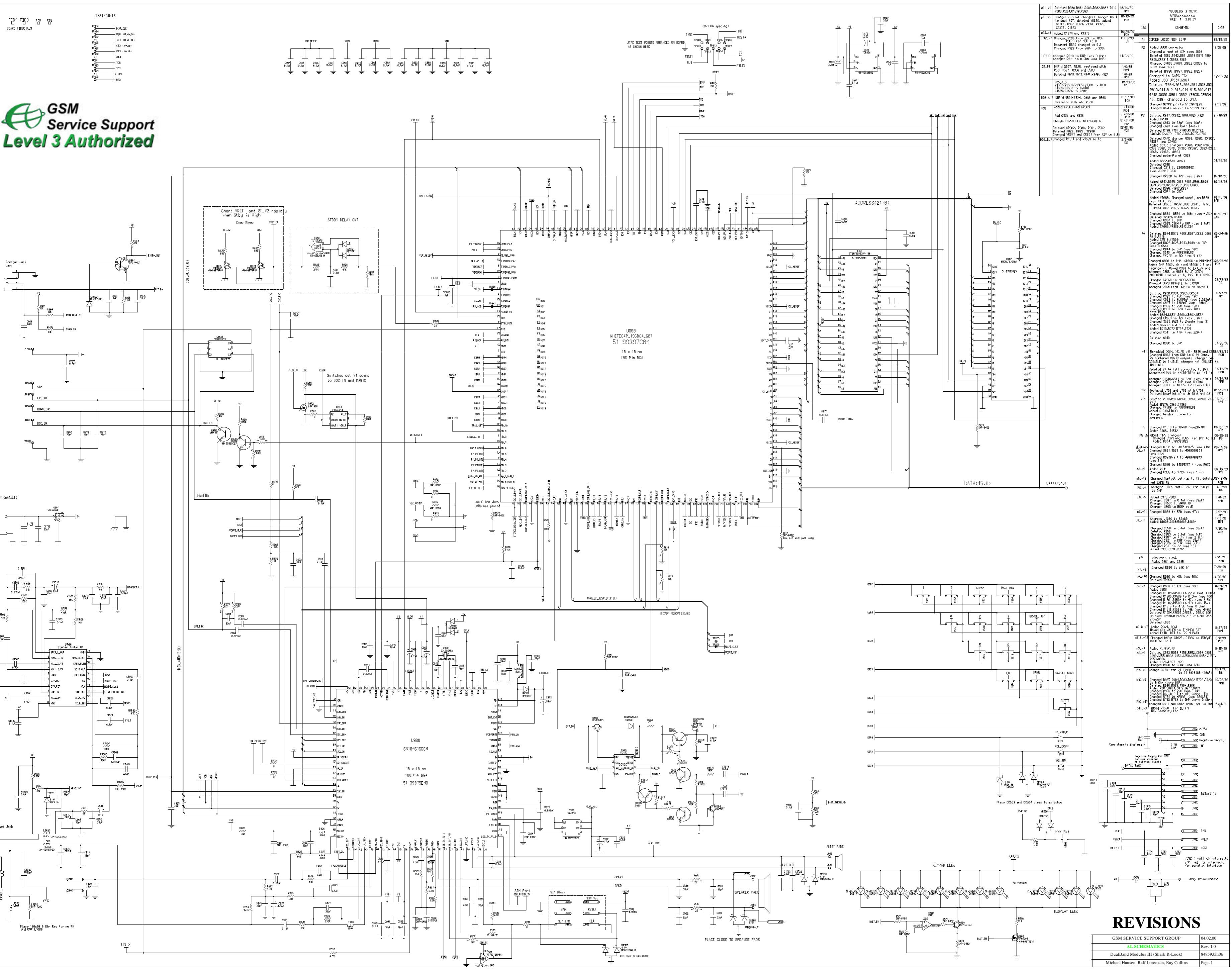


MODULUS 3 XCVR 8485933H04_P13		
ISS.	COMMENTS	DATE
P1	CREATED FROM PHILIPS DEMO BOARD	16/08/98
P2	L1001: Changed value from 55nH to 68nH L1002: Changed value from 55nH to 68nH C1003: Changed value from 10pF to 8pF R1013: Changed value from 10pF to 8pF R1012: 10k to DNP C1001 4.7uF --> DNP C1013: 4.1uF to 1uF C1005: 330pF --> .1uF C1012, C1015: .01 --> .012uF C1019: .081uF --> 0.022uF C2491: .22uF --> .1uF R1001: 18k to 47k R1002: 18k to 5.6k	12/11/98
P3	Added R1018,R1025,C1025,C1022,C1020, R1020 Changed C1003 to 1uF (was 47uF) Changed C1003 to 12pF (was 10pF) Changed C1007 to 10uF (was .22uF) Changed C1024 to 1uF (was .22uF) Changed C1024 to 100pF (was 4700pF) Changed C1023 to 15uH (was 25uH) Changed C1023 to 10uH (was 10uH) Changed R1011,R1016 to DNP (was 200) Changed D1008 to DNP (was 200)	04/02/99
P4	Changed L1001, L1002 to 47nH Changed C1003 to 18pF Deleted CR1001, CR1002, C1003, CR1004 Added R1025 10k to 3 pin package Changed C1005 to 4.1uF Added NO ST	02-23-99
P4	Replaced 44 pin IC with 48 pin LOFP Added R1021 Deleted TP u new P/N for FL1001, FL1002 and FL1003 Replaced varactors CR1001, CR1002 Deleted C1010, C1014, C1011, C1023, C1025, R1004, R1005, R1006, R1007, R1022, R1023, R1024, R1025, U1002 Updated transistor designators Added C1008, R1012 Changed C1013 to 2113928P04 1uF Changed C1001 to 2113928C04 4.1uF Changed C1001 to 50x80 DNP	04-02-99 AM
P5_v3	Added TP1002-TP1005 Added R1015 Added C1025, R1024, R1025 Changed R1002 to 47k (was 18k) Changed R1002 to 5.6k (was 18k)	06-16-99 AM
P6_v4	Added R1007 = DNP Changed C1002 from 1500pF to DNP Changed L1005 from 6.55nH to 360pF Changed L1008 from 6.55nH to 350nH Deleted L1011	07-02-99 US
P6_v5	Changed Discriminator from FL1003 to Y1003 (4887820K01)	07-28-99 DS
P7_v10	Added R1005 (D) near C1005	7-38-99 DS
P7_v2	Changed L1001 from 47 nH to DNP Changed L1002 from 47 nH to 56 nH Changed C1008 from 18 pF to 6.8 pF Changed C1003 from 18 pF to 12 pF Removed C1005	8-4-99 LV/GM
P8	R1015 --> R1019 From DNP to 0 L1002 to 6805 DNP Add R1034 4.1k C1002/3 --> 18pF R1002 --> 1k C1036 --> C1032 DNP C1012/C1015 --> 6.615uF Deleted R1007 Added R1035-R1038 Added R1040	8-20-99 BR/SNL
P8	Deleted: C1022, L1003, C1002, C1039 Deleted: R1013, R1012, R1028, C1033	8-23-99 DS
P5_v3	Changed R1011 and R1012 to Tape and Reel part numbers L1001 from DNP to 55nH L1002 from DNP to 47nH	9-14-99 DS
P5_v3	L1010 TO 47nH/L1015 TO 47pF C1003 TO 15pF (was 10pF) R1034 TO 18pF (was 10pF) R1034 TO 15pF (was 10pF) C1003 TO 15pF (was 10pF)	9-15-99 DS
P11_v3	Added R1013 (4700), R1014 (10k), R1015 (10k), R1016 (10k), Changed C1001 to 488923C16 R1025 from 10k to 140k R1012 from 15k to 100k R1013 from 15pF to 10pF R1016 from 820k to 200k R1011 from 1.6M to 1M R1012 from 3.3M to 1M Updated TP Geometry	10/18/99 DS

REVISIONS

GSM SERVICE SUPPORT GROUP	07.12.99
Schematics	Rev. 1.0
Dualband Modulus III (Shark)	8485933H04_P13
Michael Hansen, Ralf Lorenzen, Ray Collins	Page 1

DB Modulus III (Shark R-Look) 8485933h06





MOTOROLA

Shark level 3 debug

issue 17/02/2000

SHARK Modulus 3

Dual band level 3 debug

Version: 1.0

Date: Feb , 02 , 2000

Total Pages: 19

Prepared by _Fabrizio
Alba_____

Approved by _____

**MOTOROLA****Shark level 3 debug**issue 17/02/2000

REVISION HISTORY

Version	Date	Name	Reason
1.0	23/12/1999	Fabrizio Alba	First release



**Supply phone by means No 3
standard 3AAAL NiMH batteries
code SNN5542 and check following
tests sequence**

**For any page see
electrical
diagram
equivalent**

**Modulus 3
test sequence**

**Does phone
power up
correctly ?**

NO

Go to " no
power up "
on pag. 03

**Does phone
draw a lot of
current ?**

YES

ON
FUTURE

**Does display
works
correctly?**

NO

Go to " no
display " on
pag.11

**Does
backlight
works
correctly?**

NO

Go to " no
backlight "on
pag.11

**Does keypad
works
correctly?**

NO

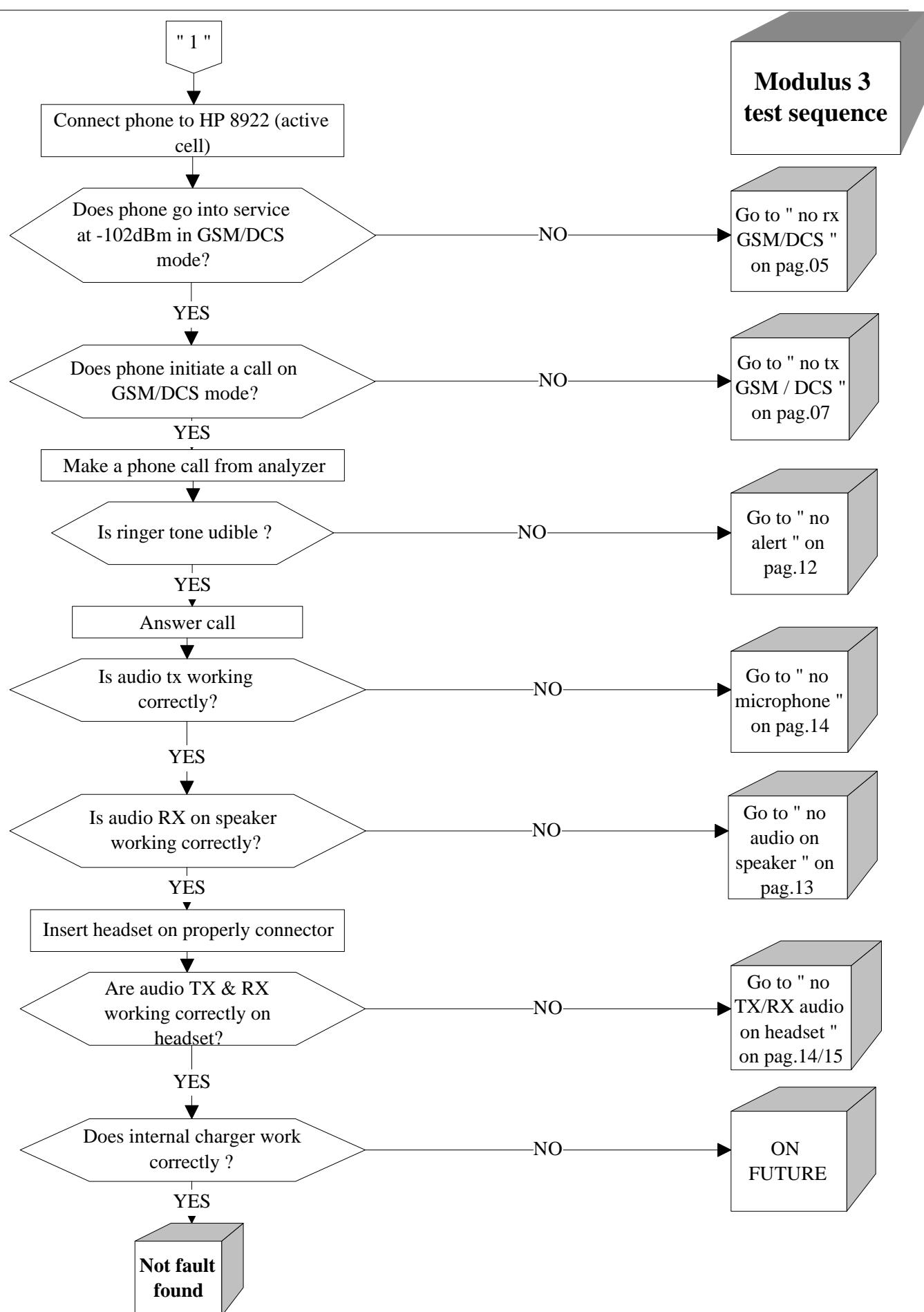
Go to " no
keypad " on
pag.12

**Does phone
shows "phone
failure see
supplier ?**

YES

ON
FUTURE

**go to " 1 "
PAG 02**

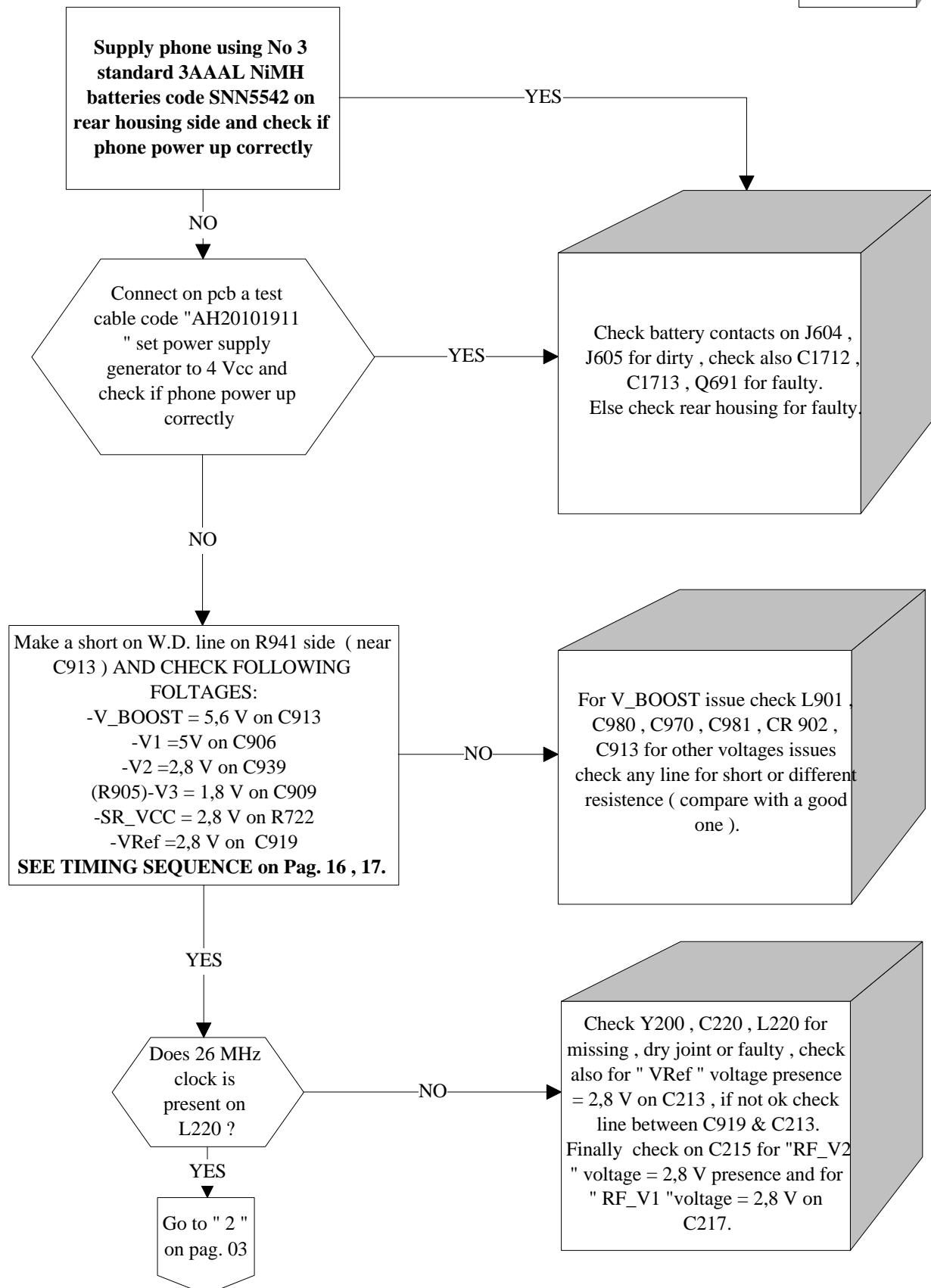


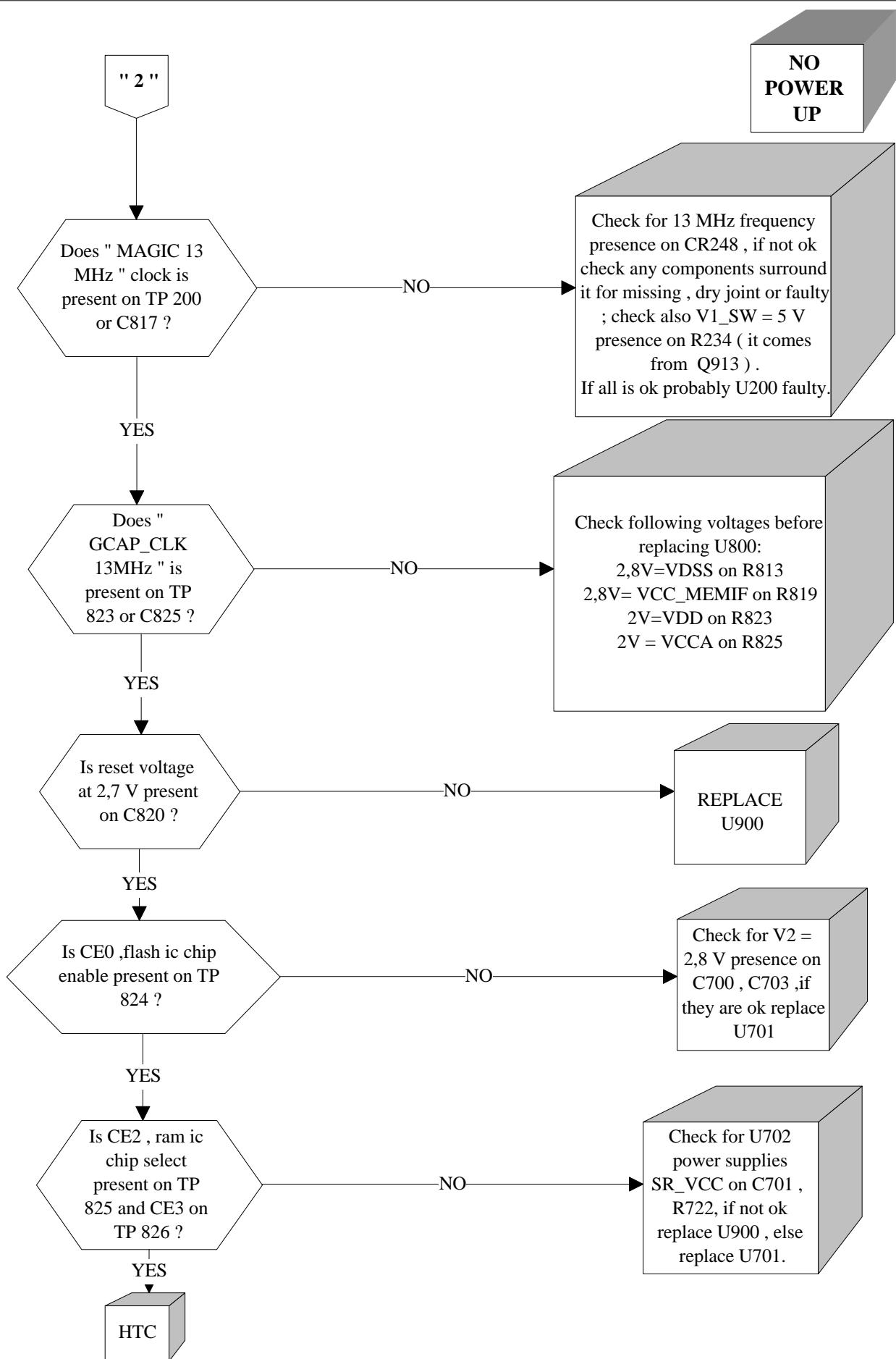


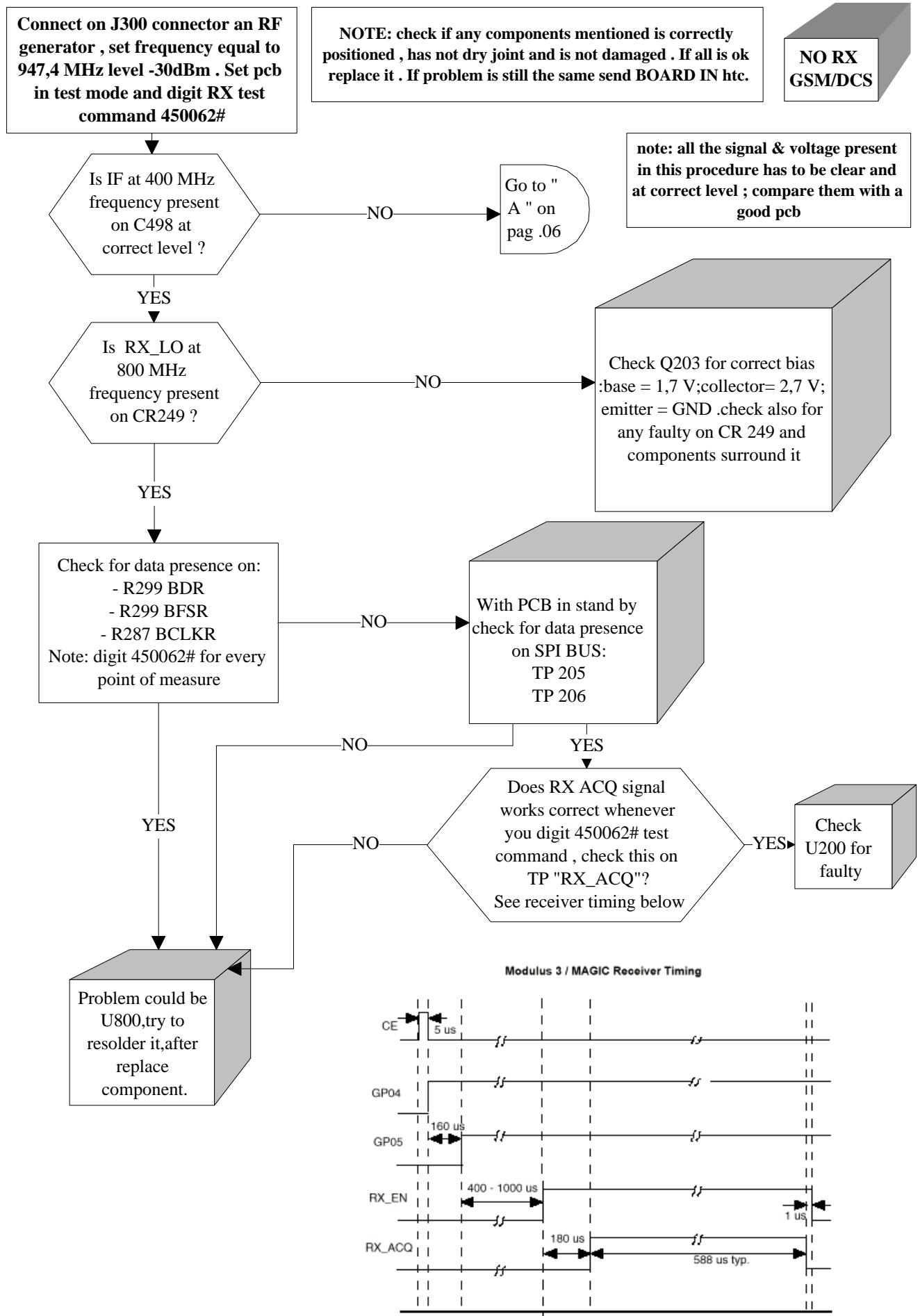
note: all the signal & voltage present in this procedure has to be clear and at correct level ; compare them with a good pcb

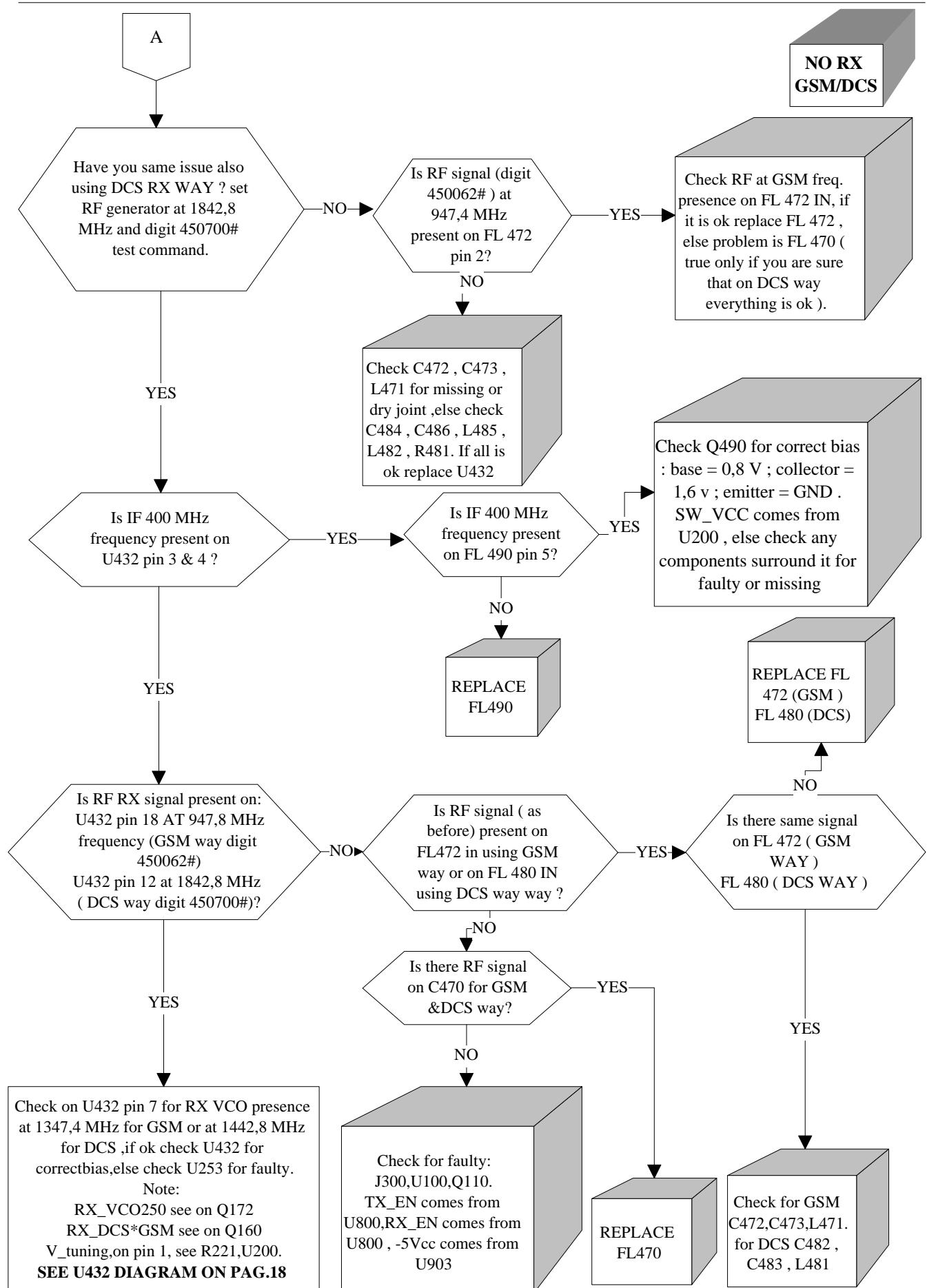
NOTE: check if any components mentioned is correctly positioned , has not dry joint and is not damaged . If all is ok replace it . If problem is still the same send BOARD IN htc.

NO
POWER
UP











note: all the signal & voltage present in this procedure has to be clear and at correct level ; compare them with a good pcb

NOTE: check if any components mentioned is correctly positioned , has not dry joint and is not damaged . If all is ok replace it . If problem is still the same send BOARD IN htc.

NO TX
GSM/DCS

NOTE 1 : You can use this procedure for GSM way & DCS way.

Whenever you have a signal with a symbol star (*) means that it is active low if you select this kind of way , while the same point of measure will be high for other way.

Differences between GSM & DCS way are:

TX_GSM*DCS

used for adjust all RF TX way for GSM/DCS choice
for any problem check on Q160

DCS_SEL comes out from U200 (or pin 2 U110)

GSM_SEL comes out from U110 pin 4

-10 V comes out from U904.

DCS_TX_VCO , GSM_TX_VCO

for any problem check Q130

Connect on J300 connector an RF spectrum analyzer , set pcb in test mode and digit following test command:

110062# 1215# 40# for a test in **GSM** way.

110700# 1215# 40# for a test in **DCS** way.

Check for RF signal presence at frequency = **902.4 MHz for GSM or 1747.8 MHz for DCS**.

**RF IS PRESENT ,
NEVER MIND
LEVEL BUT IS
DIRTY**

**RF IS NOT
PRESENT**

**RF IS
PRESENT
BUT IS LOW**

Is RF TX signal
at GSM/DCS
frequency present
on U301 pin 4 ?

YES

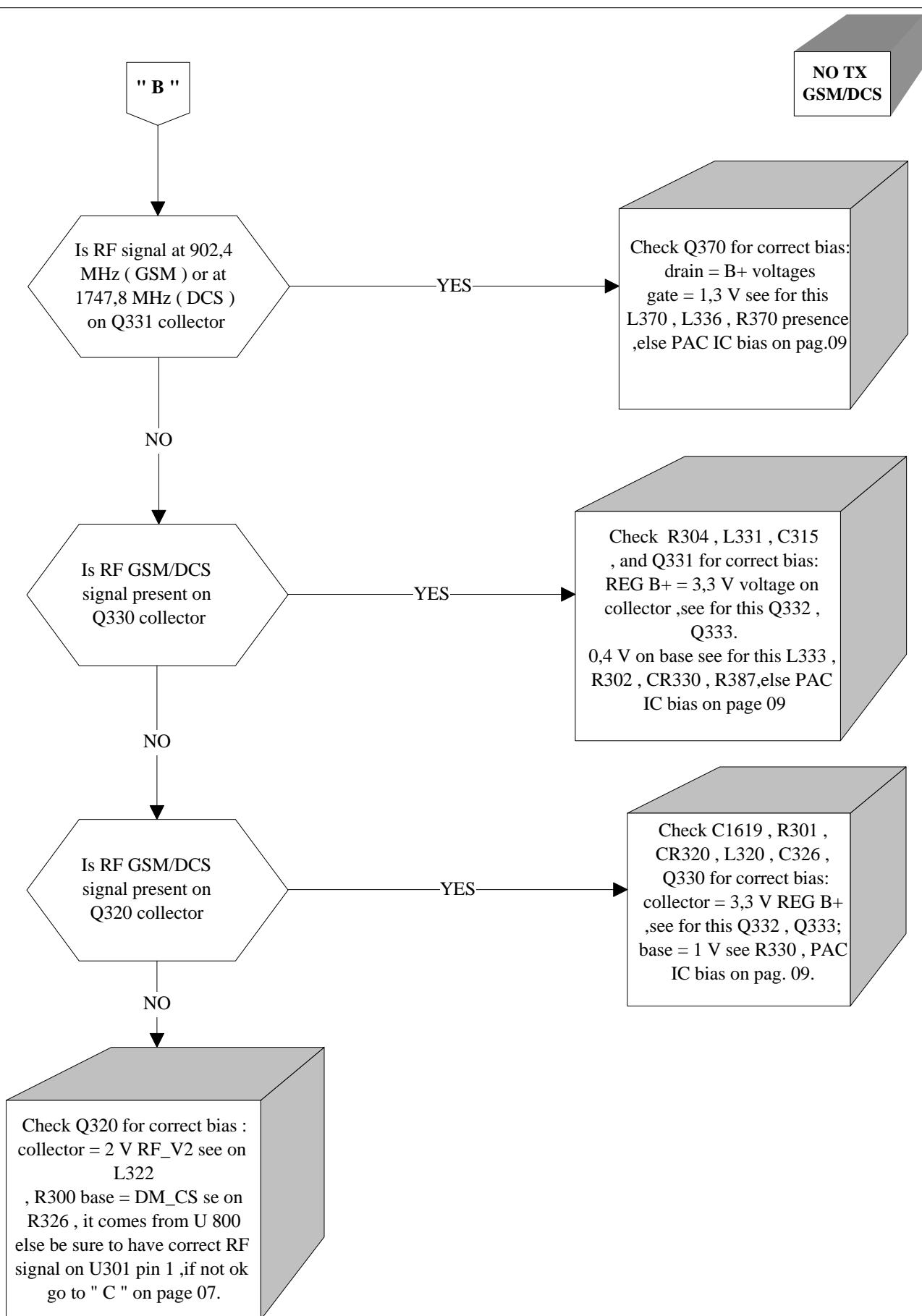
Is RF TX
GSM/DCS
present on
Q370 DRAIN?

NO

Go to "
B " on
pag.08

Check on U301:
pin 3 DCS_TX_VCO see on Q130 , Q140.
pin 8 GSM_TX_VCO see on Q130 ,
Q140.
pin 10 SF_OUT see on C246 (comes from
U200 9 .
pin6 CP TX check for this Q310 , Q311 ,
U310 , U200 , R305 , R306 , R307.
DM_CS , TX_EN , they comes from U800
VI_SW comes from Q913

Check:
L365 , L325 , L326 ,
C397 for missing or dry joint
, else check for faulty Q110 ,
U100.
-5V cc see U903
TX_EN , RX_EN comes
from U800

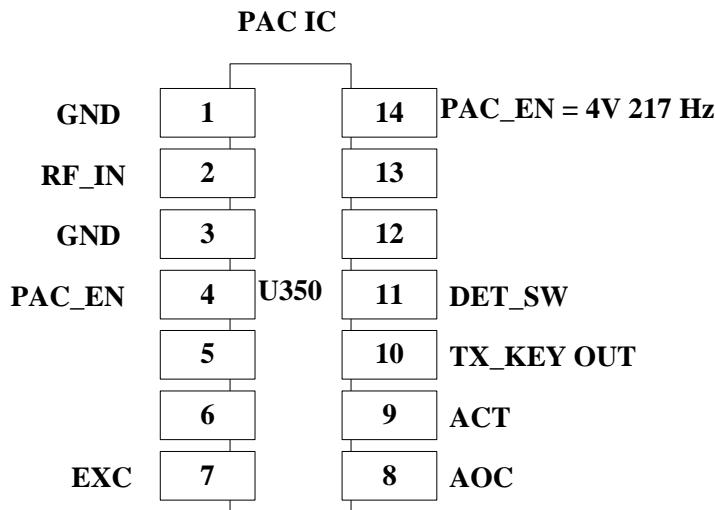




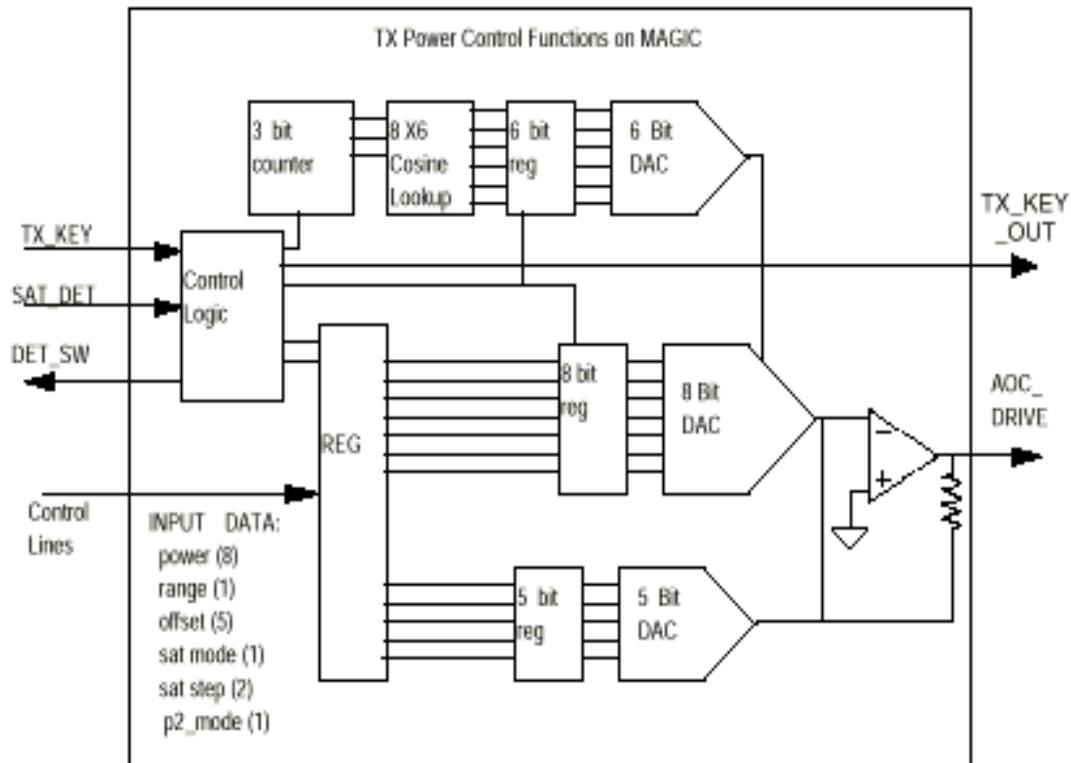
note: all the signal & voltage present in this procedure has to be clear and at correct level ; compare them with a good pcb

NOTE: check if any components mentioned is correctly positioned , has not dry joint and is not damaged . If all is ok replace it . If problem is still the same send BOARD IN htc.

NO TX
GSM/DCS



pin 4,14 PAC_EN comes from Q150 via Q350
(TX_EN comes from U800)
pin 8 , 9 , 10, 11 comes from U200 if not ok
check : SPI BUS on TP 205 & TP 206 for data
presence with pcb in stand by.
TX KEY see on TP 209
DM_CS see on TP 208.
**NOTE: REFER DIAGRAMS BELOW &
on pag. 10 FOR TIMING TX.**

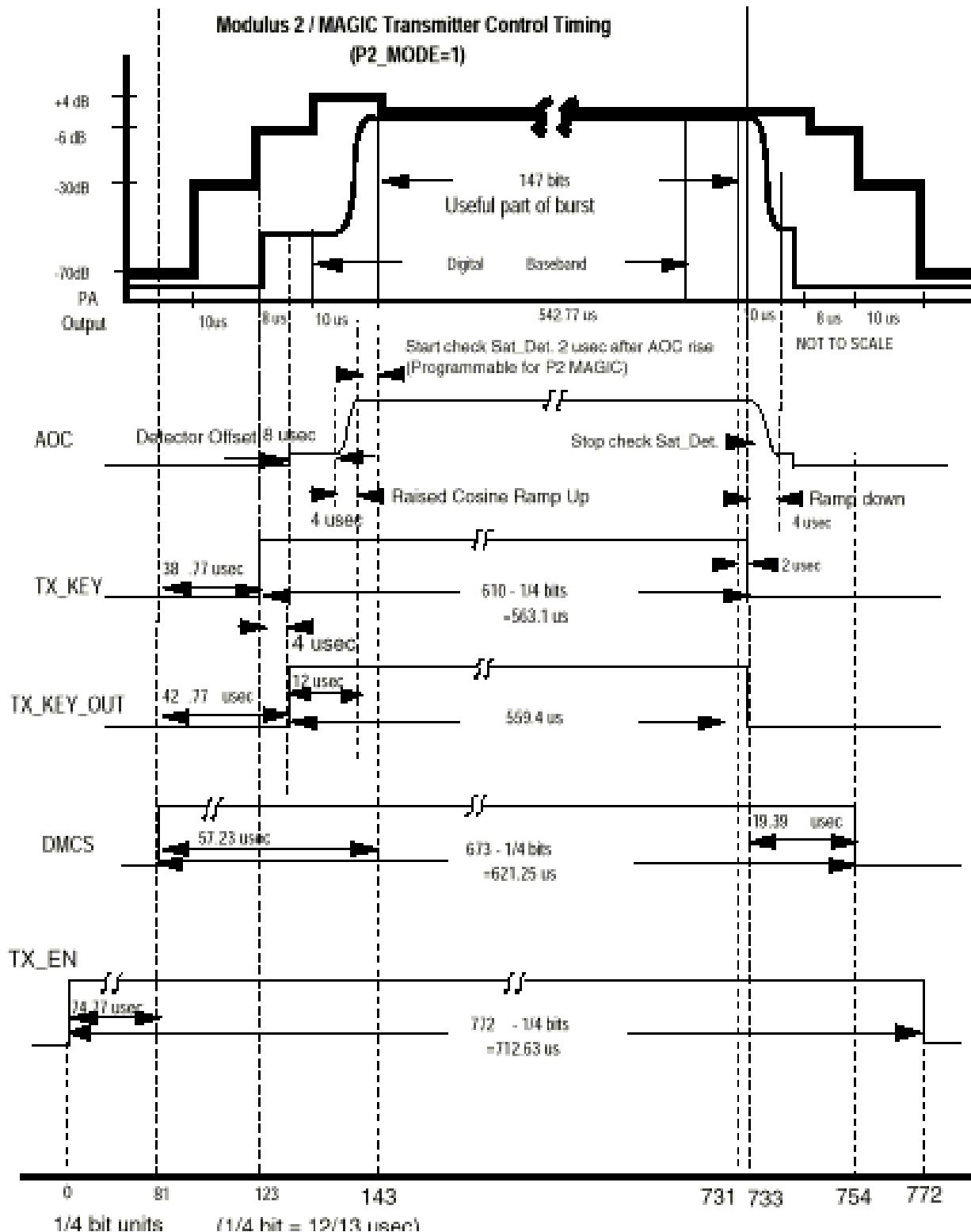


TX POWER CONTROL ON U200 IC



note: all the signal & voltage present in this procedure has to be clear and at correct level ; compare them with a good pcb

NOTE: check if any components mentioned is correctly positioned , has not dry joint and is not damaged . If all is ok replace it . If problem is still the same send BOARD IN htc.



MODULUS 2 TX TIMING on U200



note: all the signal & voltage present in this procedure has to be clear and at correct level ; compare them with a good pcb

NOTE: check if any components mentioned is correctly positioned , has not dry joint and is not damaged . If all is ok replace it . If problem is still the same send BOARD IN htc.

CHECK CARD

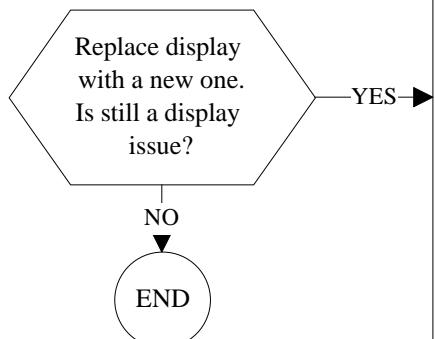
Supply PCB using pcb test cable code **AE20101903**.
Set pcb in test mode and digit 38# sim test enable
and check on J803 sim connector :
1 = GND
2 = SIM VCC 5V SEE u900 (C906)
3 = NC
4 = RESET see CR905 , R940
5 = SIM I/O see R945 , U901 , R938.
6 = CLK see R940

YES

Probably U800 faulty

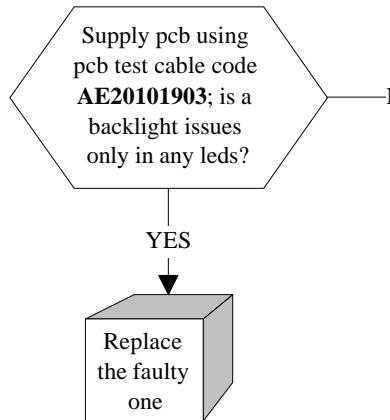
NO

Check, in order , U900 , U800 for faulty



Check on J902 display connector for presence of:
1 =data DP_EN it comes from U800
2= 2,7 V RESET it comes from U900
3= data A0 see R716 for missing
4= data R_W it comes from U800
from 5 to 12 = data see on C1714 to C1720
13 = 2,7 Vcc V2 it comes from C939
14 = GND
15 = -5 Vcc it comes from U903.
If all is ok probably U800 faulty.

NO DISPLAY



Check on Display led's anode for ALRT_VCC = 3 V presence , if not ok check Q903 and consequently U900 for faulty.
Check also on Q907 gate for BKLT_EN = 2,7 Vcc , in this way on led's chatode there must be 1 V , if not ok check for R520 presence ,else replace Q907

NO BACKLIGHT



note: all the signal & voltage present in this procedure has to be clear and at correct level ; compare them with a good pcb

NOTE: check if any components mentioned is correctly positioned , has not dry joint and is not damaged . If all is ok replace it . If problem is still the same send BOARD IN htc.

**NO
KEYPAD**

Remove keypad membrane and check if here is any issues (dirty , track , solder) on key contacts from S501 to S522.
Check also R500 , R501 , R502 for V2 = 2,8 Vcc presence, if all is ok probably U800 faulty.
Note : for "VOL_UP" , "VOL_DOWN" keys check also CR502 , while for "PWR_ON" key check R508 for missing or unsoldered issue ,else problem could be U900.

Supply pcb using "pcb test cable" cod AE20101903 , set pcb in test mode and digit test commands 432# = tone enabled on alert way) 1513# (continuos tone),4707# max volume . Check for "ALRT_VCC" = 3 Vcc presence on J510 alert pad and check for signal = 1,6 Vpp offset = 1,4 Vcc on J511 alert pad

YES →
Check alert for faulty , else be sure you have not any intermittent problem (check U900 for this),or check for dirty on J510 , J511 alert pads.

**NO
ALERT**

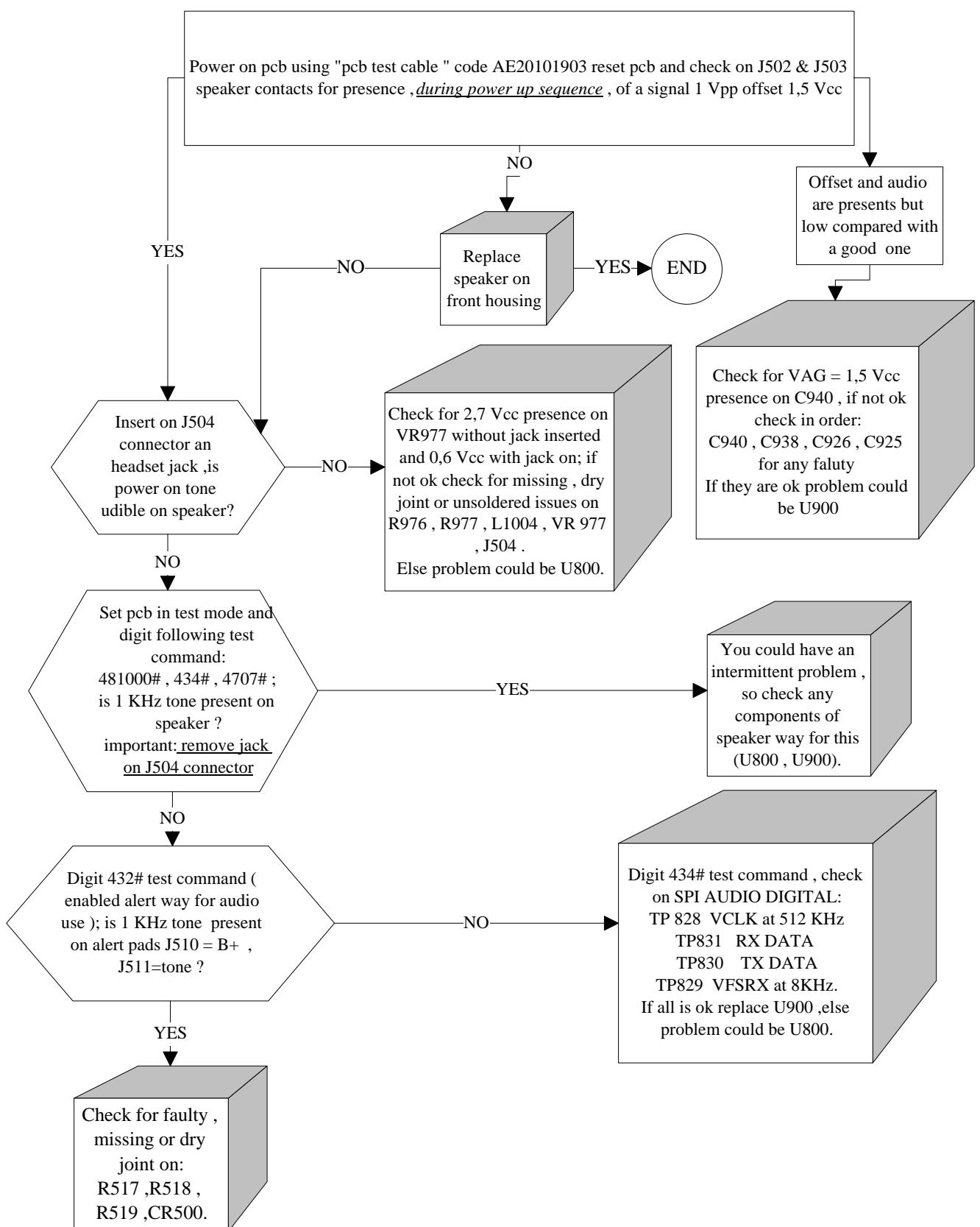
NO
Check in order:
ALRT_VCC presence = 3V on Q903 pin 1 , 2 , 5 , 6 , if not ok check on pin 4 for B+ presence . Note: because Q903 is positioned under test cable you are not able to check for ALRT_VCC presence on it,so you can check this on backlight leds anode.
Check CR510 , C1723 , C1722 , C933 for missing , dry joint or faulty.
Finally, only if you have not any issue on audio speaker, problem could be U900.



note: all the signal & voltage present in this procedure has to be clear and at correct level ; compare them with a good pcb

NOTE: check if any components mentioned is correctly positioned , has not dry joint and is not damaged . If all is ok replace it . If problem is still the same send BOARD IN htc.

**NO AUDIO
on
SPEAKER**





note: all the signal & voltage present in this procedure has to be clear and at correct level ; compare them with a good pcb

NOTE: check if any components mentioned is correctly positioned , has not dry joint and is not damaged . If all is ok replace it . If problem is still the same send BOARD IN htc.

NO AUDIO TX on microphone/headset

Supply pcb using "pcb test cable " code AE20101903 ,set pcb in test mode, digit test command:

434# audio on speaker

36# loop back on

4707# max volume

Check which way doesn't work correctly.

Note: if each way doesn't work check on U900 for PRESENCE OF " SPI AUDIO BUS " :

Tp 828 CK 512 KHz , Tp 831 data

Tp 830 data , Tp 829 8 KHz ck.

If they are not presents check on Tp 823 or C825 for 13 MHz ck , if not ok problem could be **U800**, else **U900**.

**INTERNAL
MIKE DOESN'T
WORK.**

**HEADSET
MIKE DOESN'T
WORK.**

Check for "Mic bias" = 1,4 Vcc presence on C923 , if not ok check for dry joint , missing or unsoldered issues on R927 , R926 , C934 , C927 ; if ok check for same issues on C923 , R925 , L927.

Finally problem could be U900.

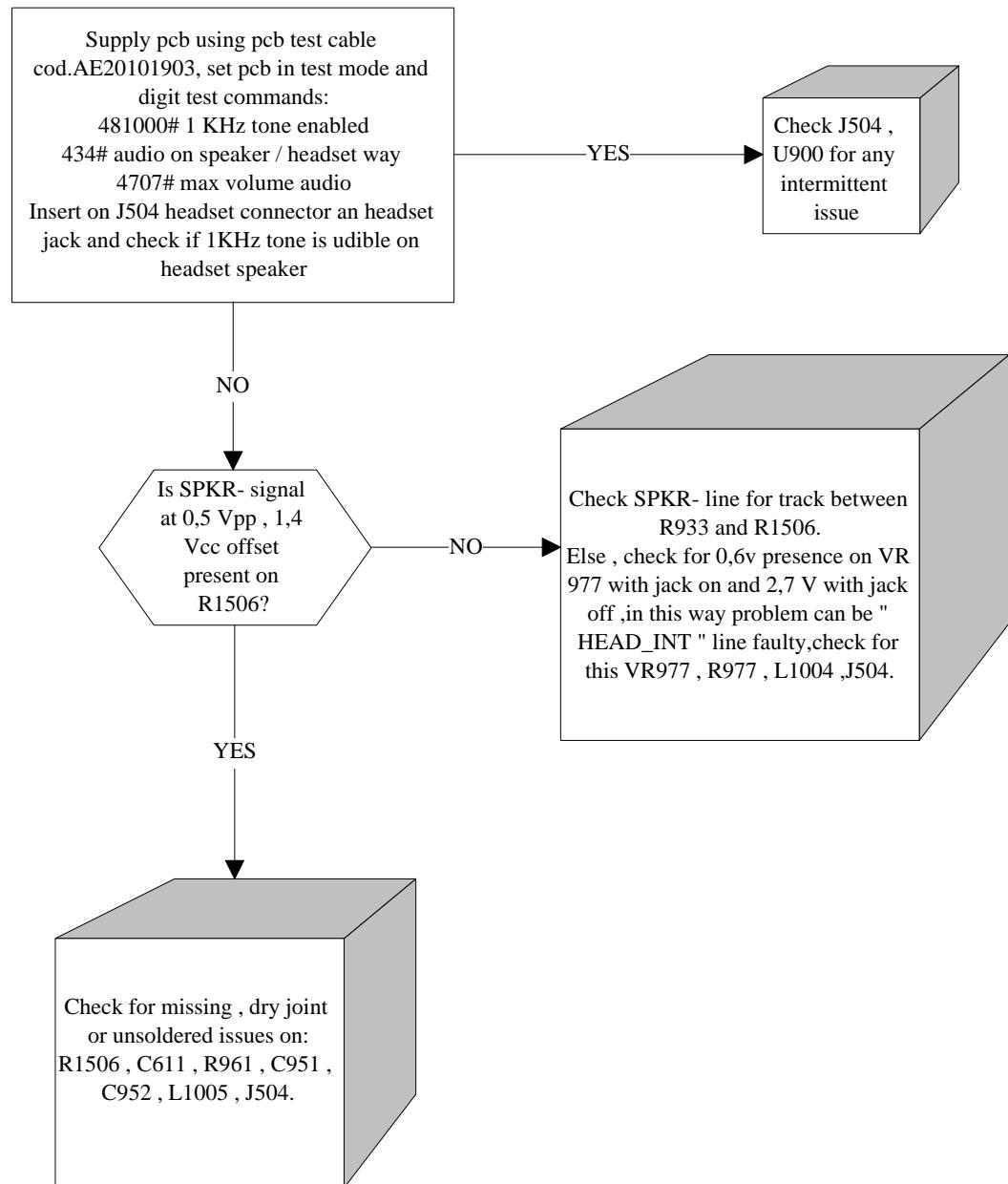
Check in order:
J504 "headset jack" for faulty or unsoldered pins.
_0,6 V presence on R977 with jack on and 2,7 Vcc with itself off , if not correct check for V2 =2,7 Vcc presence on R976 , else check R976 , R977 , L1004 , VR 977 for missing , dry joint or unsoldered issues.
_L500 , C1520 , C510 , C931 , R930 , C927 , R928 , L928 for same issues.
_Mic_bias = 1 Vcc presence on C931, if not correct ,check R957 for missing ,dry joint or unsoldered issues.



note: all the signal & voltage present in this procedure has to be clear and at correct level ; compare them with a good pcb

NOTE: check if any components mentioned is correctly positioned , has not dry joint and is not damaged . If all is ok replace it . If problem is still the same send BOARD IN htc.

**NO AUDIO RX
on headset ,
speaker ok**

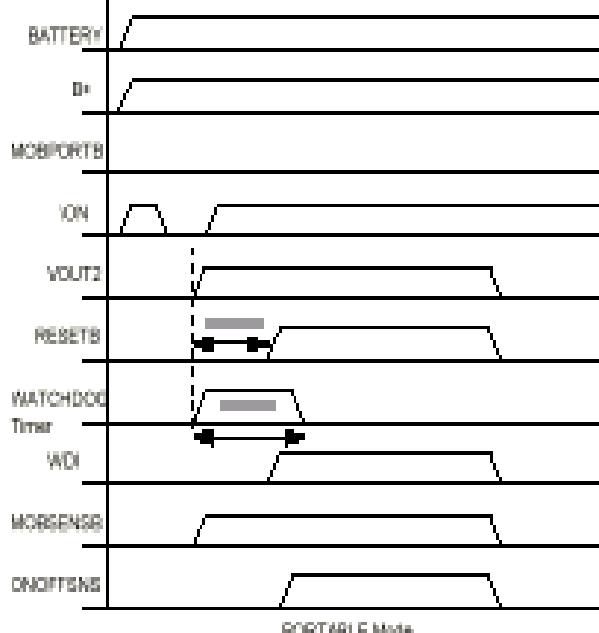




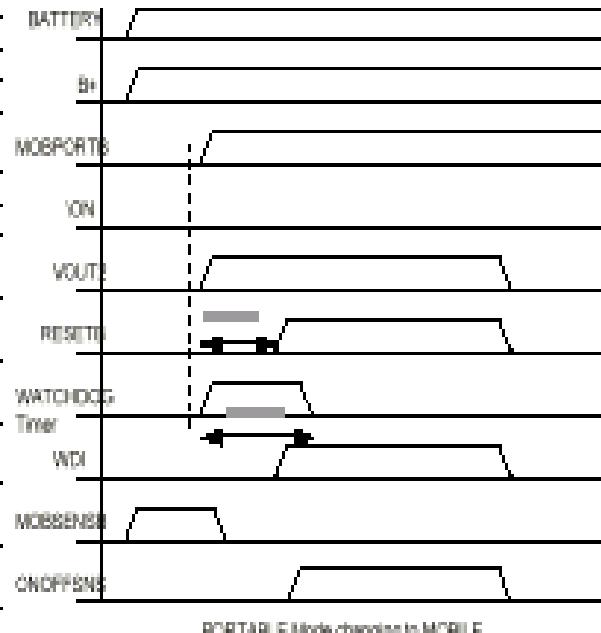
See timing sequence
below for no power
up issues on pag.03

NO POWER UP
TIMING
SEQUENCE

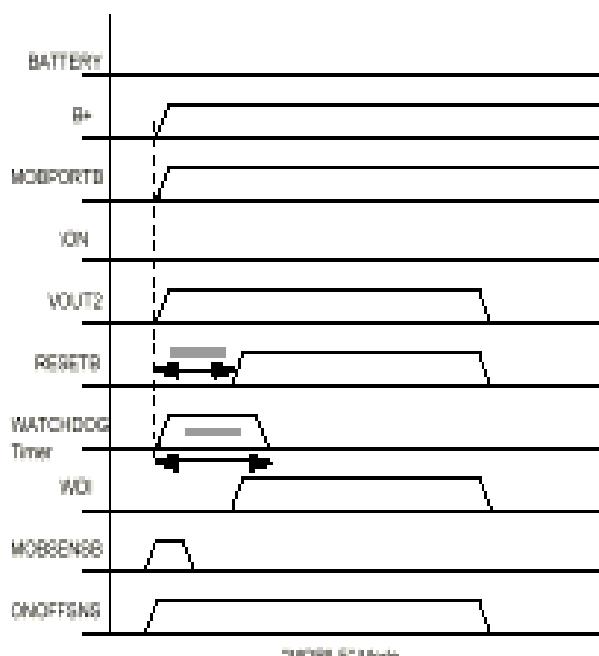
a) Radio turned on from ON/OFF



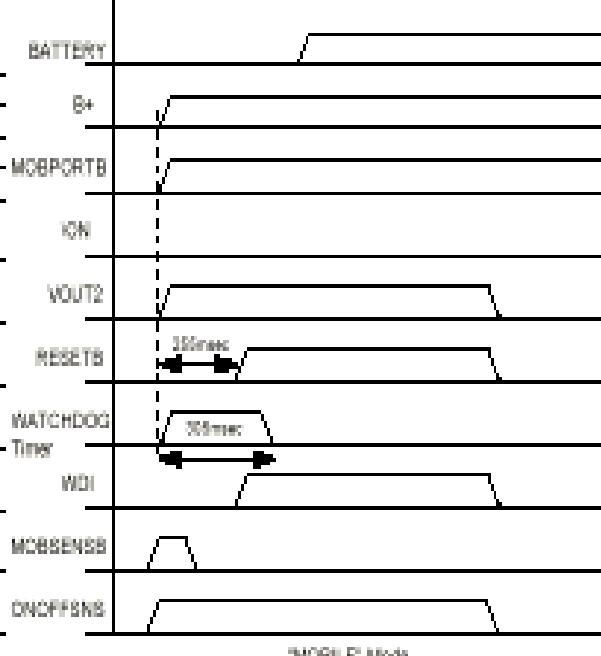
b) Radio on via transition to MOBILE



c) Radio on, no battery



d) Radio on, battery attached later



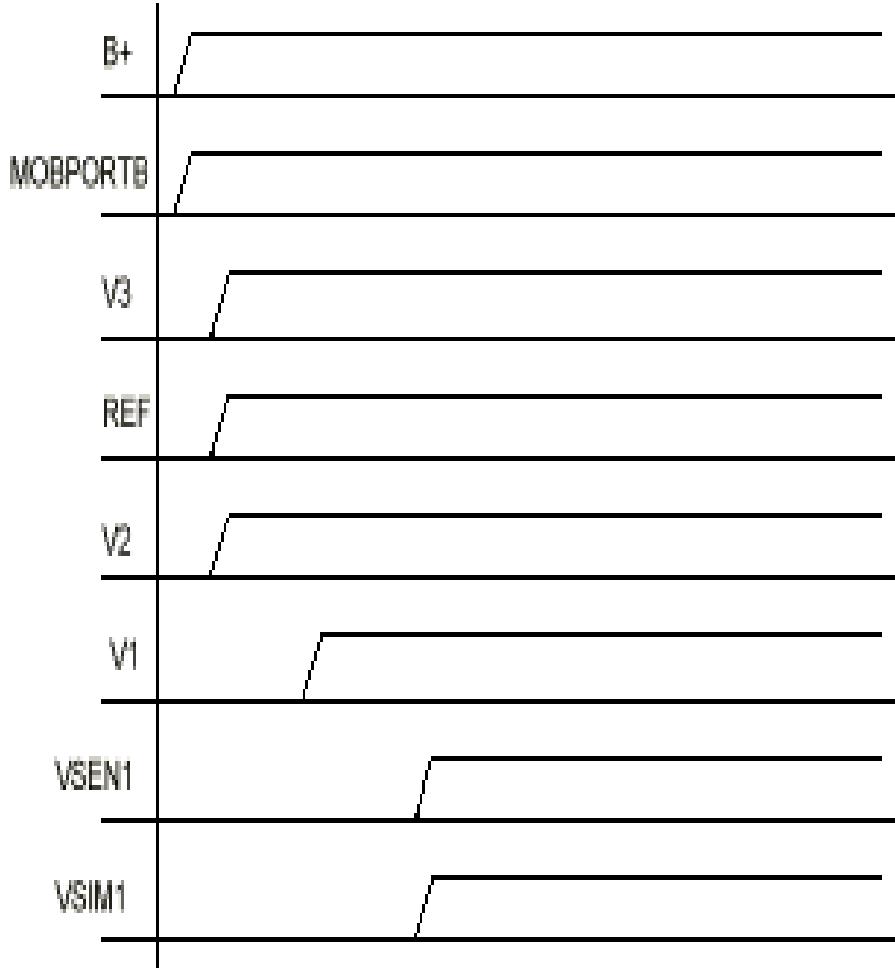


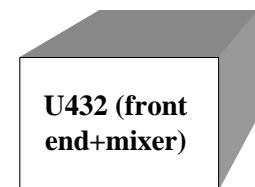
**See timing sequence
below for no power
up issues on pag.03**

**NO POWER UP
TIMING
SEQUENCE**

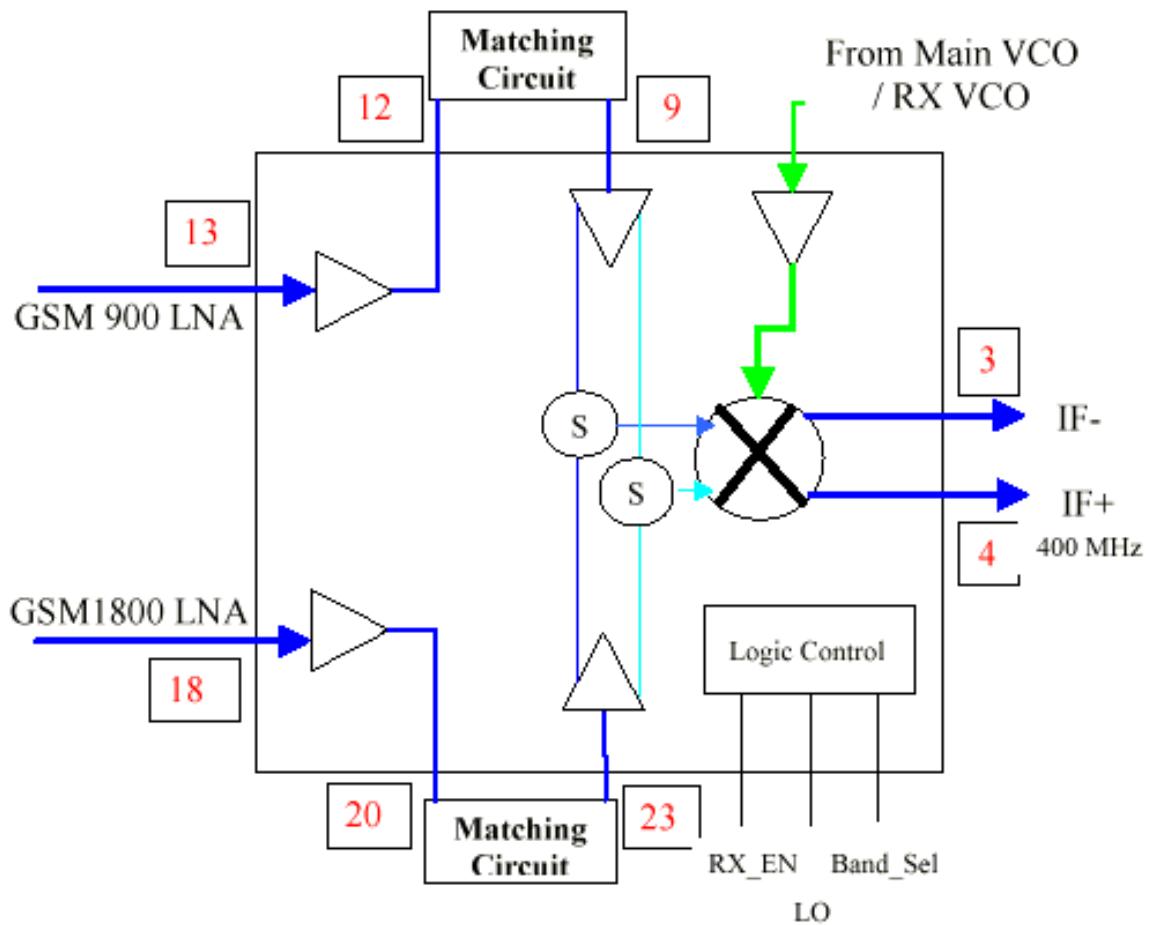
Regulator Power Up Sequence

No particular delay timing is established for any critical radio turn on sequence.



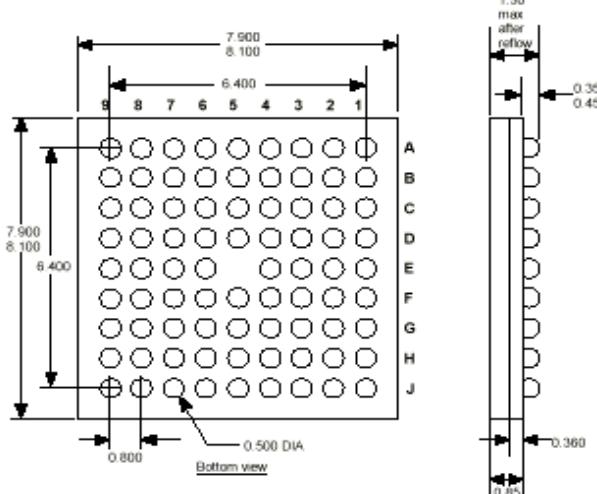
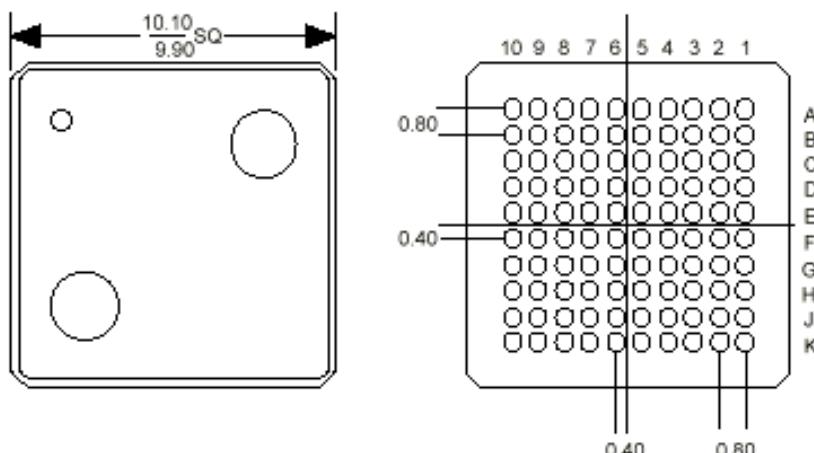


Front End IC
Internal Operation



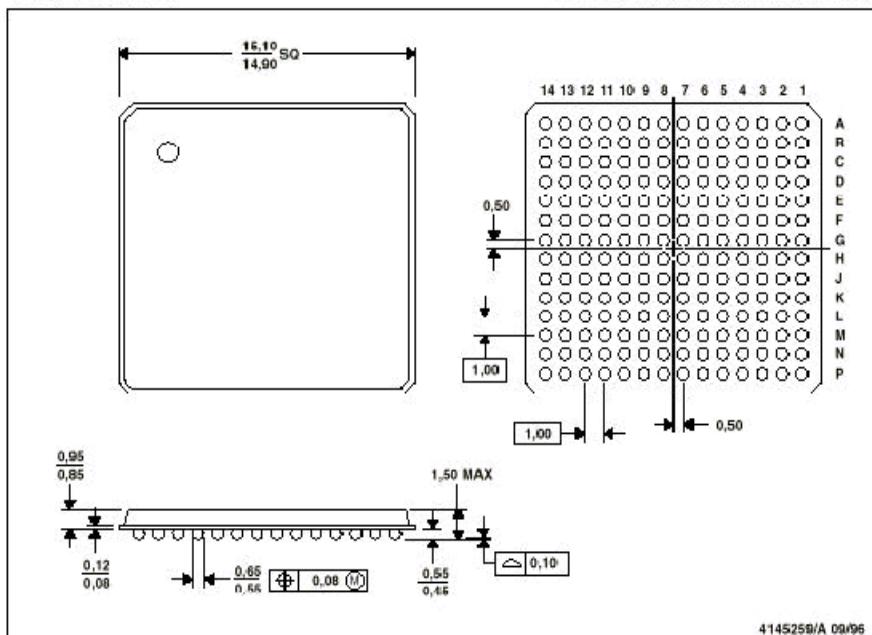
**MOTOROLA**

Dual band Modulus 3 level 3 debug rev 1.0

**MAGIC IC
U200
PACKAGE****GCAP 2 IC
U900
PACKAGE**

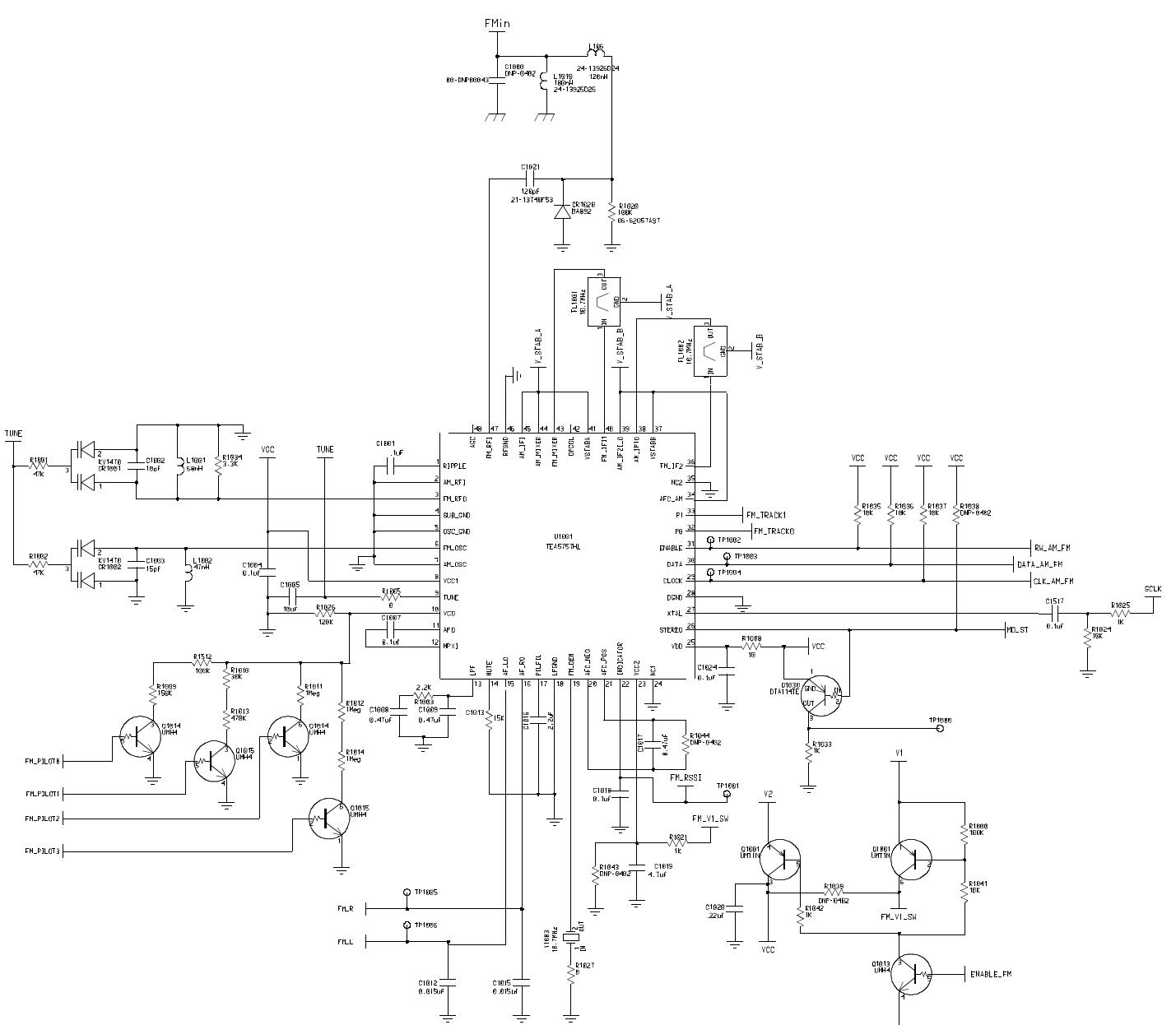
GHG (S-PBGA-N196)

PLASTIC BALL GRID ARRAY PACKAGE

**WHITECAP
IC U800
PACKAGE**

NOTES: A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. MicroStar™ BGA configuration

DB Modulus III (Shark R-Look) 8485933h06



GSM
Service Support
Level 3 Authorized

MODULUS_3_XCVR
84Dxxxxxx
SHEET 4 FM RADIO

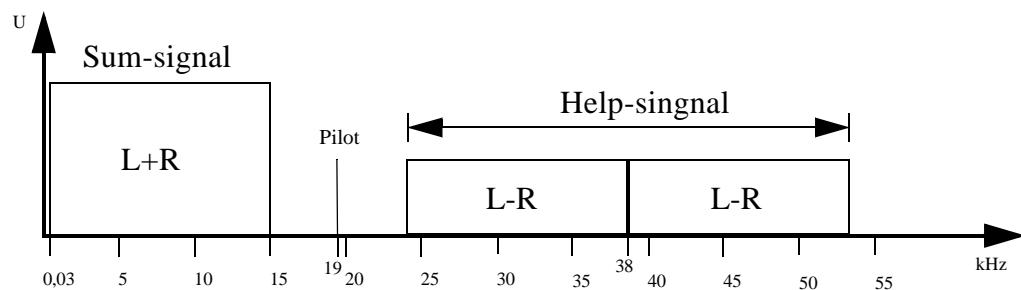
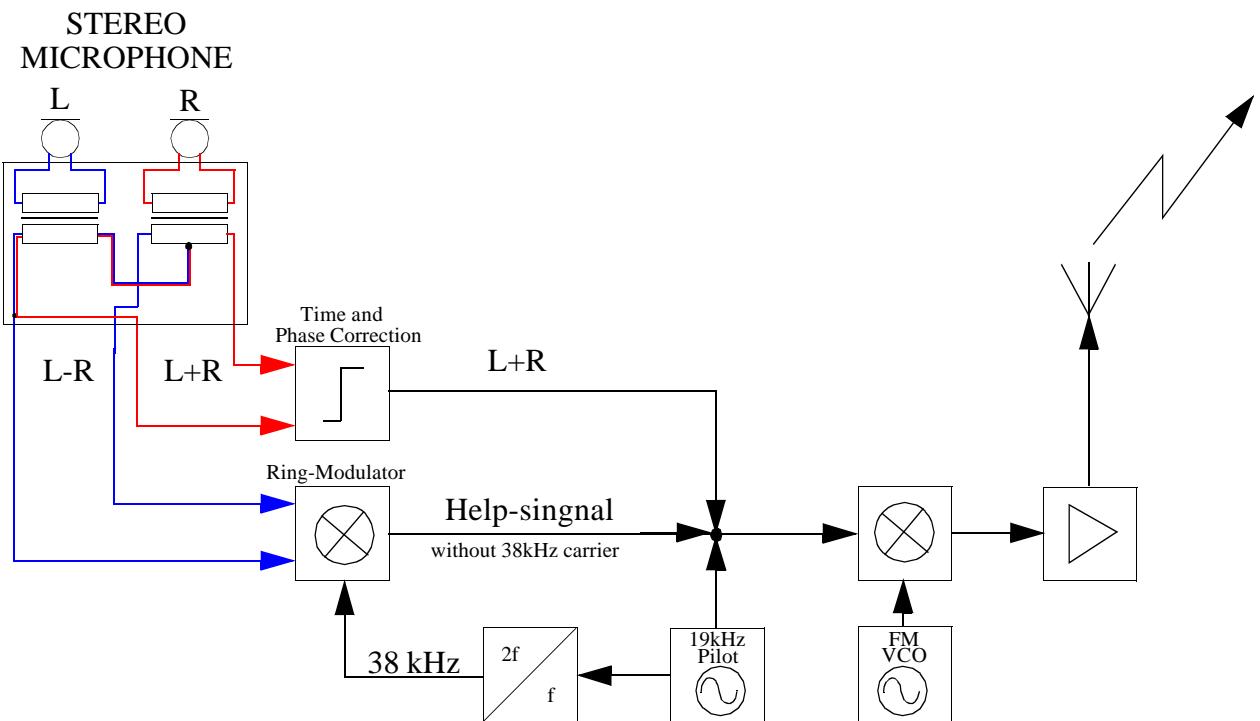
ISS.	COMMENTS	DATE
P1	CREATED FROM PHILIPS DEMO BOARD	10/08/98
P2	L1001: Changed value from 560k to 680k L1002: Changed value from 550k to 680k C1003: Changed value from 10pF to 6pF C1003: Changed value from 10pF to 6pF R1012: 10k to 1kN C1013: 4.7uF to 1uF C1005: 330pF -> 1uF C1012: C1015: 0.01 -> 0.012uF C1019: 0.01uF -> 0.022uF C2491: 220uF -> 1uF R1001: 1k to 47k R1002: 1k to 5.6k Added R1018,R1025,C1025,C1022,C1026, R1026: C1095 to 1uF (was 47uF) Changed C1083 to 12pF (was 10pF) Changed C2481 to C1024 Changed C1024 to 1uF (was 22uF) Changed C1024 to 15uH (was 55uH) Changed C1023 to 15uH (was 55uH) Changed C1011,R1010 to DNP (was 100k) Changed C1012 to DNP (was 100k) Changed C1013 to DNP (was 100k)	12/11/98
P3	Added R1018,R1025,C1025,C1022,C1026, R1026: C1095 to 1uF (was 47uF) Changed C1083 to 12pF (was 10pF) Changed C2481 to C1024 Changed C1024 to 1uF (was 22uF) Changed C1024 to 15uH (was 55uH) Changed C1023 to 15uH (was 55uH) Changed C1011,R1010 to DNP (was 100k) Changed C1012 to DNP (was 100k) Changed C1013 to DNP (was 100k)	02/23/99
P4	Replaced 44 pin IC with 48 pin LDFP Added C1010,C1014,C1011,C1013,C1025, R1004,R1005,R1006,R1007,R1022,R1023, R1024,R1025,U1002 Replaced varactors CR1001, CR1002 Deleted C1010,C1014,C1011,C1013,C1025, R1004,R1005,R1006,R1007,R1022,R1023, R1024,R1025,U1002 Updated transistor designators Added U1001, U1002 Changed C1005 to 2113528264 uF Changed C1005 to 2113528264 4.7uF Changed C1001 to 50k80 DNP	04/02/99
P5	Added U1001, U1002 to 47uH Deleted CR1001, CR1002, CR1003, CR1004 Added C1002 to 3 pin package Changed C1003 to 4.7uF Added M017	04/05/99
P6	Added U1001, U1002 to 47uH Deleted CR1001, CR1002, CR1003, CR1004 Added C1002 to 3 pin package Changed C1003 to 4.7uF Changed C1003 to 5.6uH (was 10uH)	05/16/99
P7	Added R1001 = DNP Changed L1003 from 0.55uH to DNP Changed L1003 from 0.55uH to 200pF Changed L1003 from 0.55uH to 300pF Deleted L1007	07/02/99
P8	Added R1005 (1) near C1005 Changed L1001 from 47 nH to DNP	07/28/99
P9	Added R1005 (1) near C1005 Changed L1001 from 47 nH to DNP	07/30/99
P10	Changed L1001 from 47 nH to DNP Changed L1002 from 16 pF to 5.8 pF Changed L1003 from 18 pF to 12 pF Removed C1006	07/31/99
P11	R1016 -> R1019 from DNP to 0 L1002 to 0805 DNP L1002 > 4.7uH C1002 > 4.7uH R1002 to 0803 DNP C102-C105 = 0.015uF Deleted R1007 Added R1039 Added R1035-R1038 Added R1040	08/20/99
P12	Deleted: L1002, L1003, C1002, C1030-03 Deleted: R1013, R1014, R1028, C1033	08/23/99
P13	Changed R1011 and R1012 to L1001 from DNP to 50uH L1002 from DNP to 47uH	08/14/99
P14	L1010 70 47uH/L1015 47uH L1010 70 3.3uH/L1015 50uH L1012 70 3.3uH/L1015 50uH L1013 70 3.3uH/L1015 50uH L1014 70 3.3uH/L1015 50uH L1015 70 3.3uH/L1015 50uH P11-L3 Added R1013 (47uH), R1014 (47uH), R1015 (47uH), R1016 (4.7uH) Changed R1012 from 12k to 14k R1012 from 12k to 14k R1012 from 826 to 368 R1012 from 826 to 368 R1012 from 3.3H to 1H Updated IP Geometry	08/18/99
P15	HP44-L2 Changed R1011, R1012, R1014 5% parts	11/29/99
P16	BB5_A-5 Changed C1005 to 2113528265 HEED R1044 DNP DIP	01/13/00
P17	FM Radio JCN info (insert later) R1048 back to C1013 C1008 DNP to C4002 C1008 DNP to C4002	1/18/00
H05	Deleted R1048 Added R1008 (100k) Changed C1001 from DNP to 8-kUF	2/1/00
H06	Changed C1001 from DNP to 8-kUF	2/1/00
	PCB	2/1/00

MOTOROLA PERSONAL COMMUNICATIONS SECTOR		
COPRIGHT 1999, MOTOROLA INC. MOTOROLA CONFIDENTIAL PROPRIETARY		
DESIGN NAME	\$MODULUS_3/84D85933h06_B_5	
DRAWN BY	Thomas Nagode	DATE October 8, 1998
MODIFIED BY	Peter McMahon	DATE February 1, 2000
APD BY	-	DATE -
DRAWING NO.		
ISSUE		SHEET NO. OF
TITLE	FM STEREO Radio	

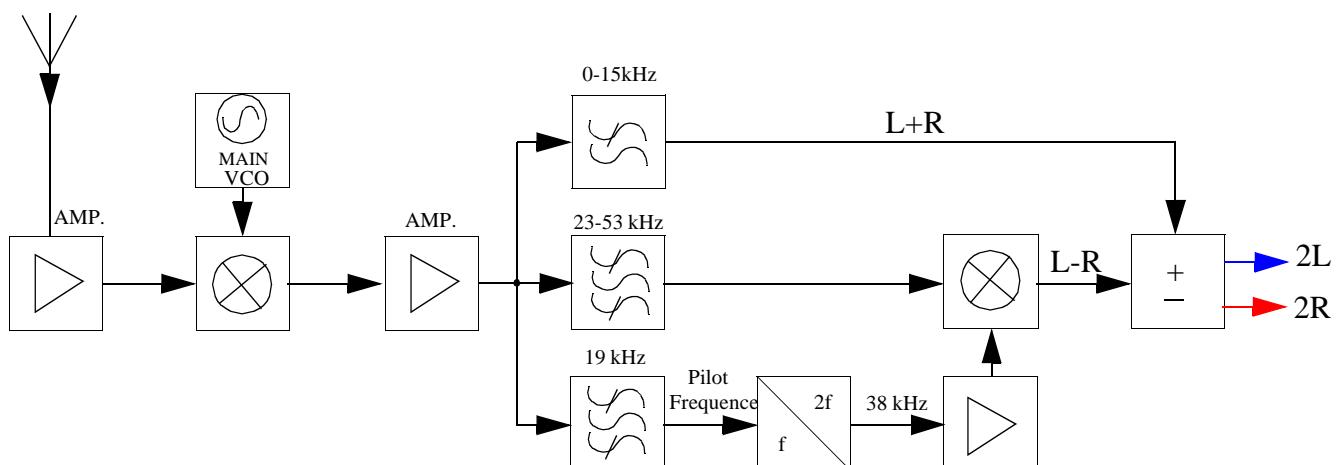
REVISIONS

GSM SERVICE SUPPORT GROUP	04.02.00
RF SCHEMATICS	Rev. 1.0
DualBand Modulus III (Shark R-Look)	8485933h06
Michael Hansen, Ralf Lorenzen, Ray Collins	Page 1

STEREO TRANSMITTER BLOCK DIAGRAM



STEREO RECEIVER BLOCK DIAGRAM



REVISIONS

GSM Service Support	03.11.99
BLOCK DIAGRAM	Rev. 1.0
FM TRANSMITTER / RECEIVER	
Michael Hansen, Ray Collins, Ralf Lorenzen	Page 1 of 1



MOTOROLA

Shark level 3 debug

issue 17/02/2000

SHARK Modulus 3

Dual band level 3 debug

Version: 1.0

Date: Feb , 02 , 2000

Total Pages: 19

Prepared by _Fabrizio
Alba_____

Approved by _____

**MOTOROLA****Shark level 3 debug**issue 17/02/2000

REVISION HISTORY

Version	Date	Name	Reason
1.0	23/12/1999	Fabrizio Alba	First release



**Supply phone by means No 3
standard 3AAAL NiMH batteries
code SNN5542 and check following
tests sequence**

**For any page see
electrical
diagram
equivalent**

**Modulus 3
test sequence**

**Does phone
power up
correctly ?**

NO

Go to " no
power up "
on pag. 03

**Does phone
draw a lot of
current ?**

YES

ON
FUTURE

**Does display
works
correctly?**

NO

Go to " no
display " on
pag.11

**Does
backlight
works
correctly?**

NO

Go to " no
backlight "on
pag.11

**Does keypad
works
correctly?**

NO

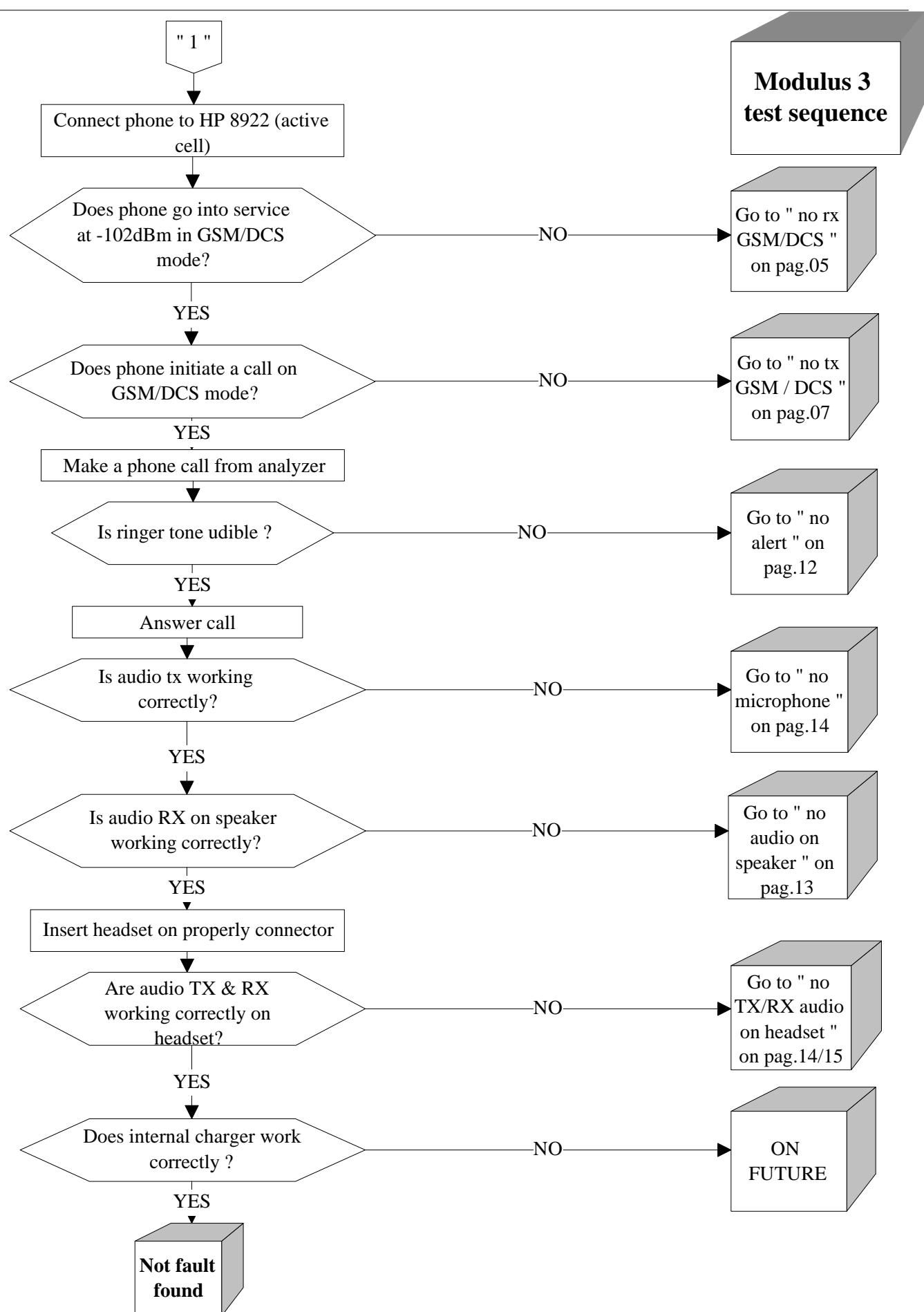
Go to " no
keypad " on
pag.12

**Does phone
shows "phone
failure see
supplier ?**

YES

ON FUTURE

**go to " 1 "
PAG 02**

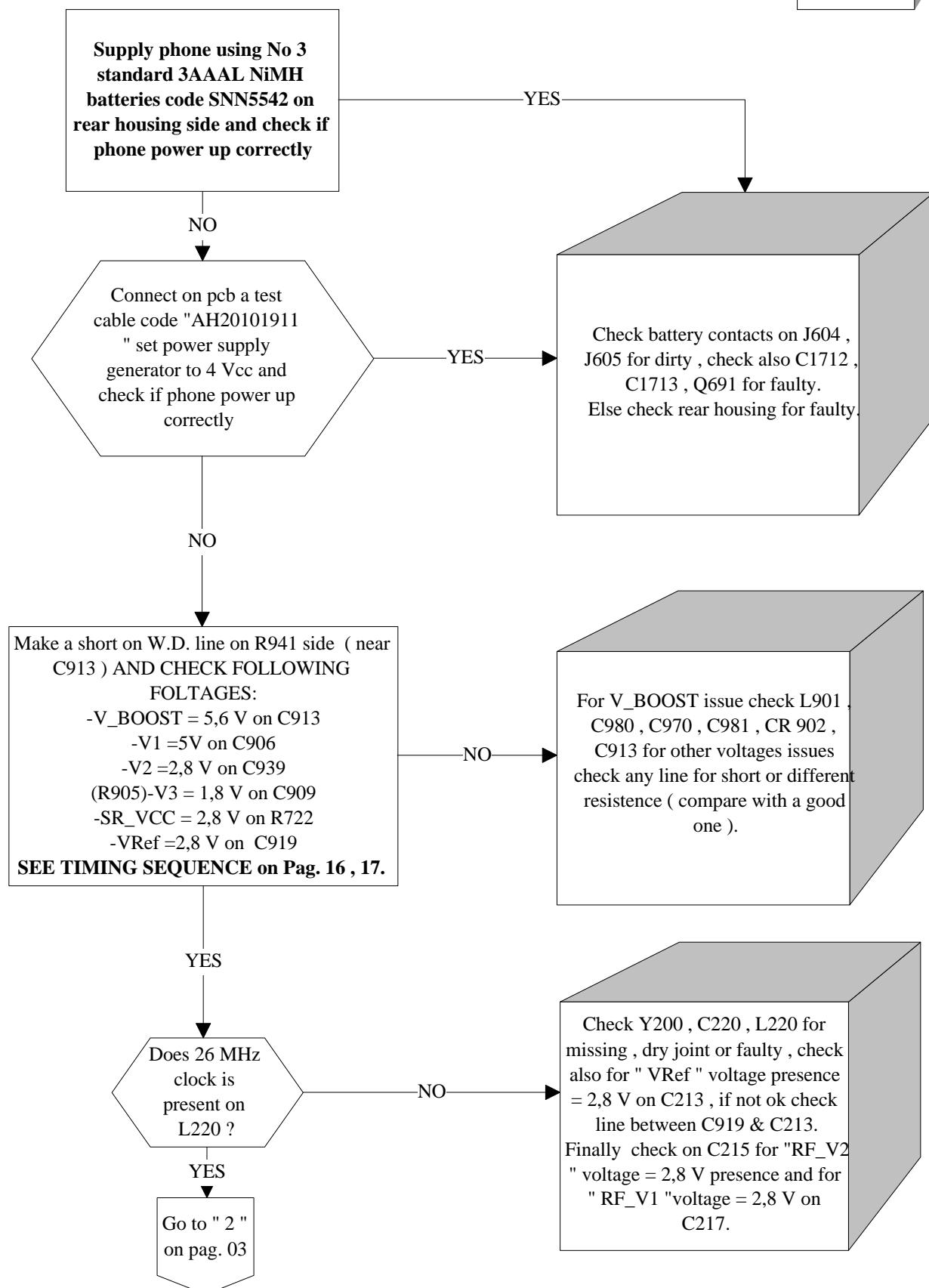


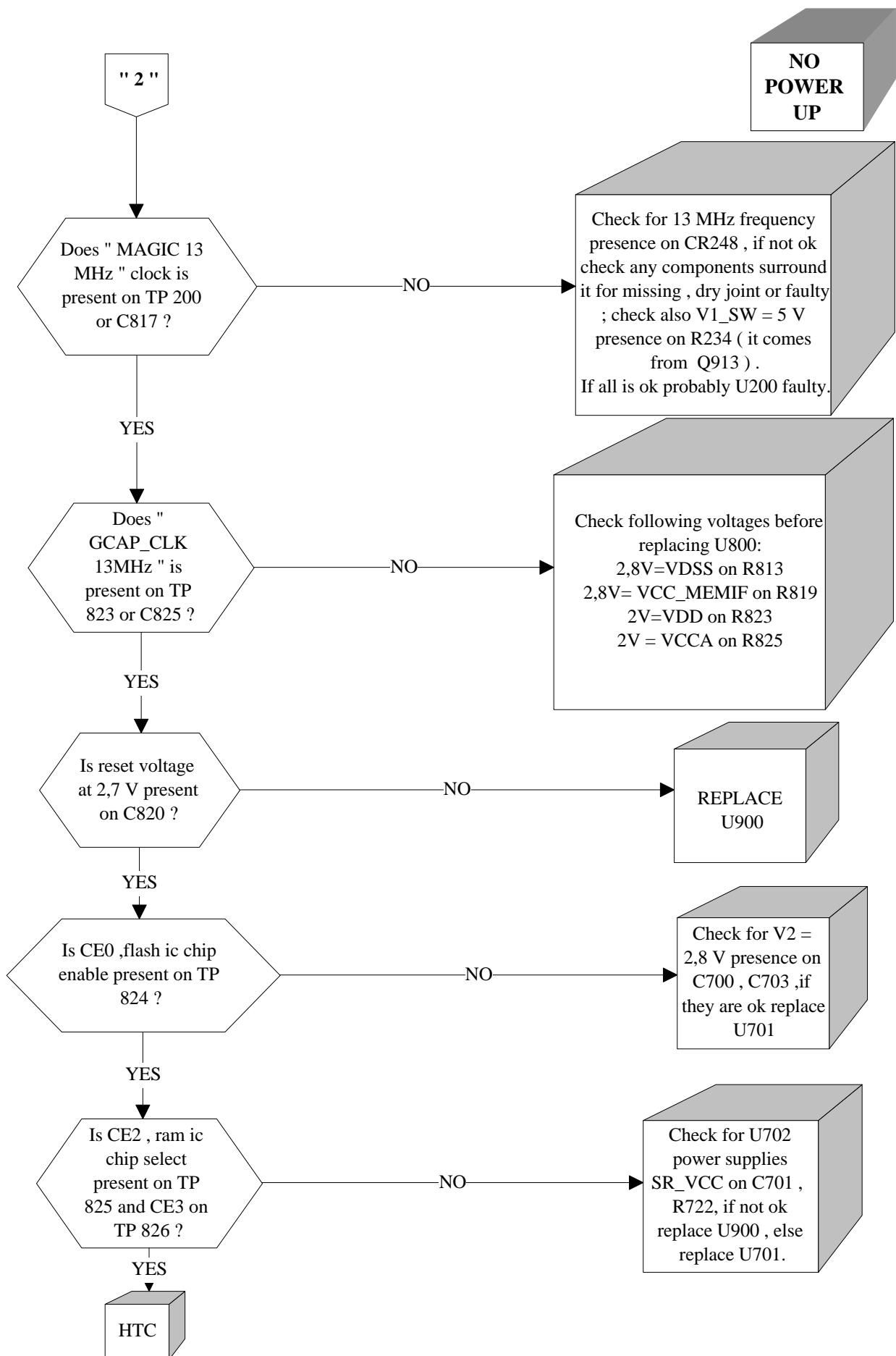


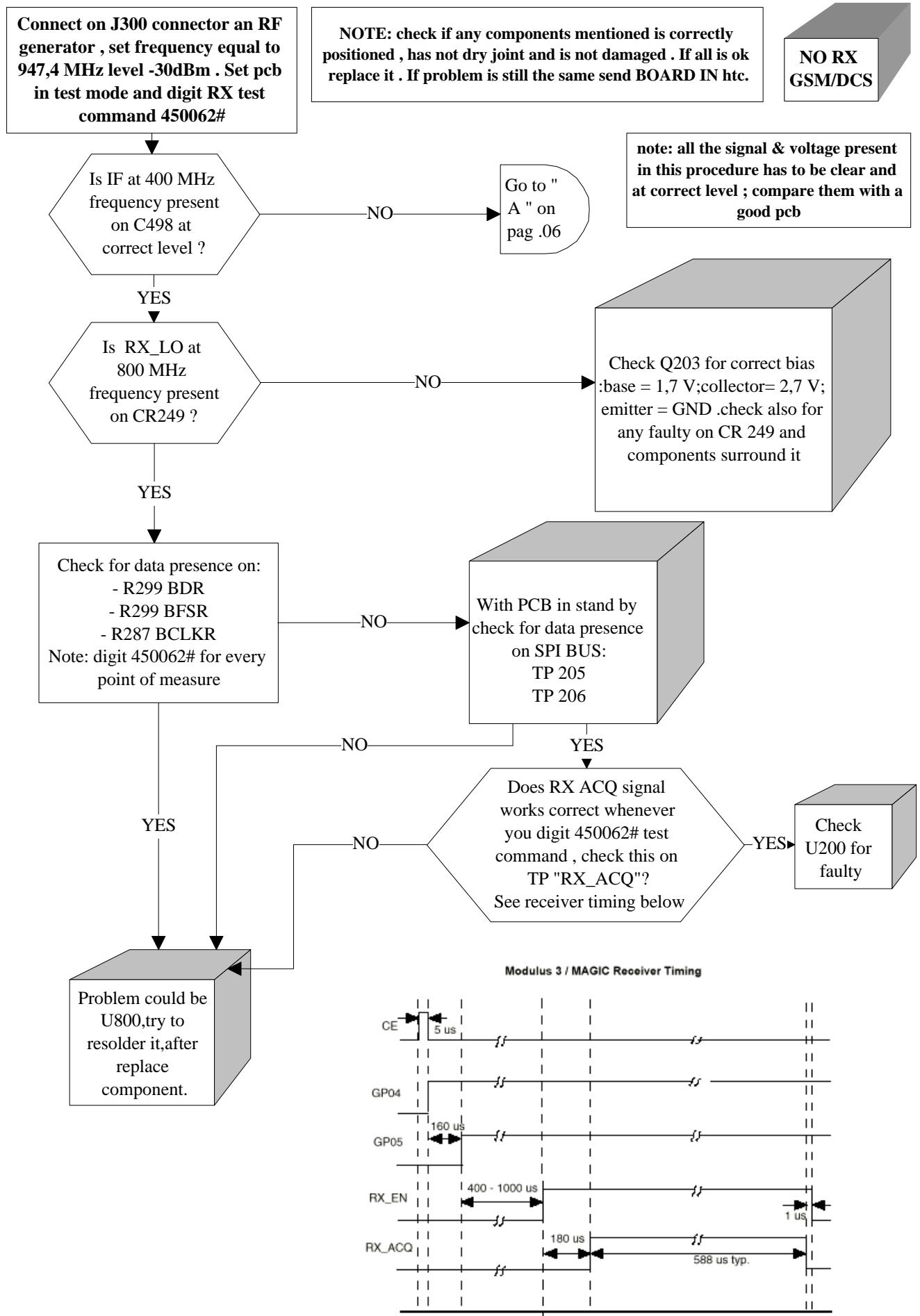
note: all the signal & voltage present in this procedure has to be clear and at correct level ; compare them with a good pcb

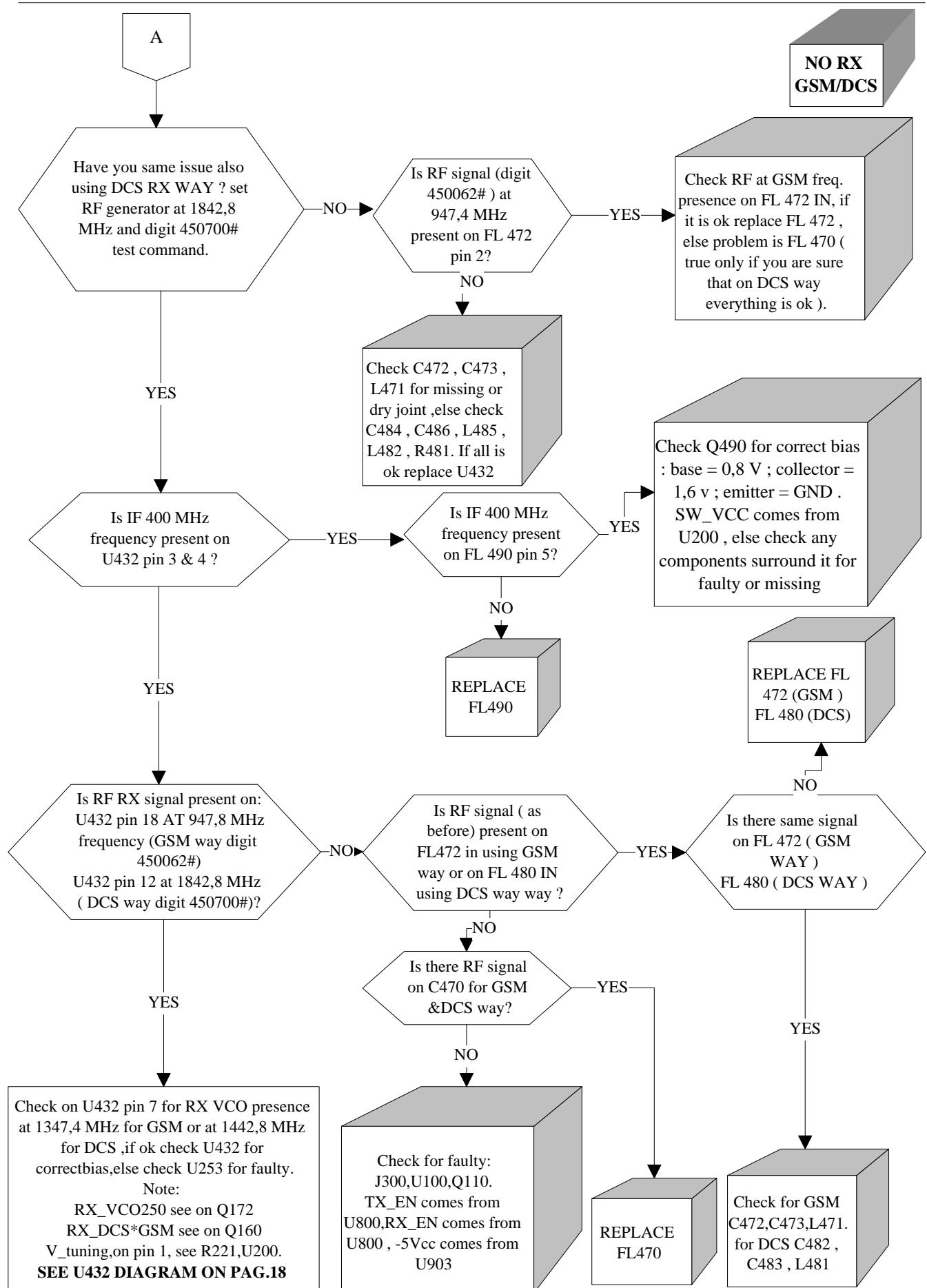
NOTE: check if any components mentioned is correctly positioned , has not dry joint and is not damaged . If all is ok replace it . If problem is still the same send BOARD IN htc.

NO
POWER
UP











note: all the signal & voltage present in this procedure has to be clear and at correct level ; compare them with a good pcb

NOTE: check if any components mentioned is correctly positioned , has not dry joint and is not damaged . If all is ok replace it . If problem is still the same send BOARD IN htc.

NO TX
GSM/DCS

NOTE 1 : You can use this procedure for GSM way & DCS way.

Whenever you have a signal with a symbol star (*) means that it is active low if you select this kind of way , while the same point of measure will be high for other way.

Differences between GSM & DCS way are:

TX_GSM*DCS

used for adjust all RF TX way for GSM/DCS choice
for any problem check on Q160

DCS_SEL comes out from U200 (or pin 2 U110)

GSM_SEL comes out from U110 pin 4

-10 V comes out from U904.

DCS_TX_VCO , GSM_TX_VCO

for any problem check Q130

Connect on J300 connector an RF spectrum analyzer , set PCB in test mode and digit following test command:

110062# 1215# 40# for a test in **GSM** way.

110700# 1215# 40# for a test in **DCS** way.

Check for RF signal presence at frequency =
902.4 MHz for GSM or 1747.8 MHz for DCS.

RF IS PRESENT , NEVER MIND LEVEL BUT IS DIRTY

RF IS NOT PRESENT

RF IS PRESENT BUT IS LOW

Is RF TX signal at GSM/DCS frequency present on U301 pin 4 ?

YES

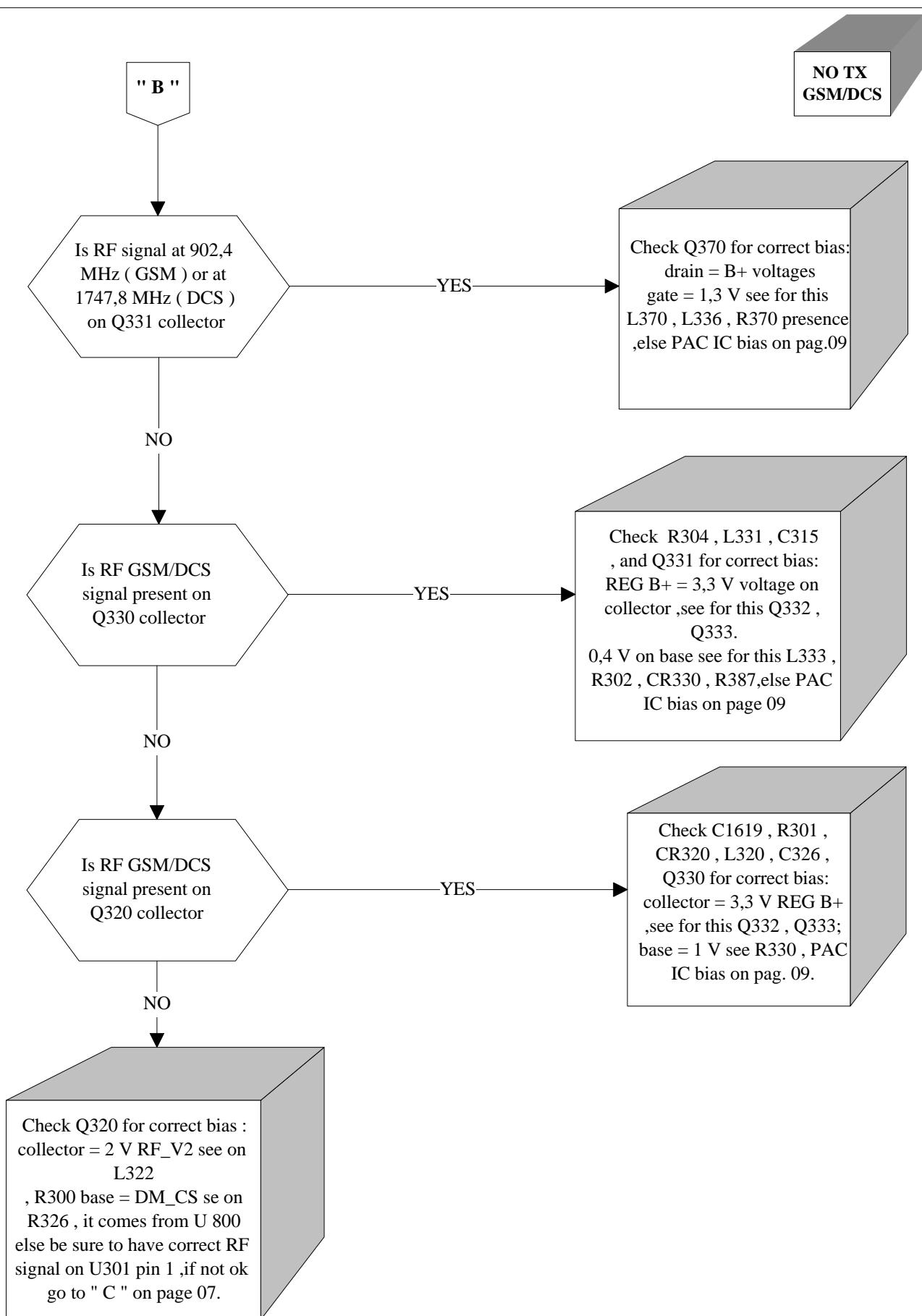
Is RF TX GSM/DCS present on Q370 DRAIN?

NO

Go to "B" on pag.08

Check on U301:
pin 3 DCS_TX_VCO see on Q130 , Q140.
pin 8 GSM_TX_VCO see on Q130 , Q140.
pin 10 SF_OUT see on C246 (comes from U200 9).
pin6 CP TX check for this Q310 , Q311 , U310 , U200 , R305 , R306 , R307 .
DM_CS , TX_EN , they comes from U800
VI_SW comes from Q913

Check:
L365 , L325 , L326 , C397 for missing or dry joint , else check for faulty Q110 , U100 .
-5V cc see U903
TX_EN , RX_EN comes from U800

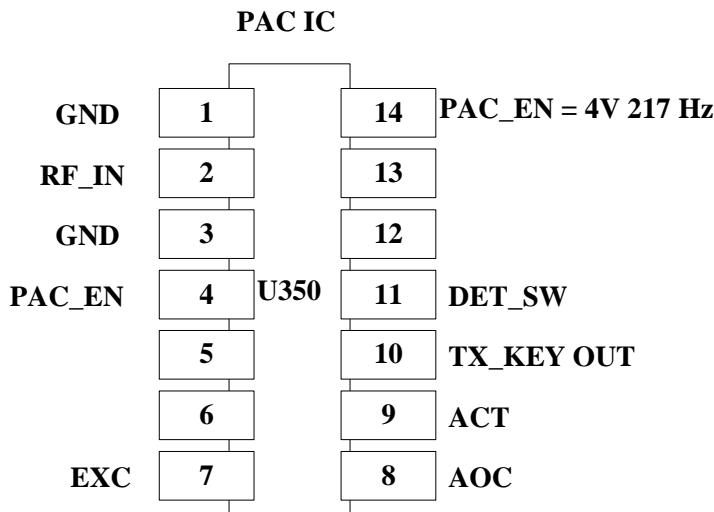




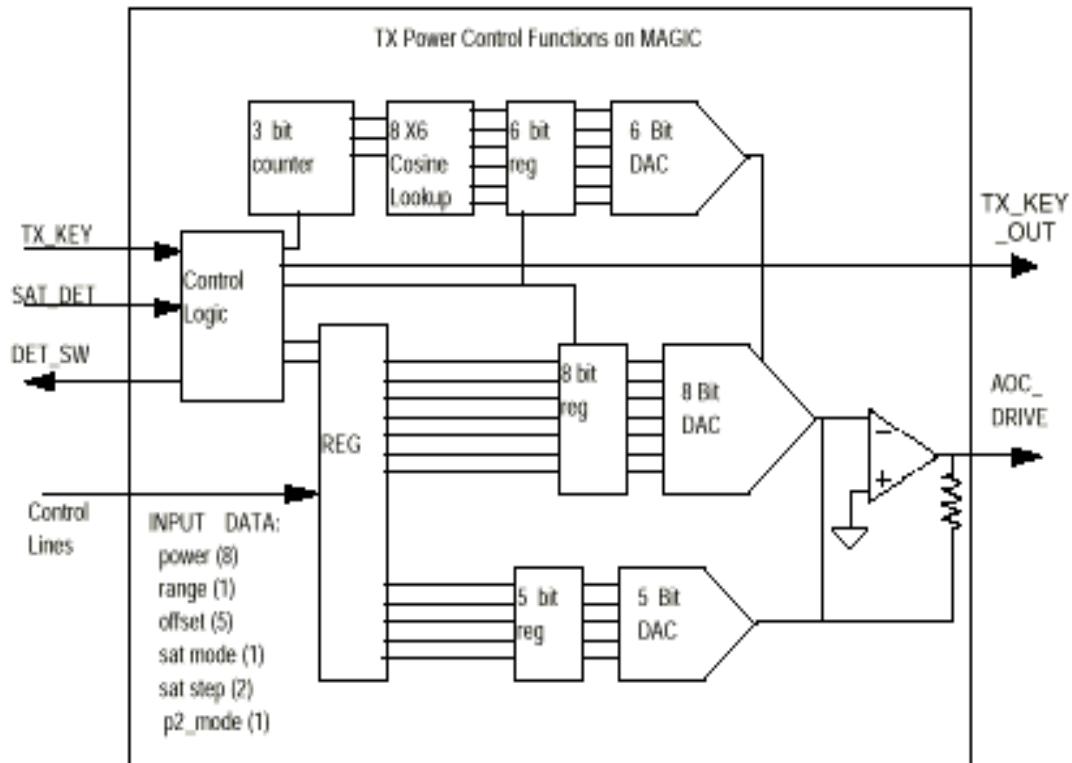
note: all the signal & voltage present in this procedure has to be clear and at correct level ; compare them with a good pcb

NOTE: check if any components mentioned is correctly positioned , has not dry joint and is not damaged . If all is ok replace it . If problem is still the same send BOARD IN htc.

NO TX
GSM/DCS



pin 4,14 PAC_EN comes from Q150 via Q350
(TX_EN comes from U800)
pin 8 , 9 , 10, 11 comes from U200 if not ok
check : SPI BUS on TP 205 & TP 206 for data
presence with pcb in stand by.
TX KEY see on TP 209
DM_CS see on TP 208.
**NOTE: REFER DIAGRAMS BELOW &
on pag. 10 FOR TIMING TX.**

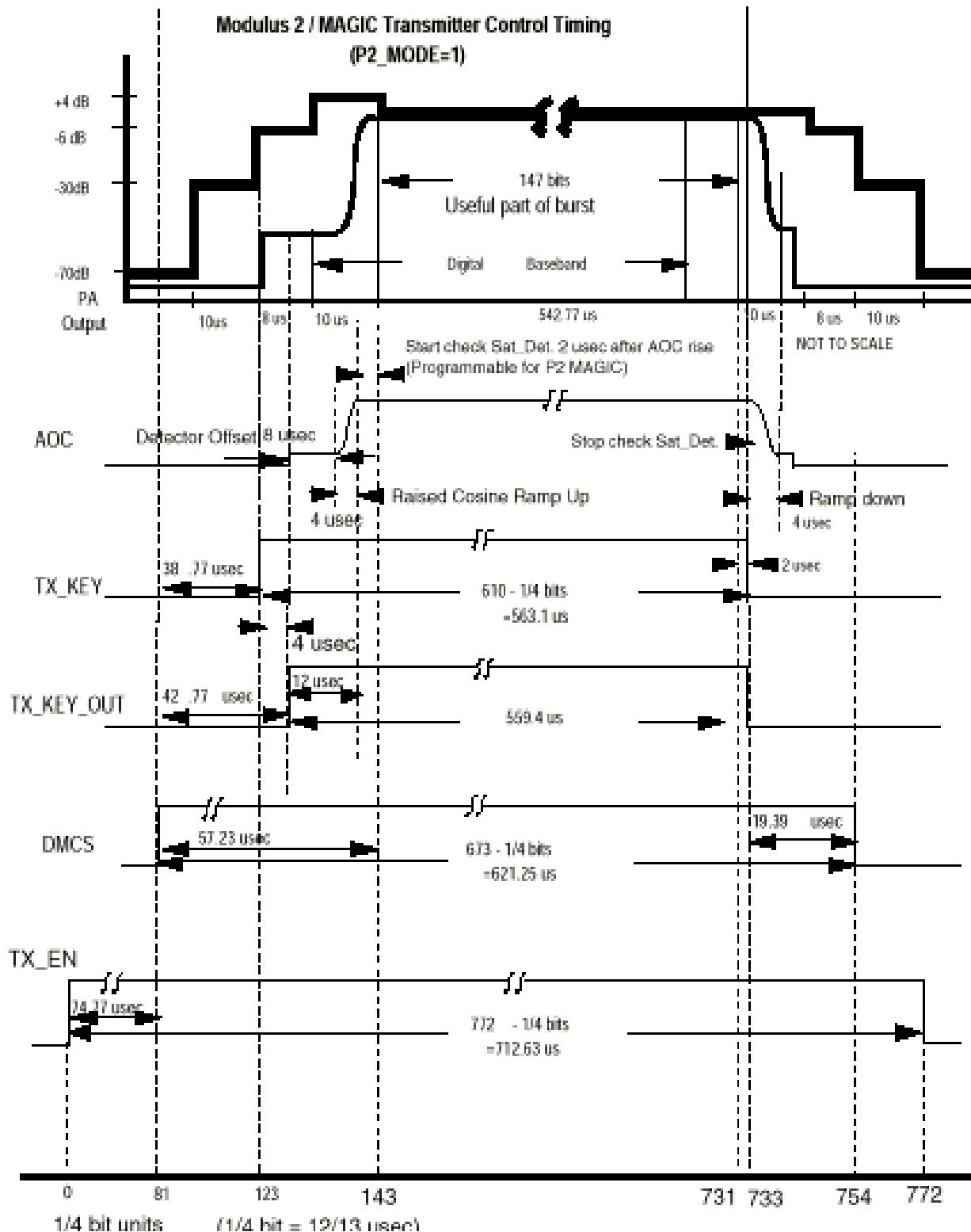


TX POWER CONTROL ON U200 IC



note: all the signal & voltage present in this procedure has to be clear and at correct level ; compare them with a good pcb

NOTE: check if any components mentioned is correctly positioned , has not dry joint and is not damaged . If all is ok replace it . If problem is still the same send BOARD IN htc.



MODULUS 2 TX TIMING on U200



note: all the signal & voltage present in this procedure has to be clear and at correct level ; compare them with a good pcb

NOTE: check if any components mentioned is correctly positioned , has not dry joint and is not damaged . If all is ok replace it . If problem is still the same send BOARD IN htc.

CHECK CARD

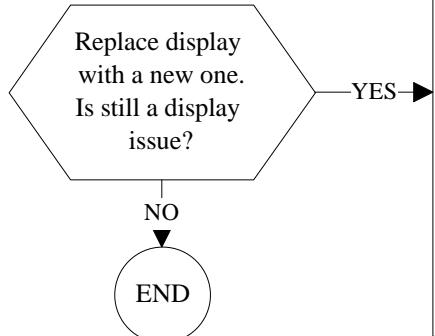
Supply PCB using pcb test cable code **AE20101903**.
Set pcb in test mode and digit 38# sim test enable
and check on J803 sim connector :
1 = GND
2 = SIM VCC 5V SEE u900 (C906)
3 = NC
4 = RESET see CR905 , R940
5 = SIM I/O see R945 , U901 , R938.
6 = CLK see R940

YES

Probably U800 faulty

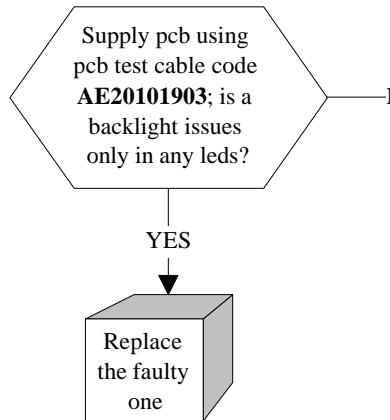
NO

Check, in order ,
U900 , U800 for
faulty



Check on J902 display connector for presence of:
1 =data DP_EN it comes from U800
2= 2,7 V RESET it comes from U900
3= data A0 see R716 for missing
4= data R_W it comes from U800
from 5 to 12 = data see on C1714 to C1720
13 = 2,7 Vcc V2 it comes from C939
14 = GND
15 = -5 Vcc it comes from U903.
If all is ok probably U800 faulty.

NO DISPLAY



Check on Display led's anode for ALRT_VCC = 3 V presence , if not ok check Q903 and consequently U900 for faulty.
Check also on Q907 gate for BKLT_EN = 2,7 Vcc , in this way on led's chatode there must be 1 V , if not ok check for R520 presence ,else replace Q907

NO BACKLIGHT



note: all the signal & voltage present in this procedure has to be clear and at correct level ; compare them with a good pcb

NOTE: check if any components mentioned is correctly positioned , has not dry joint and is not damaged . If all is ok replace it . If problem is still the same send BOARD IN htc.

**NO
KEYPAD**

Remove keypad membrane and check if here is any issues (dirty , track , solder) on key contacts from S501 to S522.
Check also R500 , R501 , R502 for V2 = 2,8 Vcc presence, if all is ok probably U800 faulty.
Note : for "VOL_UP" , "VOL_DOWN" keys check also CR502 , while for "PWR_ON" key check R508 for missing or unsoldered issue ,else problem could be U900.

Supply pcb using "pcb test cable" cod AE20101903 , set pcb in test mode and digit test commands 432# = tone enabled on alert way) 1513# (continuos tone),4707# max volume . Check for "ALRT_VCC" = 3 Vcc presence on J510 alert pad and check for signal = 1,6 Vpp offset = 1,4 Vcc on J511 alert pad

YES →
Check alert for faulty , else be sure you have not any intermittent problem (check U900 for this),or check for dirty on J510 , J511 alert pads.

**NO
ALERT**

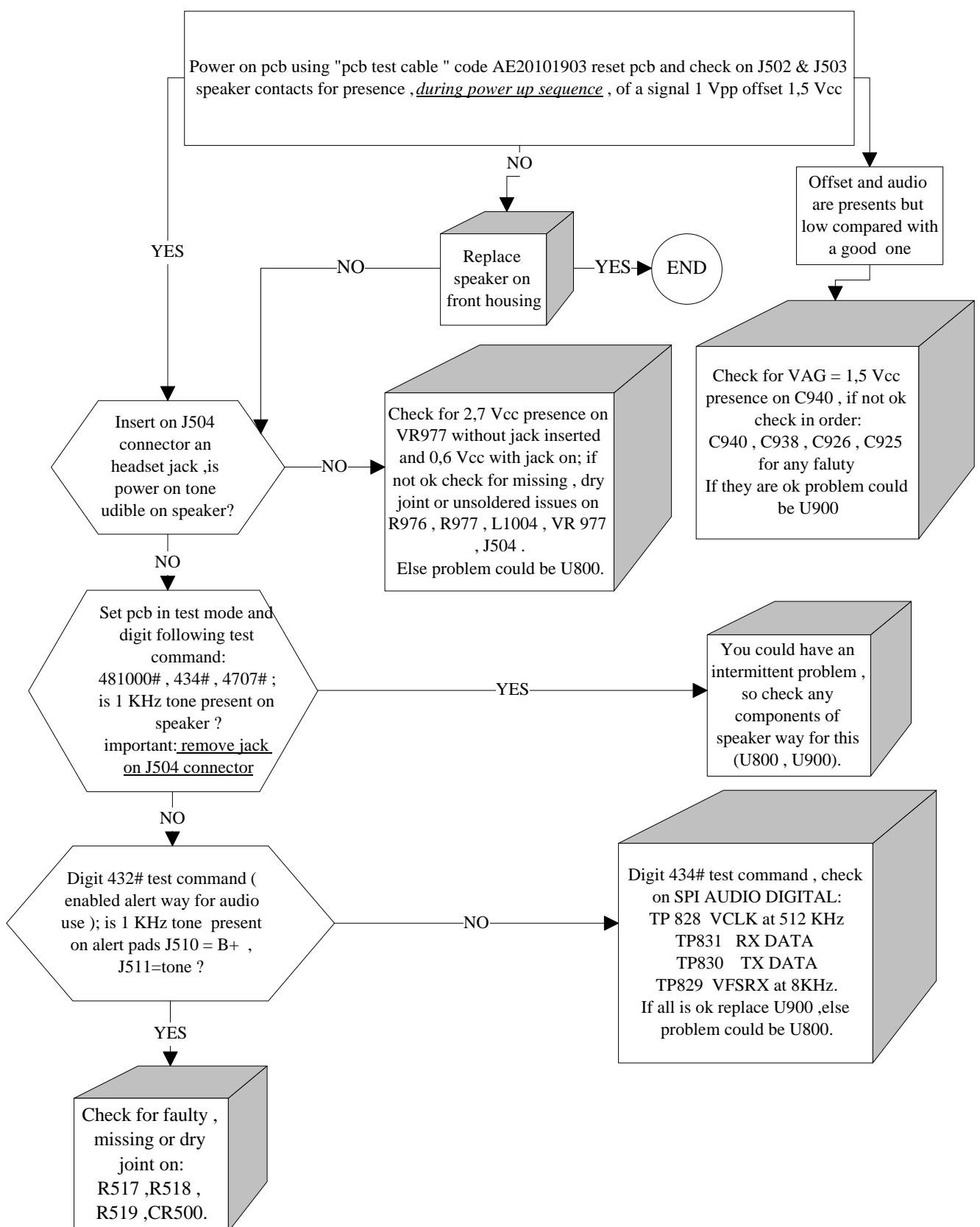
NO
Check in order:
ALRT_VCC presence = 3V on Q903 pin 1 , 2 , 5 , 6 , if not ok check on pin 4 for B+ presence . Note: because Q903 is positioned under test cable you are not able to check for ALRT_VCC presence on it,so you can check this on backlight leds anode.
Check CR510 , C1723 , C1722 , C933 for missing , dry joint or faulty.
Finally, only if you have not any issue on audio speaker, problem could be U900.



note: all the signal & voltage present in this procedure has to be clear and at correct level ; compare them with a good pcb

NOTE: check if any components mentioned is correctly positioned , has not dry joint and is not damaged . If all is ok replace it . If problem is still the same send BOARD IN htc.

**NO AUDIO
on
SPEAKER**





note: all the signal & voltage present in this procedure has to be clear and at correct level ; compare them with a good pcb

NOTE: check if any components mentioned is correctly positioned , has not dry joint and is not damaged . If all is ok replace it . If problem is still the same send BOARD IN htc.

NO AUDIO TX on microphone/headset

Supply pcb using "pcb test cable " code AE20101903 ,set pcb in test mode, digit test command:

434# audio on speaker

36# loop back on

4707# max volume

Check which way doesn't work correctly.

Note: if each way doesn't work check on U900 for PRESENCE OF " SPI AUDIO BUS " :

Tp 828 CK 512 KHz , Tp 831 data

Tp 830 data , Tp 829 8 KHz ck.

If they are not presents check on Tp 823 or C825 for 13 MHz ck , if not ok problem could be **U800**, else **U900**.

**INTERNAL
MIKE DOESN'T
WORK.**

**HEADSET
MIKE DOESN'T
WORK.**

Check for "Mic bias" = 1,4 Vcc presence on C923 , if not ok check for dry joint , missing or unsoldered issues on R927 , R926 , C934 , C927 ; if ok check for same issues on C923 , R925 , L927.

Finally problem could be U900.

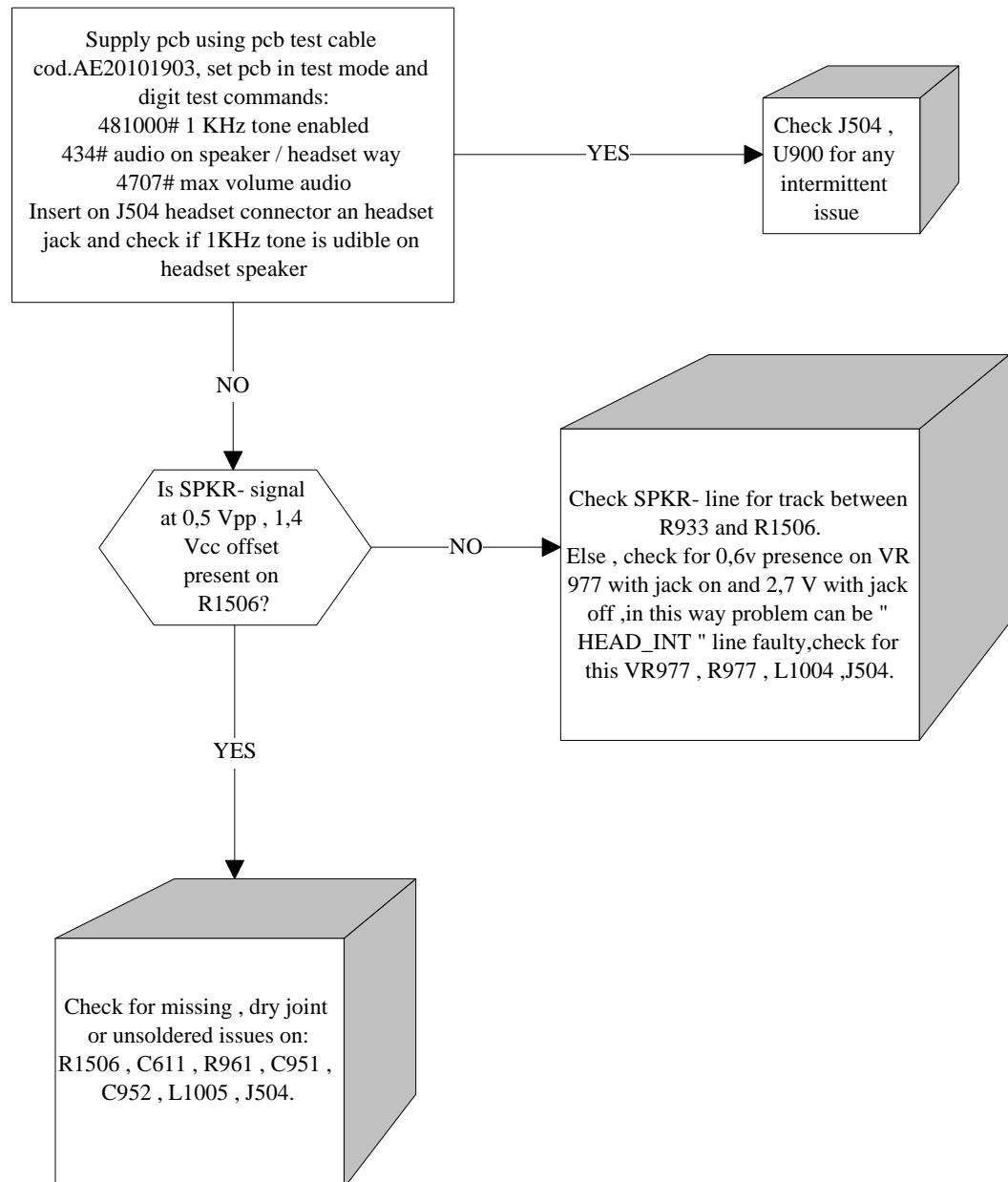
Check in order:
J504 "headset jack" for faulty or unsoldered pins.
_0,6 V presence on R977 with jack on and 2,7 Vcc with itself off , if not correct check for V2 =2,7 Vcc presence on R976 , else check R976 , R977 , L1004 , VR 977 for missing , dry joint or unsoldered issues.
_L500 , C1520 , C510 , C931 , R930 , C927 , R928 , L928 for same issues.
_Mic_bias = 1 Vcc presence on C931, if not correct ,check R957 for missing ,dry joint or unsoldered issues.



note: all the signal & voltage present in this procedure has to be clear and at correct level ; compare them with a good pcb

NOTE: check if any components mentioned is correctly positioned , has not dry joint and is not damaged . If all is ok replace it . If problem is still the same send BOARD IN htc.

**NO AUDIO RX
on headset ,
speaker ok**

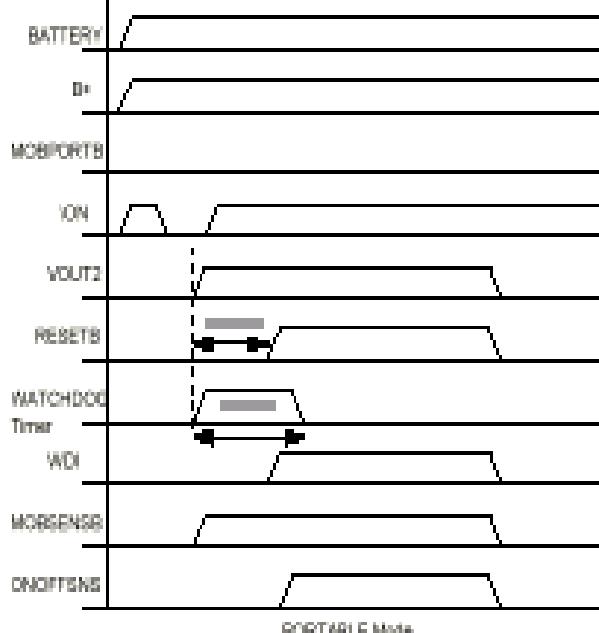




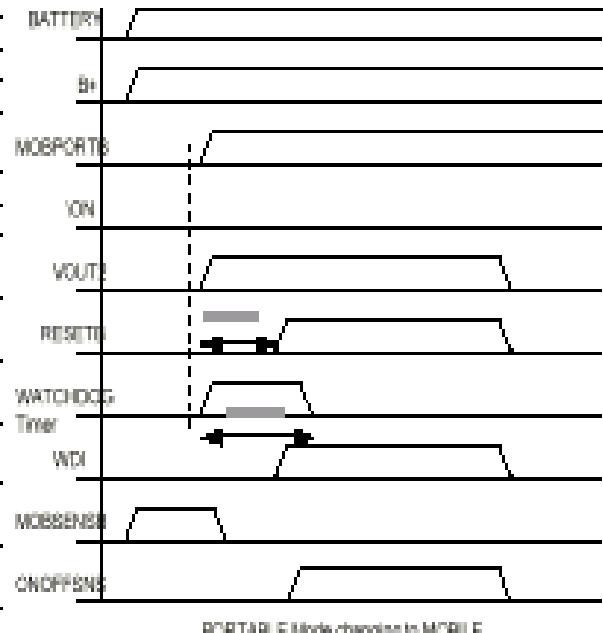
See timing sequence
below for no power
up issues on pag.03

NO POWER UP
TIMING
SEQUENCE

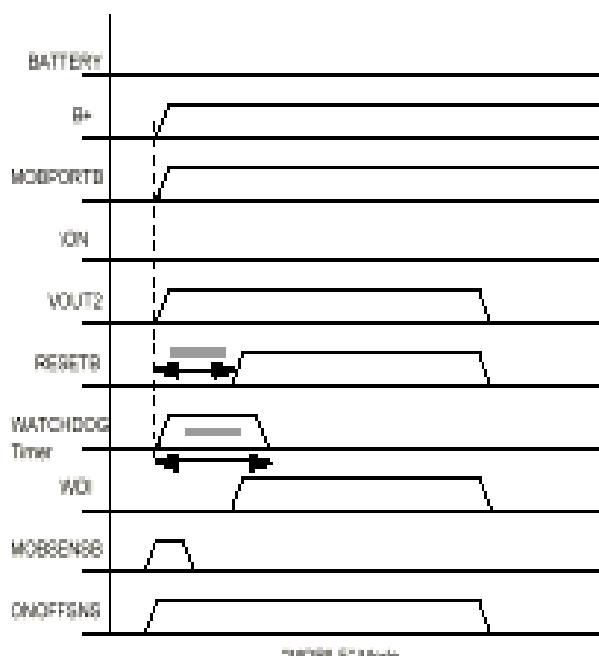
a) Radio turned on from ON/OFF



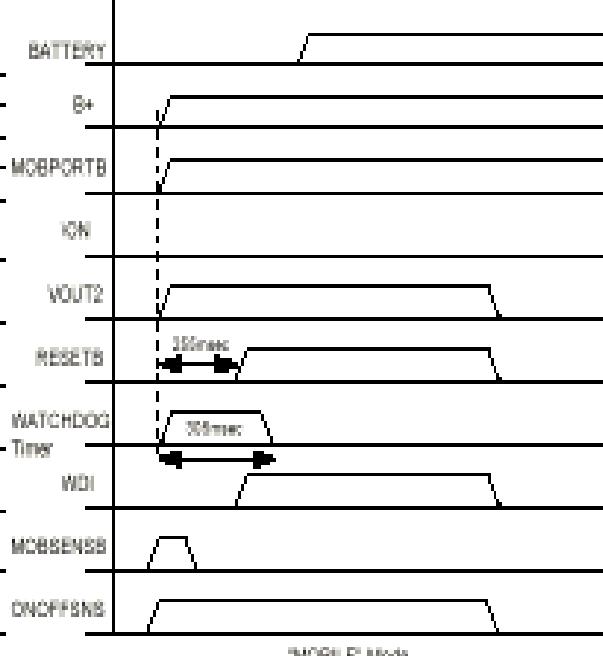
b) Radio on via transition to MOBILE



c) Radio on, no battery



d) Radio on, battery attached later



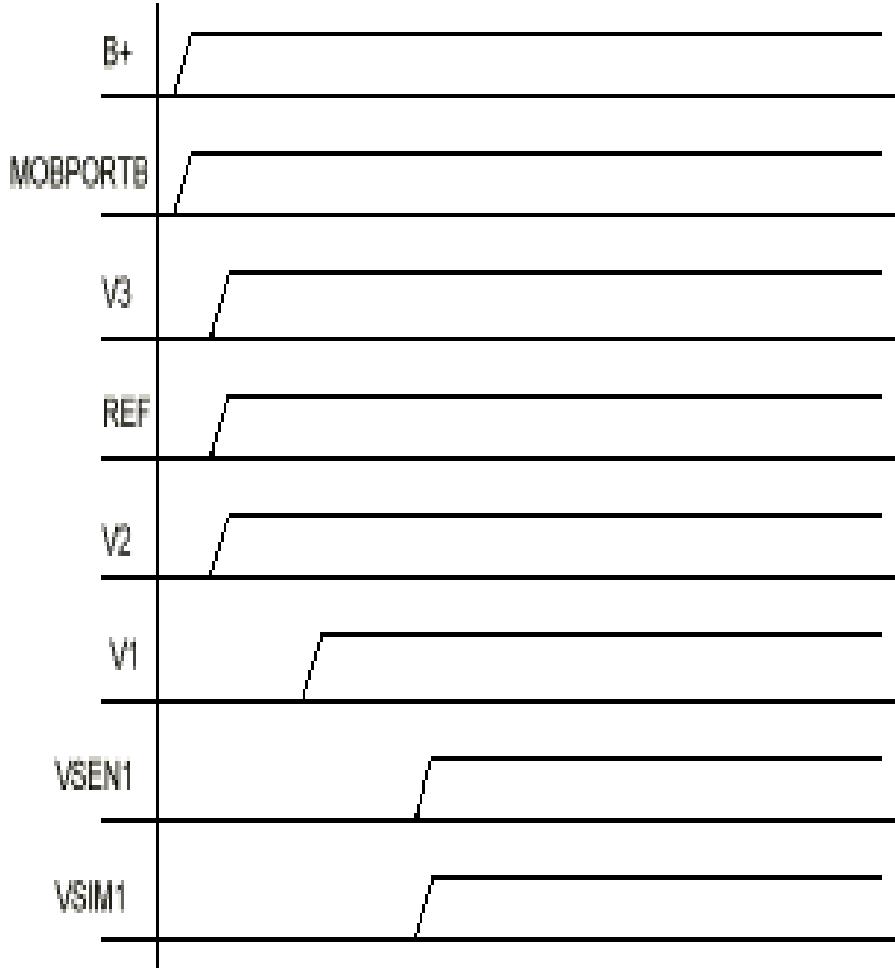


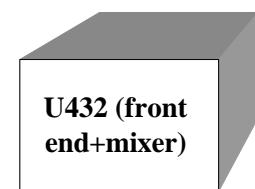
**See timing sequence
below for no power
up issues on pag.03**

**NO POWER UP
TIMING
SEQUENCE**

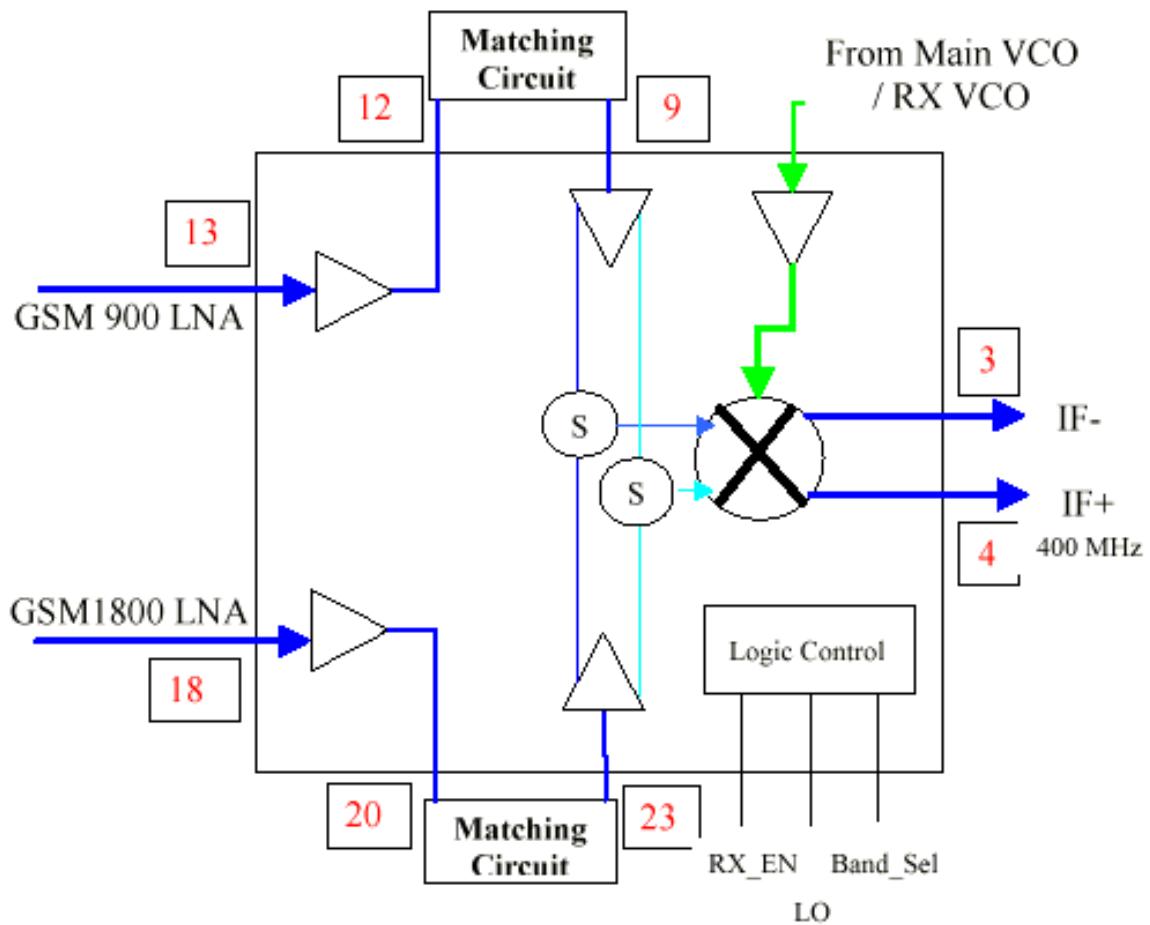
Regulator Power Up Sequence

No particular delay timing is established for any critical radio turn on sequence.



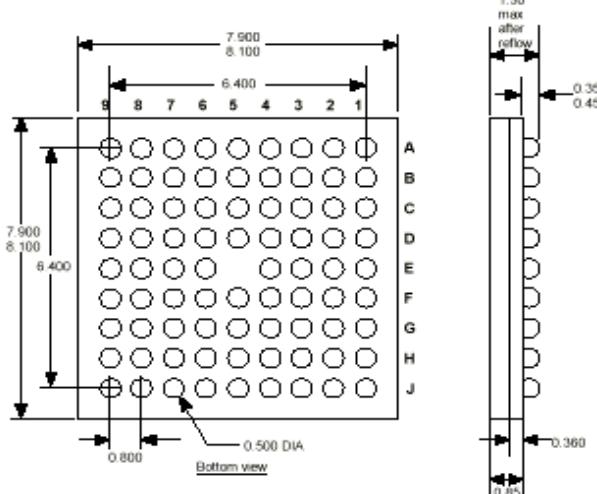
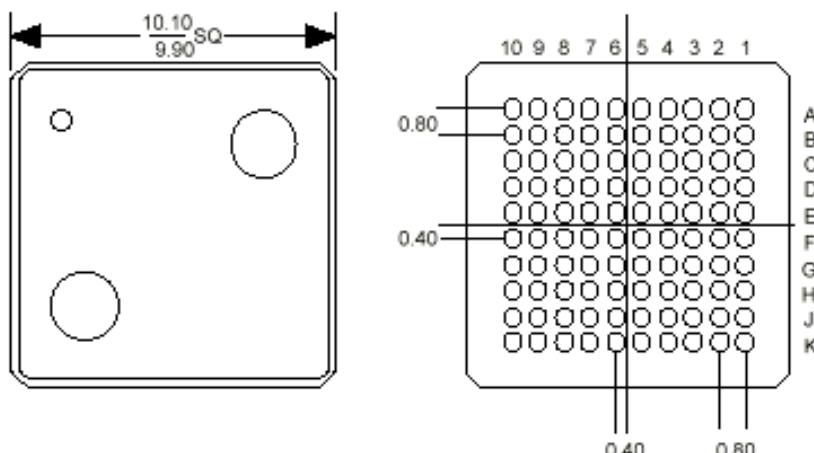
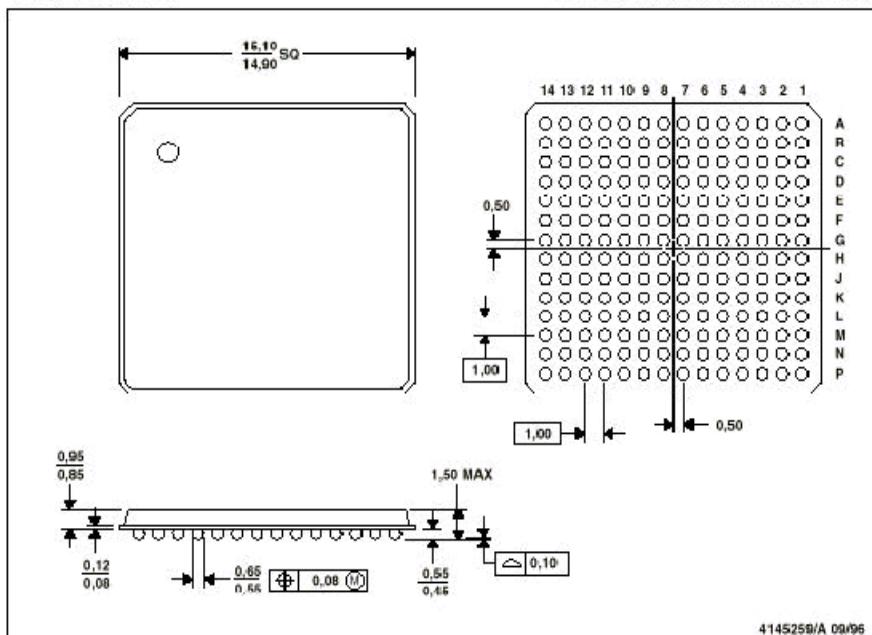


Front End IC
Internal Operation



**MOTOROLA**

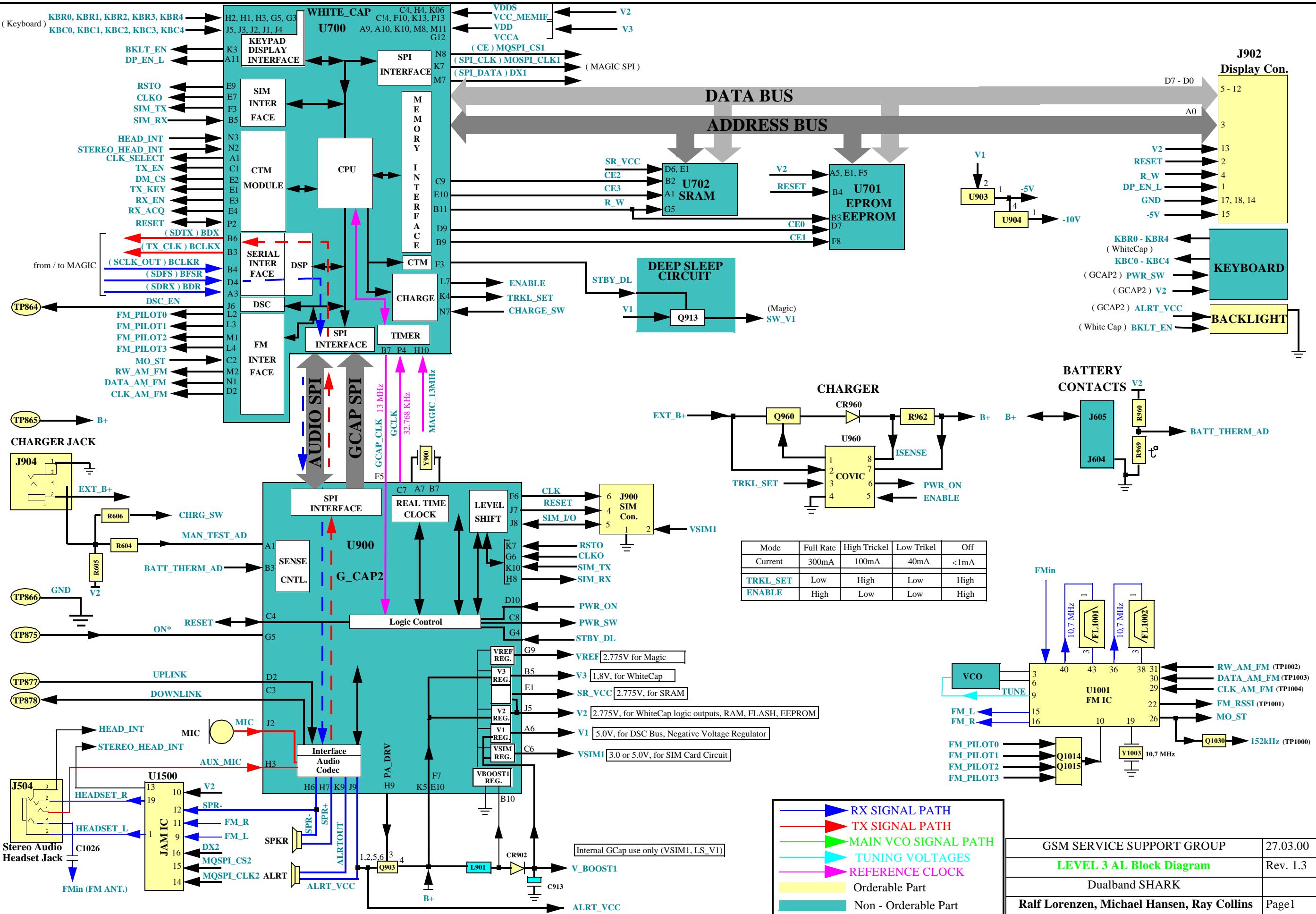
Dual band Modulus 3 level 3 debug rev 1.0

**MAGIC IC
U200
PACKAGE****GCAP 2 IC
U900
PACKAGE****GHG (S-PBGA-N196)****PLASTIC BALL GRID ARRAY PACKAGE****WHITECAP
IC U800
PACKAGE**

NOTES: A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. MicroStar™ BGA configuration

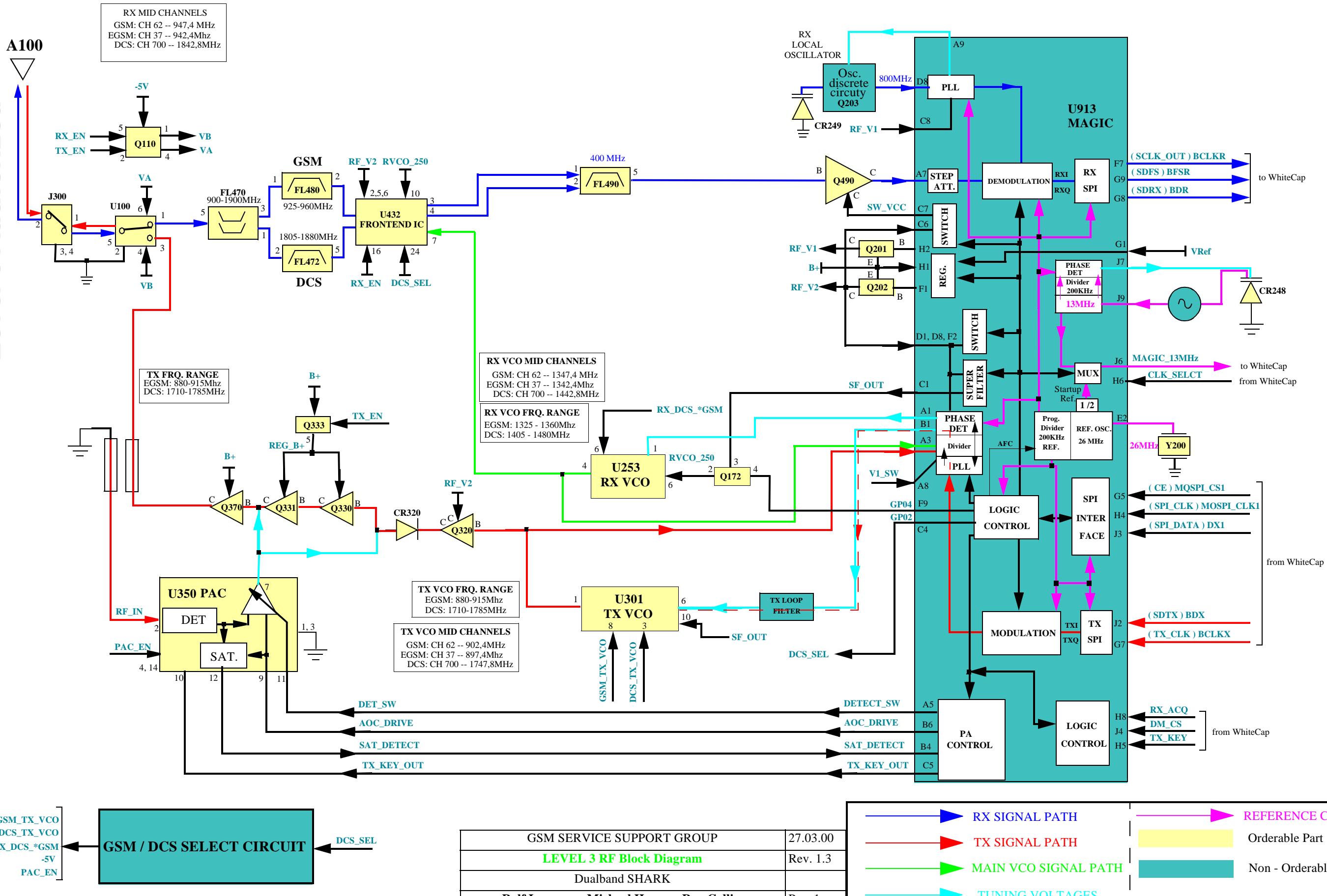
MODULUS III / SHARK

GSM Service Support
Level 3 Authorized



MODULUS III / SHARK

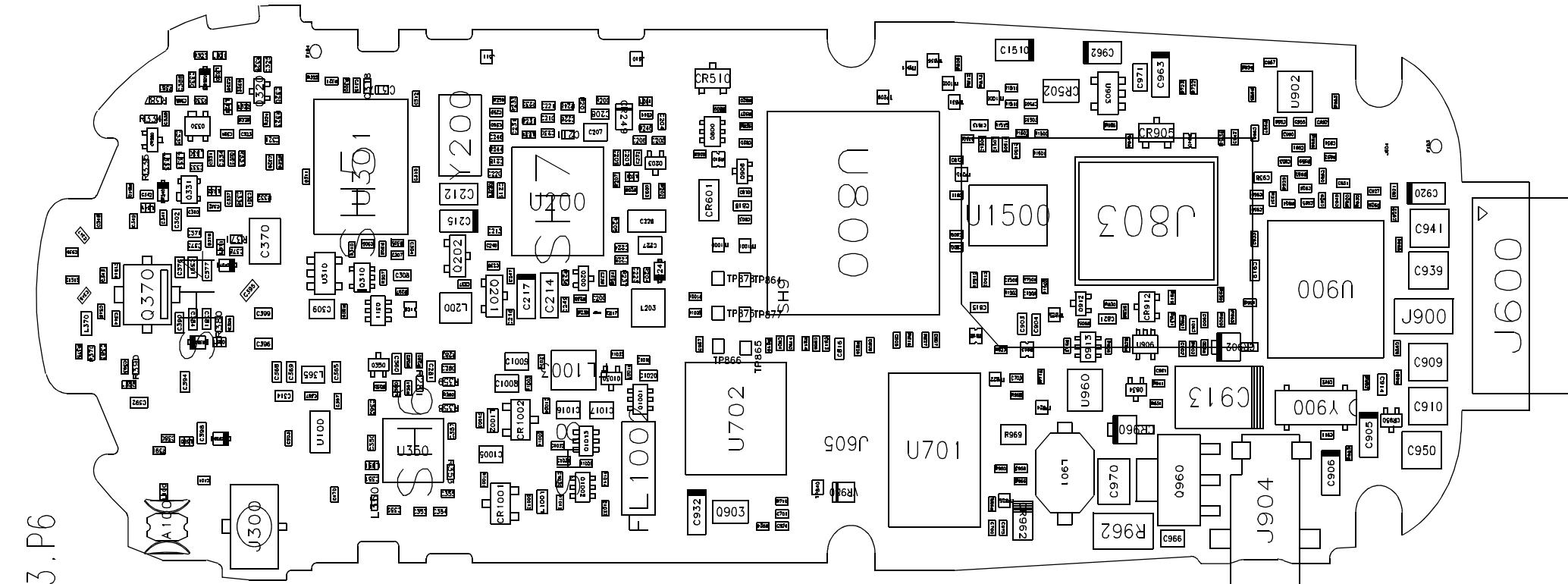
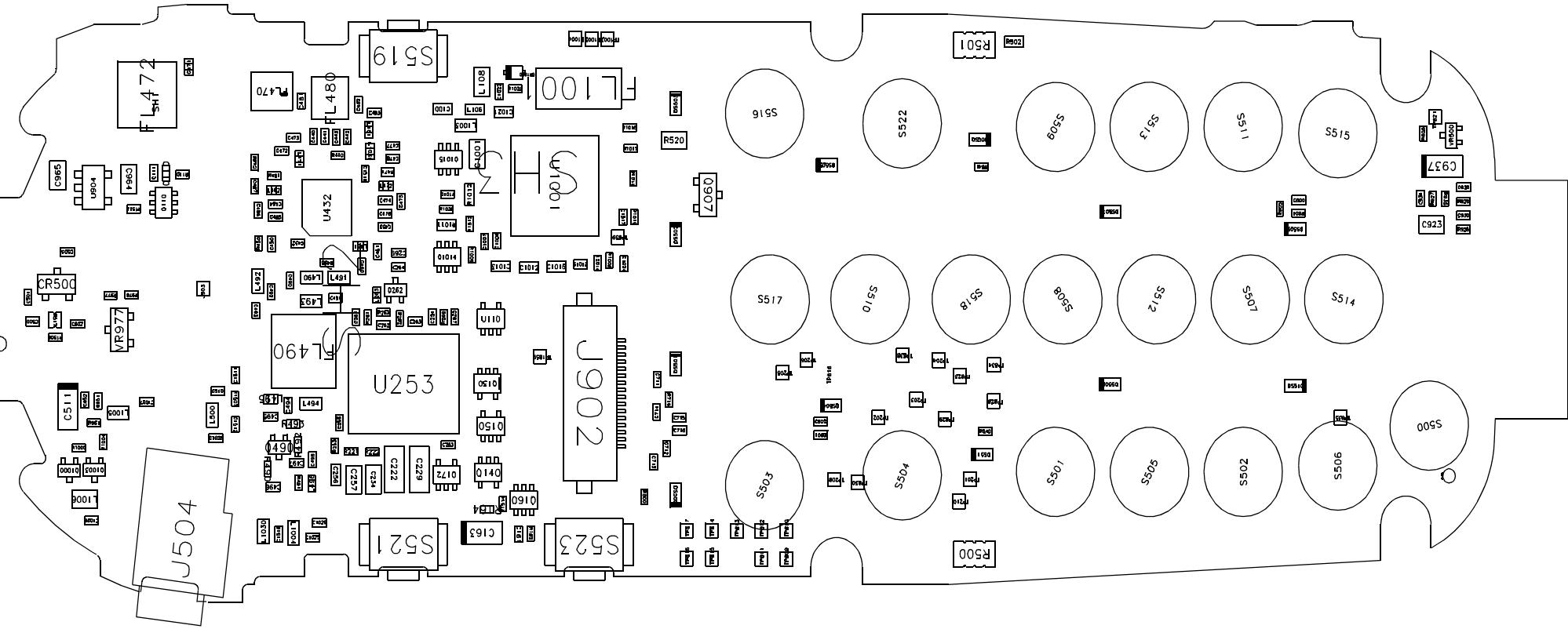
 GSM Service Support
Level 3 Authorized



Modulus III Shark_P6.0_v14

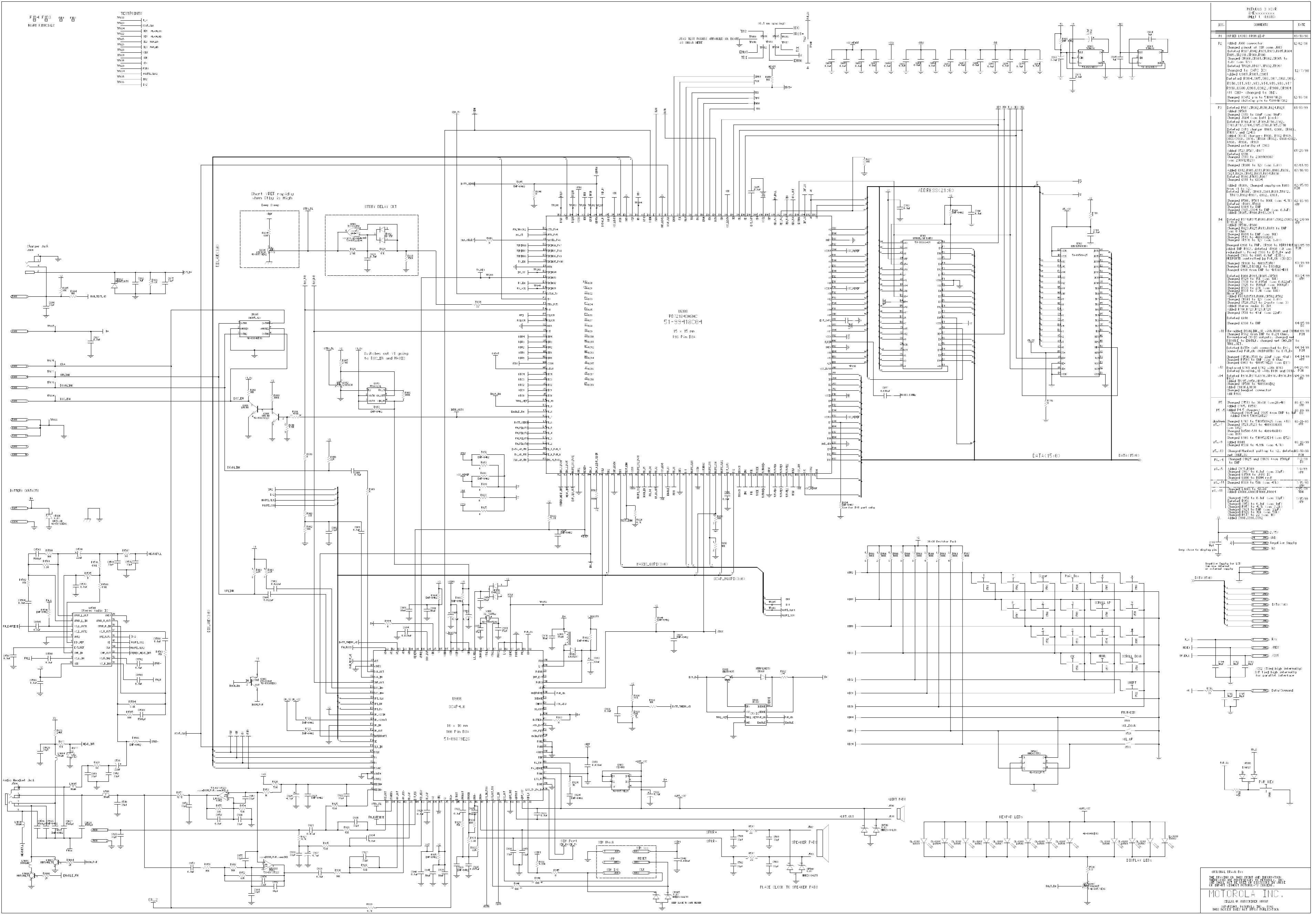


16JUL99
8485933H03.P6

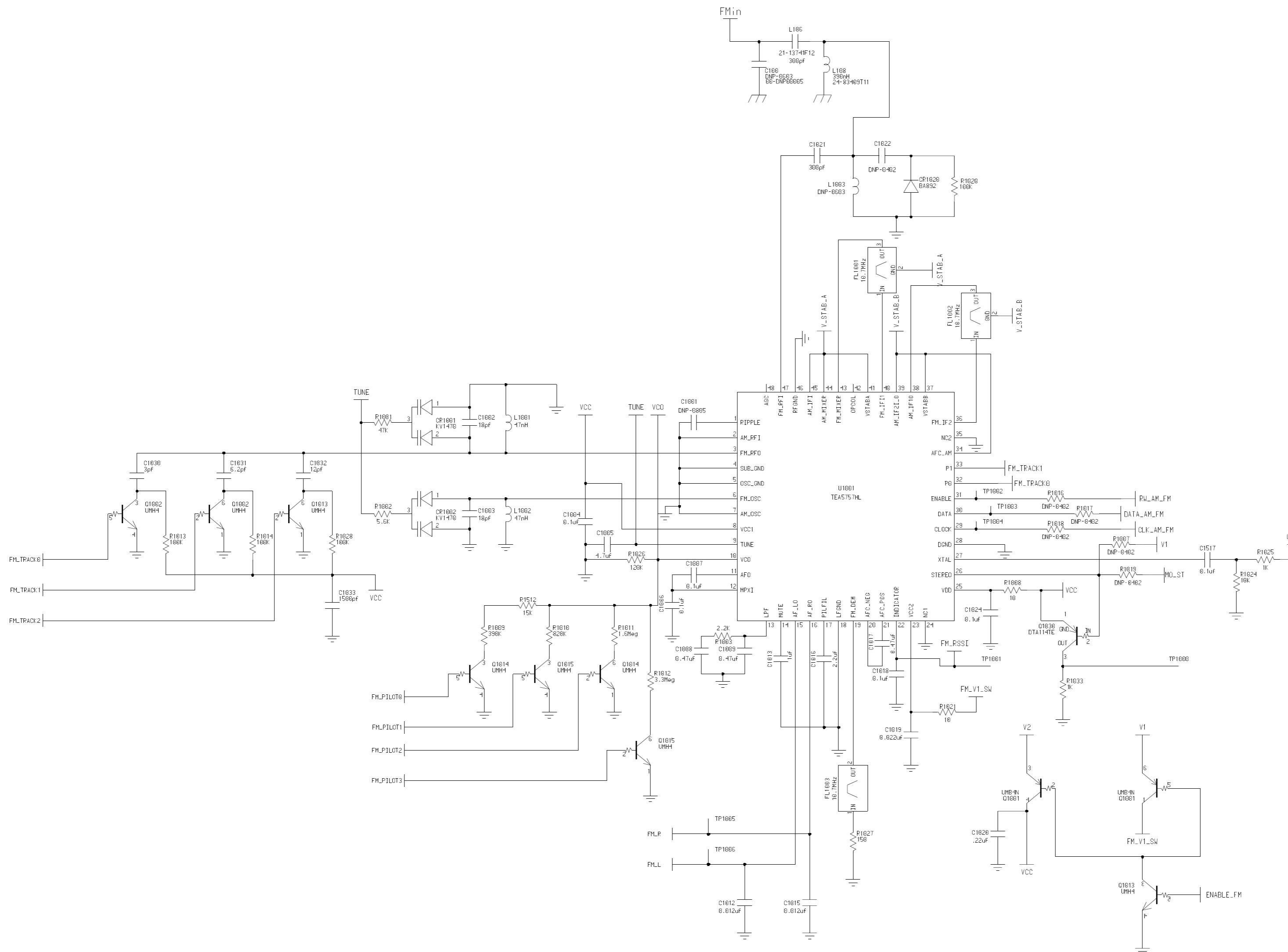


GSM Service Support	23.09.99
Level 3 Layout Diagram	Rev. 1.0
MODULUS III SHARK	P6.0_v14
Michael Hansen, Ray Collins, Ralf Lorenzen	Page 1 of 4

Modulus III / Shark_P06_v14



Modulus III / SHARK Version P06_v14



MODULUS 3 XCVR 840xxxxxx SHEET 4 FM RADIO		
ISS.	COMMENTS	DATE
P1	CREATED FROM PHILIPS DEMO BOARD	10/08/98
P2	L1081: Changed value from 55nH to 53nH L1082: Changed value from 55nH to 53nH C1082: Changed value from 10pF to 8pF C1083: Changed value from 10pF to 8pF P1082: 4.7k to 10k C1084: 4.7k to 10k C1085: 230pF to 1uF C1086: 0.015 to 0.01 C1087: 0.015 to 0.01 C2491: 22uF to 1uF P1081: 18k to 4.7k P1082: 18k to 5.0k	12/11/98
P3	Added P1081,P1082,C1085,C1082,P1082, P1083 Changed C1085 to 1uF (was -10pF) Changed C1083 to 10k (was 15pF) Changed C2491 to C1082 Changed C1082 to 100pF (was 22pF) Changed C1083 to 100pF (was 22pF) Changed C1085 to 100pF (was 50nH) Changed P1081,P1082 to DNP (was 10k) Changed P1081,P1082 to DNP (was 100pF) Deleted C1081, C1082 to 100pF Deleted C1081, C1082, C1083, P1084 Added C1084, P1085, P1086, P1087 Changed C1085 to 10k (was 15pF) Added M01ST	12/11/98
P4	Replaced 48 pin IC with 48 pin LDFP Added P1082 Replaced TP v new P/N for P1081, P1082 and P1083 Replaced varactors C1081, C1082 Deleted C1081,C1084,C10811,C10823,C1085, P1084,P1085,P1086,P1087,P1082,P1083, P1084,P1085,P1086 Updated transistor designators Added P1081, P1082 Changed C1081 to 211332804 1uF Changed C1085 to 211332804 4.7uF Changed C1081 to 56dBm DNP	02-23-99
P5_v3	Added TP1082,TP1086 Deleted P1085 Changed C1085, P1084,P1082 Changed P1082 to 5.0k (was 18k) Changed P1082 to 5.0k (was 18k)	06-15-99
P6_v4	Added P1087 = DNP Deleted C1081 From 0.55nH to DNP Changed C1085 From 100pF to DNP Changed L108 From 0.55nH to 350pF Deleted L108	07-02-99

MOTOROLA PERSONAL COMMUNICATIONS SECTOR		
COPRIGHT 1999, MOTOROLA INC. MOTOROLA CONFIDENTIAL PROPRIETARY		
DESIGN NAME	SMODULUS_3/dual net_P5_v9	
DRAWN BY	Thomas Nagode	DATE October 8, 1998
MODIFIED BY	Adrianna Petri	DATE June 16, 1999
APPD BY	-	DATE -
ISSUE	SHEET NO.	OF
TITLE	FM STEREO Radio	

GSM Service Support	23.09.99
FM Radio Level 3 SCHEMATIC	Rev. 1.0
SHARK / MODULUS III	Ver P6.0 v14
Michael Hansen, Ray Collins, Ralf Lorenzen	Page 4 of 4
TITLE	FM STEREO Radio

